Tool Power Controller Flash MCU

BP45F3640

Revision: V1.20 Date: August 20, 2021

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Features

CPU Features

- Operating voltage
  - f_{SYS}=8MHz: 2.2V~5.5V
  - High voltage driver: V_{CC}=12V (max.)
- Up to 0.5μs instruction cycle with 8MHz system clock at V_{DD}=5V
- Power down and wake-up functions to reduce power consumption
- Oscillator types
  - Internal High Speed 8MHz RC – HIRC
  - Internal Low Speed 32kHz RC – LIRC
- Multi-mode operation: FAST, SLOW, IDLE and SLEEP
- Fully integrated internal oscillators require no external components
- All instructions executed in 1~3 instruction cycles
- Table read instructions
- 115 powerful instructions
- 8-level subroutine nesting
- Bit manipulation instruction

Peripheral Features

- Flash Program Memory: 4K×16
- Data Memory: 256×8
- True EEPROM Memory: 32×8
- In Application Programming function – IAP
- Watchdog Timer function
- Up to 15 bidirectional I/O lines
- Programmable I/O port source current for LED driving applications
- Up to 2 high voltage input/output (HVIO) functions
- Two external interrupt lines shared with I/O pins
- Two Timer Modules for time measurement, compare match output or PWM output or single pulse output function
- Dual Time Base functions for generation of fixed time interrupt signals
- One I^2C interface
- 8 external channel 12-bit resolution A/D converter with internal reference voltage V_{VR}
- Over Current Protection function – OCP
- Integrated 16-bit Cyclic Redundancy Check function – CRC
- Low voltage reset function
- Low voltage detect function
- Package types: 16/20-pin SSOP

General Description

The device is a Flash Memory A/D type 8-bit high performance RISC architecture microcontroller designed for tool power controller applications.

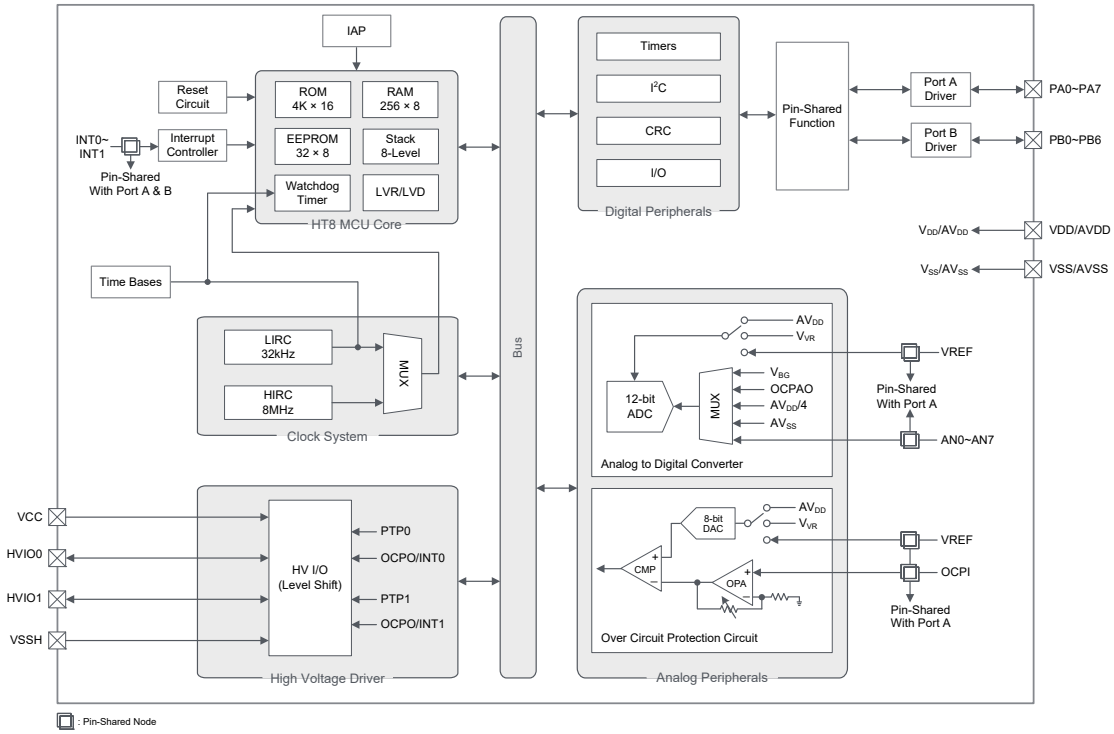
For memory features, the Flash Memory offers users the convenience of multi-programming features. By using the In Application Programming technology, users have a convenient means to directly store their measured data in the Flash Program Memory as well as having the ability to easily update their application programs. Other memory includes an area of RAM Data Memory as well as an area of true EEPROM memory for storage of non-volatile data such as serial numbers, calibration data etc.

Analog feature includes a multi-channel 12-bit A/D converter and an Over Current Protection function. With regard to internal timers, the device includes two extremely flexible Timer Modules providing functions for timing, pulse generation and PWM output operations. Communication with the outside world is catered for by including a fully integrated I^2C interface, which provides designers with a means of easy communication with external peripheral hardware. Protective features such as an internal Watchdog Timer, Low Voltage Reset and Low Voltage Detect coupled with excellent noise immunity and ESD protection ensure that reliable operation is maintained in hostile electrical environments.

The device provides two fully integrated high and low speed oscillators which require no external components for their implementation. The ability to operate and switch dynamically between a range of operating modes using different clock sources gives users the ability to optimise microcontroller operation and minimise power consumption.

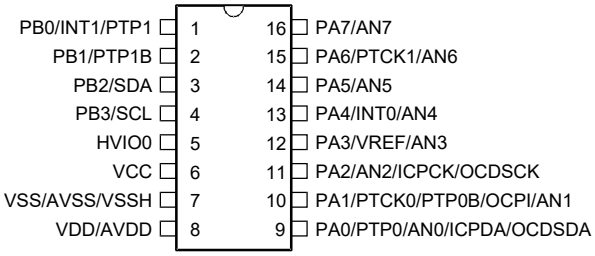
The High Voltage I/O function specific to 12V high voltage applications is also fully integrated within the device. The inclusion of flexible I/O programming features, 16-bit Cyclic Redundancy Check function, Time Base functions and many other features further enhance device functionality and flexibility. The device will find excellent use in electric tools, gargen tools, heating products and other related fields.

Block Diagram

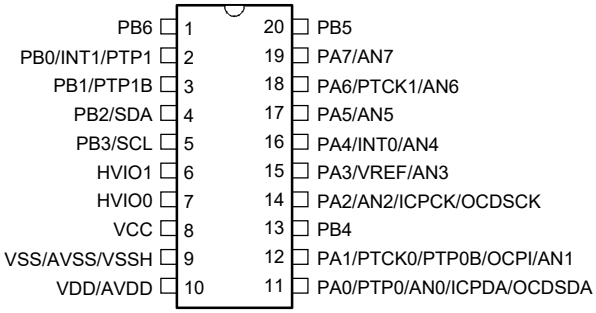


Note: VSSH is actually pin-shared with VSS and AVSS.

Pin Assignment



BP45F3640/BP45V3640
16 SSOP-A



BP45F3640/BP45V3640
20 SSOP-A

Note: 1. If the pin-shared pin functions have multiple outputs, the desired pin-shared function is determined by the corresponding software control bits.

2. The OCDSDA and OCDSCK pins are supplied for the OCDS dedicated pins and as such only available for the BP45V3640 device which is the OCDS EV chip for the BP45F3640 device.

3. For less pin-count package types there will be unbonded pins which should be properly configured to avoid unwanted current consumption resulting from floating input conditions. Refer to the "Standby Current Considerations" and "Input/Output Ports" sections.

Pin Descriptions

The function of each pin is listed in the following table, however the details behind how each pin is configured is contained in other sections of the datasheet. As the Pin Description table shows the situation for the package with the most pins, not all pins in the table will be available on smaller package sizes.

Pin Name	Function	OPT	I/T	O/T	Description
PA0/PTP0/AN0/ ICPDA/OCDSDA	PA0	PAPU PAWU	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	PTP0	PAS0	—	CMOS	PTM0 output
	AN0	PAS0	AN	—	A/D converter external input channel 0
	ICPDA	—	ST	CMOS	ICP data/address
	OCDSDA	—	ST	CMOS	OCDS data/address, for EV chip only
PA1/PTCK0/PTP0B/ OCPI/AN1	PA1	PAPU PAWU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	PTCK0	PAS0	ST	—	PTM0 clock input
	PTP0B	PAS0	—	CMOS	PTM0 inverted output
	OCPI	PAS0	AN	—	Over current protection input
	AN1	PAS0	AN	—	A/D converter external input channel 1
PA2/AN2/ ICPCK/OCDSCK	PA2	PAPU PAWU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	AN2	PAS0	AN	—	A/D converter external input channel 2
	ICPCK	—	ST	—	ICP clock
	OCDSCK	—	ST	—	OCDS clock, for EV chip only
PA3/VREF/AN3	PA3	PAPU PAWU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	VREF	PAS0	AN	—	External reference input for A/D converter and OCP DAC
	AN3	PAS0	AN	—	A/D converter external input channel 3

Pin Name	Function	OPT	I/T	O/T	Description
PA4/INT0/AN4	PA4	PAPU PAWU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	INT0	PAS1 INTC0 INTEG	ST	—	External interrupt input 0
	AN4	PAS1	AN	—	A/D converter external input channel 4
PA5/AN5	PA5	PAPU PAWU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	AN5	PAS1	AN	—	A/D converter external input channel 5
PA6/PTCK1/AN6	PA6	PAPU PAWU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	PTCK1	PAS1	ST	—	PTM1 clock input
	AN6	PAS1	AN	—	A/D converter external input channel 6
PA7/AN7	PA7	PAPU PAWU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	AN7	PAS1	AN	—	A/D converter external input channel 7
PB0/INT1/PTP1	PB0	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	INT1	PBS0 INTC0 INTEG	ST	—	External interrupt input 1
	PTP1	PBS0	—	CMOS	PTM1 output
PB1/PTP1B	PB1	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	PTP1B	PBS0	—	CMOS	PTM1 inverted output
PB2/SDA	PB2	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	SDA	PBS0	ST	NMOS	I^2C data line
PB3/SCL	PB3	PBPU	ST	CMOS	General purpose I/O. Register enabled pull-up
	SCL	PBPU	ST	NMOS	I^2C clock line
PB4~PB6	PB4~PB6	PBPU	ST	CMOS	General purpose I/O. Register enabled pull-up
HVIO0	HVIO0	—	ST	CMOS	High voltage input/output 0
HVIO1	HVIO1	—	ST	CMOS	High voltage input/output 1
VCC	VCC	—	PWR	—	High voltage positive power supply for HVIO and level shifter
VDD/AVDD	VDD	—	PWR	—	Digital positive power supply
	AVDD	—	PWR	—	Analog positive power supply
VSS/AVSS/VSSH	VSS	—	PWR	—	Digital negative power supply, ground
	AVSS	—	PWR	—	Analog negative power supply, ground
	VSSH	—	PWR	—	High voltage negative power supply, ground

Legend: I/T: Input type;
OPT: Optional by register selection;
ST: Schmitt Trigger input;
NMOS: NMOS output;
O/T: Output type;
PWR: Power;
CMOS: CMOS output;
AN: Analog signal.

Absolute Maximum Ratings

Supply Voltage for V_{CC} ..... V_{DD} to 12V

Supply Voltage for V_{DD} ..... V_{SS}−0.3V to 6.0V

Input Voltage ..... V_{SS}−0.3V to V_{DD}+0.3V

Storage Temperature ..... -50°C to 125°C

Operating Temperature ..... -40°C to 85°C

I_{OH} Total ..... -80mA

I_{OL} Total 80mA

Total Power Dissipation 500mW

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to this device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Electrical Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency, pin load conditions, temperature and program instruction type, can all exert an influence on the measured values.

Operating Voltage Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{DD}	Operating Voltage – HIRC	f_{SYS}=8MHz	2.2	—	5.5	V
	Operating Voltage – LIRC	f_{SYS}=32kHz	2.2	—	5.5	V

Operating Current Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{DD}	SLOW Mode – LIRC	2.2V	f_{SYS}=32kHz	—	8	16	μA
		3V		—	10	20	
		5V		—	30	50	
	FAST Mode – HIRC	2.2V	f_{SYS}=8MHz	—	0.6	1.0	mA
		3V		—	0.8	1.2	
		5V		—	1.6	2.4	

Note: When using the characteristic table data, the following notes should be taken into consideration:

1. Any digital input is set in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Operating Current values are measured using a continuous NOP instruction program loop.

Standby Current Characteristics

Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Max. @85°C	Unit
		V_{DD}	Conditions					
I_{STB}	SLEEP Mode	2.2V	WDT off	—	0.08	0.12	1.40	μA
		3V		—	0.08	0.12	1.40	
		5V		—	0.15	0.29	2.20	
	IDLE0 Mode – LIRC	2.2V	f_{SUB} on	—	2.4	4.0	4.8	μA
		3V		—	3	5	6	
		5V		—	5	10	12	
	IDLE1 Mode – HIRC	2.2V	f_{SUB} on, f_{SYS}=8MHz	—	288	400	480	μA
		3V		—	360	500	600	
		5V		—	600	800	960	

Note: When using the characteristic table data, the following notes should be taken into consideration:

1. Any digital input is set in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Standby Current values are taken after a HALT instruction executed thus stopping all instruction execution.

A.C. Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency and temperature etc., can all exert an influence on the measured values.

High Speed Internal Oscillator – HIRC – Frequency Accuracy

During the program writing operation the writer will trim the HIRC oscillator at a user-selected voltage of either 3V or 5V.

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Temp.				
f_{HIRC}	8MHz Writer Trimmed HIRC Frequency	3V/5V	25°C	-1%	8	+1%	MHz
			-40°C~85°C	-2%	8	+2%	
		2.2V~5.5V	25°C	-2.5%	8	+2.5%	
			-40°C~85°C	-3%	8	+3%	

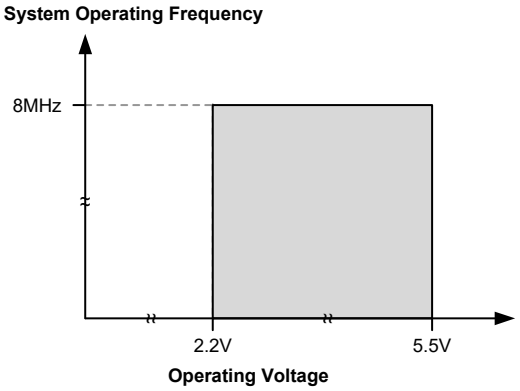
Note: 1. The 3V/5V values for V_{DD} are provided as these are the two selectable fixed voltages at which the HIRC frequency is trimmed by the writer.

2. The row below the 3V/5V trim voltage row is provided to show the values for the full V_{DD} range operating voltage. It is recommended that the trim voltage is fixed at 3V for application voltage ranges from 2.2V to 3.6V and fixed at 5V for application voltage ranges from 3.3V to 5.5V.

Low Speed Internal Oscillator Characteristics – LIRC

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Temp.				
f_{LIRC}	LIRC Frequency	2.2V~5.5V	-40°C~85°C	-7%	32	+7%	kHz
t_{START}	LIRC Start Up Time	—	-40°C~85°C	—	—	100	μs

Operating Frequency Characteristic Curves



System Start Up Time Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
t_{SST}	System Start-up Time Wake-up from Condition where f_{SYS} is Off	—	$f_{SYS}=f_H\sim f_H/64$, $f_H=f_{HIRC}$	—	16	—	t_{SYS}
		—	$f_{SYS}=f_{SUB}=f_{LIRC}$	—	2	—	t_{SYS}
	System Start-up Time Wake-up from Condition where f_{SYS} is On	—	$f_{SYS}=f_H\sim f_H/64$, $f_H=f_{HIRC}$	—	2	—	t_{SYS}
		—	$f_{SYS}=f_{SUB}=f_{LIRC}$	—	2	—	t_{SYS}
	System Speed Switch Time FAST to SLOW Mode or SLOW to FAST Mode	—	f_{HIRC} switches from off → on	—	16	—	t_{HIRC}
t_{RSTD}	System Reset Delay Time Reset Source from Power-on Reset or LVR Hardware Reset	—	RR_{POR}=5V/ms	14	16	18	ms
	System Reset Delay Time LVRC/WDTC Software Reset	—	—	14	16	18	
	System Reset Delay Time Reset Source from WDT Overflow	—	—	14	16	18	
t_{SRESET}	Minimum Software Reset Width to Reset	—	—	45	90	120	μs

Note: 1. For the System Start-up time values, whether f_{SYS} is on or off depends upon the mode type and the chosen f_{SYS} system oscillator. Details are provided in the System Operating Modes section.

2. The time units, shown by the symbols t_{HIRC}, t_{SYS} etc. are the inverse of the corresponding frequency values as provided in the frequency tables. For example $t_{HIRC}=1/f_{HIRC}$, $t_{SYS}=1/f_{SYS}$ etc.

3. The System Speed Switch Time is effectively the time taken for the newly activated oscillator to start up.

Input/Output Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{IL}	Input Low Voltage for I/O Ports	5V	—	0	—	1.5	V
		—		0	—	$0.2V_{DD}$	
V_{IH}	Input High Voltage for I/O Ports	5V	—	3.5	—	5.0	V
		—		$0.8V_{DD}$	—	V_{DD}	
I_{OL}	Sink Current for I/O Ports	3V	$V_{OL}=0.1V_{DD}$	16	32	—	mA
		5V		32	65	—	

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{OH}	Source Current for I/O Ports	3V	V_{OH}=0.9V_{DD}, SLEDC[m+1:m]=00B (m=0, 2, 4 or 6)	-0.7	-1.5	—	mA
		5V		-1.5	-2.9	—	
		3V	V_{OH}=0.9V_{DD}, SLEDC[m+1:m]=01B (m=0, 2, 4 or 6)	-1.3	-2.5	—	
		5V		-2.5	-5.1	—	
		3V	V_{OH}=0.9V_{DD}, SLEDC[m+1:m]=10B (m=0, 2, 4 or 6)	-1.8	-3.6	—	
		5V		-3.6	-7.3	—	
		3V	V_{OH}=0.9V_{DD}, SLEDC[m+1:m]=11B (m=0, 2, 4 or 6)	-4	-8	—	
		5V		-8	-16	—	
R_{PH}	Pull-high Resistance for I/O Ports (Note)	3V	—	20	60	100	kΩ
		5V		10	30	50	
I_{LEAK}	Input Leakage Current	5V	V_{IN}=V_{DD} or V_{IN}=V_{SS}	—	—	±1	μA
t_{INT}	External Interrupt Minimum Pulse Width	—	—	10	—	—	μs
t_{TCK}	PTM Clock Input Pin Minimum Pulse Width	—	—	0.3	—	—	μs

Note: The R_{PH} internal pull-high resistance value is calculated by connecting to ground and enabling the input pin with a pull-high resistor and then measuring the pin current at the specified supply voltage level. Dividing the voltage by this measured current provides the R_{PH} value.

High Voltage I/O Electrical Characteristics

Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	Input Voltage (Note)	—	—	4.5	5.0	5.5	V
V_{IN}	Input Voltage (Note)	—	—	V_{DD}	—	12	V
I_{OH}	Source Current for HVIO pins	5V	V_{OH}=0.9V_{IN}, V_{IN}=10V, Ta=-40°C~85°C	-100	—	—	mA
I_{OL}	Sink Current for HVIO pins	5V	V_{OL}=0.1V_{IN}, V_{IN}=10V, Ta=-40°C~85°C	100	—	—	mA
V_{IH}	Input High Voltage for HVIO pins	5V	—	0.8V_{CC}	—	V_{CC}	V
V_{IL}	Input Low Voltage for HVIO pins	5V	—	0	—	0.2V_{CC}	V

Note: To use the high voltage I/O function, the MCU VDD pin input voltage should be in the range of 4.5V~5.5V and the VCC pin input voltage should be larger than V_{DD}.

Memory Characteristics

Ta=-40°C~85°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
Flash Program Memory							
t_{DEW}	Erase/Write Cycle Time	—	—	—	2	3	ms
I_{DDPGM}	Programming/Erase Current on V_{DD}	—	—	—	—	5	mA
E_P	Cell Endurance	—	—	10K	—	—	E/W
t_{RETD}	Data Retention Time	—	Ta=25°C	—	40	—	Year

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
EEPROM Memory							
t_{EERD}	EEPROM Read Time	—	—	—	—	4	t_{SYS}
t_{EEWR}	EEPROM Write Time	—	—	—	4	6	ms
E_P	Cell Endurance	—	—	100K	—	—	E/W
t_{RETD}	Data Retention Time	—	Ta=25°C	—	40	—	Year
Data Memory							
V_{DR}	Data Retention Voltage	—	—	1.0	—	—	V

Note: "E/W" means Eease/Write times.

LVR/LVD Electrical Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{LVR}	Low Voltage Reset Voltage	—	LVR enable, voltage select 2.1V	-5%	2.1	+5%	V
			LVR enable, voltage select 2.55V		2.55		
			LVR enable, voltage select 3.15V		3.15		
			LVR enable, voltage select 3.8V		3.8		
V_{LVD}	Low Voltage Detection Voltage	—	LVD enable, voltage select 2.0V	-5%	2.0	+5%	V
			LVD enable, voltage select 2.2V		2.2		
			LVD enable, voltage select 2.4V		2.4		
			LVD enable, voltage select 2.7V		2.7		
			LVD enable, voltage select 3.0V		3.0		
			LVD enable, voltage select 3.3V		3.3		
			LVD enable, voltage select 3.6V		3.6		
			LVD enable, voltage select 4.0V		4.0		
$I_{LVRLVDBG}$	Operating Current	3V	LVD enable, LVR enable, VBGEN=0	—	—	20	μA
		5V		—	20	25	
		3V	LVD enable, LVR enable, VBGEN=1	—	—	25	
		5V		—	25	30	
I_{LVR}	Additional Current for LVR Enable	—	LVD disable, VBGEN=0	—	—	24	μA
t_{LVDS}	LVDO Stable Time	—	LVR enable, VBGEN=0, LVD off → on	—	—	18	μs
t_{LVD}	Minimum Low Voltage Width to Interrupt	—	—	60	120	240	μs
t_{LVR}	Minimum Low Voltage Width to Reset	—	—	120	240	480	μs

Reference Voltage Electrical Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{BG}	Bandgap Reference Voltage	—	—	-5%	1.04	+5%	V

Note: The V_{BG} voltage is used as the A/D converter internal signal input.

A/D Converter Electrical Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{ADI}	Input Voltage	—	—	0	—	V_{REF}	V
V_{REF}	Reference Voltage	—	—	2	—	V_{DD}	V
NR	Resolution	—	—	—	—	12	Bit
DNL	Differential Non-linearity	—	V_{REF}=V_{DD}, t_{ADCK}=0.5μs	-3	—	+3	LSB
INL	Integral Non-linearity	—	V_{REF}=V_{DD}, t_{ADCK}=0.5μs	-4	—	+4	LSB
I_{ADC}	Additional Current for A/D Converter Enable	2.2V	No load, t_{ADCK}=0.5μs	—	300	420	μA
		3V		—	340	500	
		5V		—	500	700	
t_{ADCK}	Clock Period	—	—	0.5	—	10	μs
t_{ON2ST}	A/D Converter On-to-Start Time	—	—	4	—	—	μs
t_{ADC}	A/D Conversion Time (Including A/D Sampling and Hold Time)	—	—	—	16	—	t_{ADCK}
V_{VR}	OPA Output Voltage	2.55V~5.50V	—	-1%	2.4	+1%	V

OCP Electrical Characteristics

Ta=-40°C~85°C

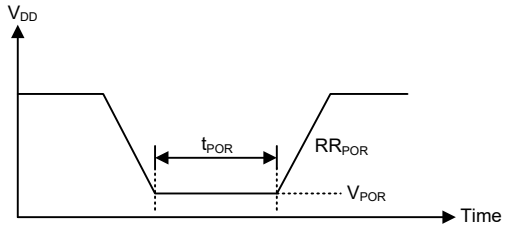
Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{OCP}	Operating Current	3V	OCPEN[1:0]=01B, OCPVRS[1:0]=10B, OCPCHY=1, G[2:0]=000B	—	300	500	μA
		5V		—	450	600	
V_{REF}	D/A Converter Reference Voltage	3V	OCPVRS[1:0]=01B	2.2	—	V_{DD}	V
		5V		2.2	—	V_{DD}	
V_{OS_CMP}	Comparator Input Offset Voltage	3V	Without calibration (OCPCOF[4:0]=10000B)	-15	—	15	mV
		5V		-15	—	15	
		3V	With calibration	-2	—	2	
		5V		-2	—	2	
V_{HYS}	Hysteresis	3V	—	10	40	60	mV
		5V		10	40	60	
V_{CM_CMP}	Comparator Common Mode Voltage Range	3V	—	V_{SS}	—	V_{DD}-1.0	V
		5V		V_{SS}	—	V_{DD}-1.0	
V_{OS_OPA}	OPA Input Offset Voltage	3V	Without calibration (OCPOOF[5:0]=100000B)	-15	—	15	mV
		5V		-15	—	15	
		3V	With calibration	-2	—	2	
		5V		-2	—	2	
V_{CM_OPA}	OPA Common Mode Voltage Range	3V	—	V_{SS}	—	V_{DD}-1.4	V
		5V		V_{SS}	—	V_{DD}-1.4	
V_{OR}	OPA Maximum Output Voltage Range	3V	—	V_{SS}+0.1	—	V_{DD}-0.1	V
		5V		V_{SS}+0.1	—	V_{DD}-0.1	
Ga	PGA Gain Accuracy	3V	All gains	-5	—	+5	%
		5V		-5	—	+5	
Ro	R2R Output Resistance	3V	—	—	10	—	kΩ
		5V		—	10	—	

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
DNL	Differential Non-linearity	3V	DAC V_{REF}=V_{DD}	—	—	±1.5	LSB
		5V		—	—	±1	
INL	Integral Non-linearity	3V	DAC V_{REF}=V_{DD}	—	—	±2	LSB
		5V		—	—	±1.5	

Power-on Reset Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{POR}	V_{DD} Start Voltage to Ensure Power-on Reset	—	—	—	—	100	mV
RR_{POR}	V_{DD} Rising Rate to Ensure Power-on Reset	—	—	0.035	—	—	V/ms
t_{POR}	Minimum Time for V_{DD} Stays at V_{POR} to Ensure Power-on Reset	—	—	1	—	—	ms



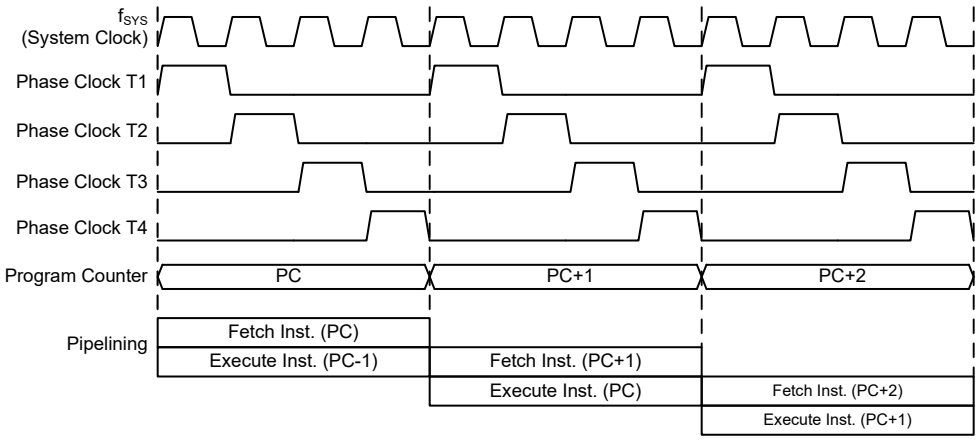
System Architecture

A key factor in the high-performance features of the range of microcontrollers is attributed to their internal system architecture. The device takes advantage of the usual features found within RISC microcontrollers providing increased speed of operation and enhanced performance. The pipelining scheme is implemented in such a way that instruction fetching and instruction execution are overlapped, hence instructions are effectively executed in one or two cycles for most of the standard or extended instructions respectively. The exceptions to this are branch or call instructions which need one more cycle. An 8-bit wide ALU is used in practically all instruction set operations, which carries out arithmetic operations, logic operations, rotation, increment, decrement, branch decisions, etc. The internal data path is simplified by moving data through the Accumulator and the ALU. Certain internal registers are implemented in the Data Memory and can be directly or indirectly addressed. The simple addressing methods of these registers along with additional architectural features ensure that a minimum of external components is required to provide a functional I/O and A/D control system with maximum reliability and flexibility. This makes the device suitable for low-cost, high-volume production for controller applications.

Clocking and Pipelining

The main system clock, derived from either a HIRC or LIRC oscillator is subdivided into four internally generated non-overlapping clocks, T1~T4. The Program Counter is increased at the beginning of the T1 clock during which time a new instruction is fetched. The remaining T2~T4 clocks carry out the decoding and execution functions. In this way, one T1~T4 clock cycle forms one instruction cycle. Although the fetching and execution of instructions takes place in consecutive instruction cycles, the pipelining structure of the microcontroller ensures that instructions are

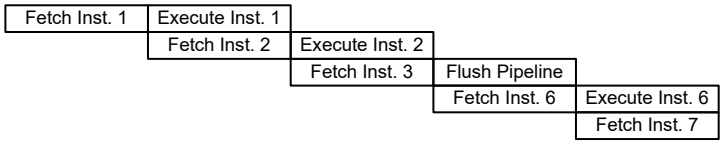
effectively executed in one instruction cycle. The exception to this are instructions where the contents of the Program Counter are changed, such as subroutine calls or jumps, in which case the instruction will take one more instruction cycle to execute.



System Clocking and Pipelining

For instructions involving branches, such as jump or call instructions, two machine cycles are required to complete instruction execution. An extra cycle is required as the program takes one cycle to first obtain the actual jump or call address and then another cycle to actually execute the branch. The requirement for this extra cycle should be taken into account by programmers in timing sensitive applications.

```
1          MOV A,[12H]
2          CALL DELAY
3          CPL [12H]
4          :
5          :
6  DELAY:  NOP
```



Instruction Fetching

Program Counter

During program execution, the Program Counter is used to keep track of the address of the next instruction to be executed. It is automatically increased by one each time an instruction is executed except for instructions, such as "JMP" or "CALL" that demand a jump to a non-consecutive Program Memory address. Only the lower 8 bits, known as the Program Counter Low Register, are directly addressable by the application program.

When executing instructions requiring jumps to non-consecutive addresses such as a jump instruction, a subroutine call, interrupt or reset, etc., the microcontroller manages program control by loading the required address into the Program Counter. For conditional skip instructions, once the condition has been met, the next instruction, which has already been fetched during the present instruction execution, is discarded and a dummy cycle takes its place while the correct instruction is obtained.

Program Counter	
High Byte	**Low Byte (PCL)**
PC11~PC8	PCL7~PCL0

Program Counter

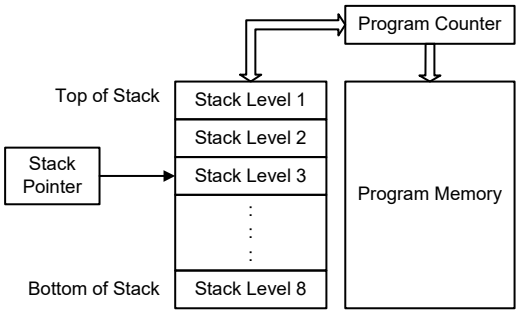
The lower byte of the Program Counter, known as the Program Counter Low register or PCL, is available for program control and is a readable and writeable register. By transferring data directly into this register, a short program jump can be executed directly; however, as only this low byte is available for manipulation, the jumps are limited to the present page of memory that is 256 locations. When such program jumps are executed it should also be noted that a dummy cycle will be inserted. Manipulating the PCL register may cause program branching, so an extra cycle is needed to pre-fetch.

Stack

This is a special part of the memory which is used to save the contents of the Program Counter only. The stack is organized into 8 levels and neither part of the data nor part of the program space, and is neither readable nor writeable. The activated level is indexed by the Stack Pointer, STKPTR, which is a read only register. At a subroutine call or interrupt acknowledge signal, the contents of the Program Counter are pushed onto the stack and the Stack Pointer is increased by one. At the end of a subroutine or an interrupt routine, signaled by a return instruction, RET or RETI, the Program Counter is restored to its previous value from the stack and the Stack Pointer is decreased by one. After a device reset or when the stack is full, the Stack Pointer will point to the top of the stack with a value of 00H.

If the stack is full and an enabled interrupt takes place, the interrupt request flag will be recorded but the acknowledge signal will be inhibited. When the Stack Pointer is decreased, by RET or RETI, the interrupt will be serviced. This feature prevents stack overflow allowing the programmer to use the structure more easily. However, when the stack is full, a CALL subroutine instruction can still be executed which will result in a stack overflow. Precautions should be taken to avoid such cases which might cause unpredictable program branching.

If the stack is overflow, the first Program Counter save in the stack will be lost.



- **SKPTR Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: Stack pointer register

The following example shows how the Stack Pointer changes when program branching conditions occur.

(1) When the CALL subroutine instruction is executed 8 times continuously and the RET instruction is not executed during the period, the corresponding changes of the STKPTR are as follows:

00H→01H→02H→03H→04H→05H→06H→07H→00H

(2) Then the RET instruction is executed 8 times continuously after (1), the corresponding changes of the STKPTR are as follows:

00H→07H→06H→05H→04H→03H→02H→01H→00H

Arithmetic and Logic Unit – ALU

The arithmetic-logic unit or ALU is a critical area of the microcontroller that carries out arithmetic and logic operations of the instruction set. Connected to the main microcontroller data bus, the ALU receives related instruction codes and performs the required arithmetic or logical operations after which the result will be placed in the specified register. As these ALU calculation or operations may result in carry, borrow or other status changes, the status register will be correspondingly updated to reflect these changes. The ALU supports the following functions:

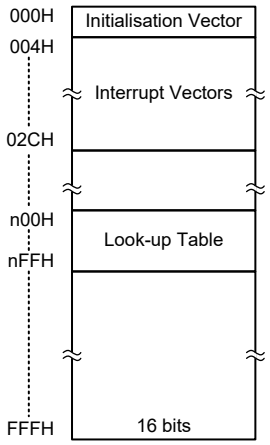
- Arithmetic operations:
  ADD, ADDM, ADC, ADCM, SUB, SUBM, SBC, SBCM, DAA,
  LADD, LADDM, LADC, LADCM, LSUB, LSUBM, LSBC, LSBCM, LDAA
- Logic operations:
  AND, OR, XOR, ANDM, ORM, XORM, CPL, CPLA,
  LAND, LANDM, LOR, LORM, LXOR, LXORM, LCPL, LCPLA
- Rotation:
  RRA, RR, RRCA, RRC, RLA, RL, RLCA, RLC,
  LRRA, LRR, LRRCA, LRRC, LRLA, LRL, LRLCA, LRLC
- Increment and Decrement:
  INCA, INC, DECA, DEC,
  LINCA, LINC, LDECA, LDEC
- Branch decision:
  JMP, SZ, SZA, SNZ, SIZ, SDZ, SIZA, SDZA, CALL, RET, RETI,
  LSZ, LSZA, LSNZ, LSIZ, LSDZ, LSIZA, LSDZA

Flash Program Memory

The Program Memory is the location where the user code or program is stored. For this device the Program Memory is Flash type, which means it can be programmed and re-programmed a large number of times, allowing the user the convenience of code modification on the same device. By using the appropriate programming tools, the Flash device offers users the flexibility to conveniently debug and develop their applications while also offering a means of field programming and updating.

Structure

The Program Memory has a capacity of 4K×16 bits. The Program Memory is addressed by the Program Counter and also contains data, table information and interrupt entries. Table data, which can be configured in any location within the Program Memory, is addressed by a separate table pointer register.



Program Memory Structure

Special Vectors

Within the Program Memory, certain locations are reserved for the reset and interrupts. The location 000H is reserved for use by the device reset for program initialisation. After a device reset is initiated, the program will jump to this location and begin execution.

Look-up Table

Any location within the Program Memory can be defined as a look-up table where programmers can store fixed data. To use the look-up table, the table pointer must first be configured by placing the address of the look up data to be retrieved in the table pointer register, TBLP and TBHP. These registers define the total address of the look-up table.

After setting up the table pointer, the table data can be retrieved from the Program Memory using the “TABRD [m]” or “TABRDL [m]” instructions respectively when the memory [m] is located in Sector 0. If the memory [m] is located in other sectors except Sector 0, the data can be retrieved from the program memory using the corresponding extended table read instruction such as “LTABRD [m]” or “LTABRDL [m]” respectively. When the instruction is executed, the lower order table byte from the Program Memory will be transferred to the user defined Data Memory register [m] as specified in the instruction. The higher order table data byte from the Program Memory will be transferred to the TBLH special register.

The accompanying diagram illustrates the addressing data flow of the look-up table.

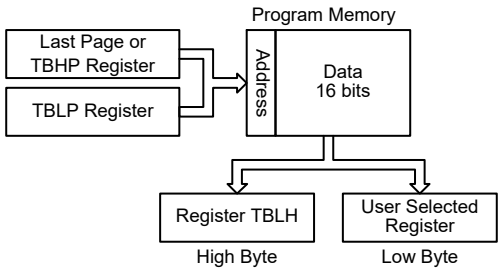


Table Program Example

The following example shows how the table pointer and table data is defined and retrieved from the microcontroller. This example uses raw table data located in the Program Memory which is stored there using the ORG statement. The value at this ORG statement is "0F00H" which refers to the start address of the last page within the 4K Program Memory of the device. The table pointer low byte register is set here to have an initial value of "06H". This will ensure that the first data read from the data table will be at the Program Memory address "0F06H" or 6 locations after the start of the last page. Note that the value for the table pointer is referenced to a specific address pointed by the TBLP and TBHP registers if the "TABRD [m]" or "LTABRD [m]" instruction is being used. The high byte of the table data which in this case is equal to zero will be transferred to the TBLH register automatically when the "TABRD [m]" instruction is executed.

Because the TBLH register is a read/write register and can be restored, care should be taken to ensure its protection if both the main routine and Interrupt Service Routine use table read instructions. If using the table read instructions, the Interrupt Service Routines may change the value of the TBLH and subsequently cause errors if used again by the main routine. As a rule it is recommended that simultaneous use of the table read instructions should be avoided. However, in situations where simultaneous use cannot be avoided, the interrupts should be disabled prior to the execution of any main routine table-read instructions. Note that all table related instructions require two instruction cycles to complete their operation.

Table Read Program Example

```
tempreg1 db ?   ; temporary register #1
tempreg2 db ?   ; temporary register #2
:
:
mov a,06h       ; initialise low table pointer - note that this address is referenced
mov tblp,a      ; to the last page or the page that tbhp pointed
mov a,0Fh       ; initialise high table pointer
mov tbhp,a
:
:
tabrd tempreg1  ; transfers value in table referenced by table pointer data at program
                ; memory address "0F06H" transferred to tempreg1 and TBLH
dec tblp        ; reduce value of table pointer by one
tabrd tempreg2  ; transfers value in table referenced by table pointer
                ; data at program memory address "0F05H" transferred to tempreg2 and TBLH
                ; in this example the data "1AH" is transferred to tempreg1 and data "0FH"
                ; to register tempreg2
:
:
org 0F00h       ; sets initial address of program memory
dc 00Ah, 00Bh, 00Ch, 00Dh, 00Eh, 00Fh, 01Ah, 01Bh
:
:
```

In Circuit Programming – ICP

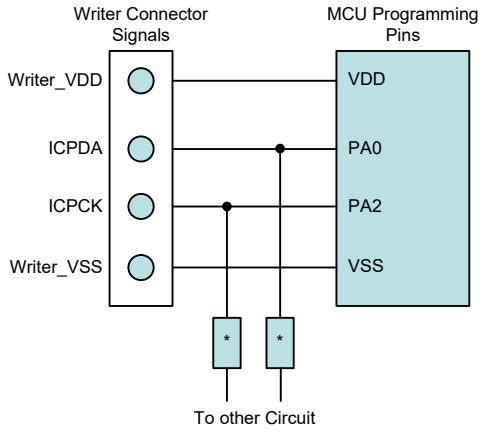
The provision of Flash type Program Memory provides the user with a means of convenient and easy upgrades and modifications to their programs on the same device.

As an additional convenience, Holtek has provided a means of programming the microcontroller in-circuit using a 4-pin interface. This provides manufacturers with the possibility of manufacturing their circuit boards complete with a programmed or un-programmed microcontroller, and then programming or upgrading the program at a later stage. This enables product manufacturers to easily keep their manufactured products supplied with the latest program releases without removal and re-insertion of the device.

Holtek Writer Pins	MCU Programming Pins	Pin Description
ICPDA	PA0	Programming Serial Data/Address
ICPCK	PA2	Programming Clock
VDD	VDD	Power Supply
VSS	VSS	Ground

The Program Memory can be programmed serially in-circuit using this 4-wire interface. Data is downloaded and uploaded serially on a single pin with an additional line for the clock. Two additional lines are required for the power supply. The technical details regarding the in-circuit programming of the device is beyond the scope of this document and will be supplied in supplementary literature.

During the programming process, the user must take care of the ICPDA and ICPCK pins for data and clock programming purposes to ensure that no other outputs are connected to these two pins.



Note: * may be resistor or capacitor. The resistance of * must be greater than 1kΩ or the capacitance of * must be less than 1nF.

On-Chip Debug Support – OCDS

An EV chip exists for the purposes of device emulation. The EV chip device also provides an "On-Chip Debug" function to debug the real MCU device during the development process. The EV chip and the real MCU device are almost functionally compatible except for "On-Chip Debug" function. Users can use the EV chip device to emulate the real chip device behavior by connecting the OCDSDA and OCDSCK pins to the Holtek HT-IDE development tools. The OCDSDA pin is the OCDS Data/Address input/output pin while the OCDSCK pin is the OCDS clock input pin. When users use the EV chip device for debugging, the corresponding pin functions shared with the OCDSDA and OCDSCK pins in the real MCU device will have no effect on the EV chip. However, the two OCDS pins which are pin-shared with the ICP programming pins are still used as the Flash Memory programming pins for ICP. For more detailed OCDS information, refer to the corresponding document named "Holtek e-Link for 8-bit MCU OCDS User's Guide".

Holtek e-Link Pins	EV Chip OCDS Pins	Pin Description
OCDSDA	OCDSDA	On-Chip Debug Support Data/Address input/output
OCDSCK	OCDSCK	On-Chip Debug Support Clock input
VDD	VDD	Power Supply
VSS	VSS	Ground

In Application Programming – IAP

Flash type Program Memory provides the user with a means of convenient and easy upgrades and modifications to their programs on the same device. The provision of the IAP function offers users the convenience of Flash Memory multi-programming features. The convenience of the IAP function is that it can execute the updated program procedure using its internal firmware, without requiring an external Program Writer or PC. In addition, the IAP interface can also be any type of communication protocol, such as UART or USB, using I/O pins. Regarding the internal firmware, the user can select versions provided by Holtek or create their own. The following section illustrates the procedures regarding how to implement the IAP firmware.

Flash Memory Read/Write Size

The Flash memory Erase and Write operations are carried out in a page format while the Read operation is carried out in a word format. The page size and write buffer size are both assigned with a capacity of 32 words. Note that the Erase operation should be executed before the Write operation is executed.

When the Flash Memory Erase/Write Function is successfully enabled, the CFWEN bit will be set high. When the CFWEN bit is set high, the data can be written into the write buffer. The FWT bit is used to initiate the write process and then indicate the write operation status. This bit is set high by application programs to initiate a write process and will be cleared by hardware if the write process is finished.

The Read operation can be carried out by executing a specific read procedure. The FRDEN bit is used to enable the read function and the FRD bit is used to initiate the read process by application programs and then indicate the read operation status. When the read process is finished, this bit will be cleared by hardware.

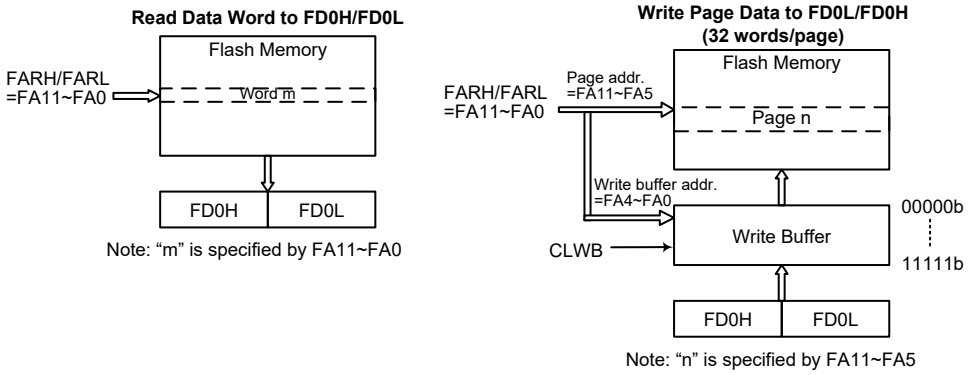
Operations	Format
Erase	32 words/page
Write	32 words/time
Read	1 word/time
Note: Page size = Write buffer size = 32 words.	

IAP Operation Format

Erase Page	FARH	FARL[7:5]	FARL[4:0]
0	0000 0000	000	x xxxx
1	0000 0000	001	x xxxx
2	0000 0000	010	x xxxx
3	0000 0000	011	x xxxx
4	0000 0000	100	x xxxx
: :	: :	: :	: :
126	0000 1111	110	x xxxx
127	0000 1111	111	x xxxx

"x": don't care

Erase Page Number and Selection



Flash Memory IAP Read/Write Structure

Write Buffer

The write buffer is used to store the written data temporarily when executing the write operation. The Write Buffer can be filled with written data after the Flash Memory Erase/Write Function has been successfully enabled by executing the Flash Memory Erase/Write Function Enable procedure. The write buffer can be cleared by configuring the CLWB bit in the FC2 register. The CLWB bit can be set high to enable the Clear Write Buffer procedure. When the procedure is finished this bit will be cleared to low by the hardware. It is recommended that the write buffer should be cleared by setting the CLWB bit high before the write buffer is used for the first time or when the data in the write buffer is updated.

The write buffer size is 32 words corresponding to a page. The write buffer address is mapped to a specific flash memory page specified by the memory address bits, FA11~FA5. The data written into the FD0L and FD0H registers will be loaded into the write buffer. When data is written into the high byte data register, FD0H, it will result in the data stored in the high and low byte data registers both being written into the write buffer. It will also cause the flash memory address to be increased by one, after which the new address will be loaded into the FARH and FARL address registers. When the flash memory address reaches the page boundary, 11111b of a page with 32 words, the address will now not be increased but will stop at the last address of the page. At this point a new page address should be specified for any other erase/write operations.

After a write process is finished, the write buffer will automatically be cleared by the hardware. Note that the write buffer should be cleared manually by the application program when the data written into the flash memory is incorrect in the data verification step. The data should again be written into the write buffer after the write buffer has been cleared when the data is found to be incorrect during the data verification step.

IAP Flash Program Memory Registers

There are two address registers, four 16-bit data registers and three control registers, which are all located in Sector 0. Read and Write operations to the Flash memory are carried out by 16-bit data operations using the address and data registers and the control registers. The address registers are named FARL and FARH, the data registers are named FDnL and FDnH and the control registers are named FC0, FC1 and FC2.

Register Name	Bit							
	7	6	5	4	3	2	1	0
FC0	CFWEN	FMOD2	FMOD1	FMOD0	FWPEN	FWT	FRDEN	FRD
FC1	D7	D6	D5	D4	D3	D2	D1	D0
FC2	—	—	—	—	—	—	—	CLWB
FARL	FA7	FA6	FA5	FA4	FA3	FA2	FA1	FA0
FARH	—	—	—	—	FA11	FA10	FA9	FA8
FD0L	D7	D6	D5	D4	D3	D2	D1	D0
FD0H	D15	D14	D13	D12	D11	D10	D9	D8
FD1L	D7	D6	D5	D4	D3	D2	D1	D0
FD1H	D15	D14	D13	D12	D11	D10	D9	D8
FD2L	D7	D6	D5	D4	D3	D2	D1	D0
FD2H	D15	D14	D13	D12	D11	D10	D9	D8
FD3L	D7	D6	D5	D4	D3	D2	D1	D0
FD3H	D15	D14	D13	D12	D11	D10	D9	D8

IAP Register List

- **FARL Register**

Bit	7	6	5	4	3	2	1	0
Name	FA7	FA6	FA5	FA4	FA3	FA2	FA1	FA0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 Flash Memory Address bit 7 ~ bit 0

- **FARH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	FA11	FA10	FA9	FA8
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3~0 Flash Memory Address bit 11 ~ bit 8

- **FD0L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 The first Flash Memory Data bit 7 ~ bit 0

Note that data written into the low byte data register FD0L will only be stored in the FD0L register and not loaded into the lower 8-bit write buffer.

• **FD0H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 The first Flash Memory Data bit 15 ~ bit 8

Note that when an 8-bit data is written into the high byte data register FD0H, the whole 16 bits of data stored in the FD0H and FD0L registers will simultaneously be loaded into the 16-bit write buffer after which the contents of the Flash memory address register pair, FARH and FARL, will be increased by one.

• **FD1L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 The second Flash Memory Data bit 7 ~ bit 0

• **FD1H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 The second Flash Memory Data bit 15 ~ bit 8

• **FD2L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 The third Flash Memory Data bit 7 ~ bit 0

• **FD2H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 The third Flash Memory Data bit 15 ~ bit 8

• **FD3L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 The fourth Flash Memory Data bit 7 ~ bit 0

• **FD3H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 The fourth Flash Memory Data bit 15 ~ bit 8

• **FC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	CFWEN	FMOD2	FMOD1	FMOD0	FWPEN	FWT	FRDEN	FRD
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **CFWEN**: Flash Memory Erase/Write function enable control
0: Flash Memory erase/write function is disabled
1: Flash Memory erase/write function has been successfully enabled
When this bit is cleared to 0 by application program, the Flash Memory erase/write function is disabled. Note that this bit cannot be set high by application programs. Writing "1" into this bit results in no action. This bit is used to indicate that the Flash Memory erase/write function status. When this bit is set to 1 by hardware, it means that the Flash Memory erase/write function is enabled successfully. Otherwise, the Flash Memory erase/write function is disabled as the bit content is zero.

Bit 6~4 **FMOD2~FMOD0**: Flash Memory Mode selection
000: Write Mode
001: Page erase Mode
010: Reserved
011: Read Mode
100: Reserved
101: Reserved
110: Flash Memory Erase/Write Function Enable Mode
111: Reserved
These bits are used to select the Flash Memory operation modes. Note that the "Flash Memory Erase/Write function Enable Mode" should first be successfully enabled before the Erase or Write Flash memory operation is executed.

Bit 3 **FWPEN**: Flash Memory Erase/Write function enable procedure trigger
0: Erase/Write function enable procedure is not triggered or procedure timer times out
1: Erase/Write function enable procedure is triggered and procedure timer starts to count
This bit is used to activate the Flash Memory Erase/Write function enable procedure and an internal timer. It is set by the application programs and then cleared by the hardware when the internal timer times out. The correct patterns must be written into the FD1L/FD1H, FD2L/FD2H and FD3L/FD3H register pairs respectively as soon as possible after the FWPEN bit is set high.

Bit 2 **FWT**: Flash Memory write initiate control
0: Do not initiate Flash Memory write or indicating that a Flash Memory write process has completed
1: Initiate a Flash Memory write process
This bit is set by software and cleared by the hardware when the Flash Memory write process has completed.

Bit 1 **FRDEN**: Flash Memory read enabled bit
0: Disable Flash Memory read
1: Enable Flash Memory read
This is the Flash Memory Read Enable bit which must be set high before any Flash Memory read operations are carried out. Clearing this bit to zero will inhibit Flash Memory read operations.

Bit 0 **FRD**: Flash Memory read control bit
0: Do not initiate Flash Memory read or indicating that a Flash Memory read process has completed
1: Initiate a Flash Memory read process
This bit is set by software and cleared by the hardware when the Flash Memory read process has completed.

Note: 1. The FWT, FRDEN and FRD bits cannot be set to "1" at the same time with a single instruction.
2. Ensure that the f_{SUB} clock is stable before executing the erase or write operation.
3. Note that the CPU will be stopped when a read, write or erase operation is successfully activated.
4. Ensure that the read, erase or write operation is totally complete before executing other operations.

• **FC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: Chip Reset Pattern
When a specific value of "55H" is written into this register, a reset signal will be generated to reset the whole chip.

• **FC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	CLWB
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as "0"

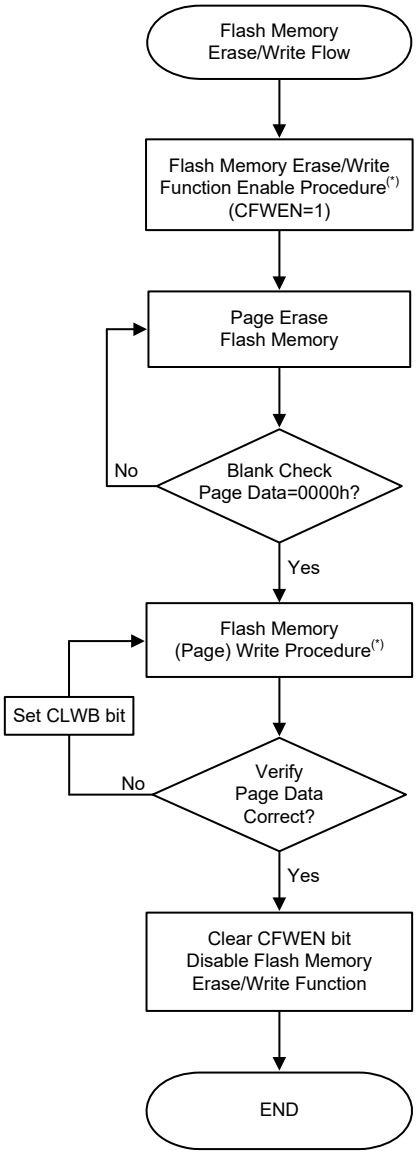
Bit 0 **CLWB**: Flash Memory Write buffer clear control
0: Do not initiate a Write Buffer Clear process or indicating that a Write Buffer Clear process has completed
1: Initiate a Write Buffer Clear process
This bit is set by software and cleared by hardware when the Write Buffer Clear process has completed.

Flash Memory Erase/Write Flow

It is important to understand the Flash Memory Erase/Write flow before the Flash Memory contents are updated. Users can refer to the corresponding operation procedures when developing their IAP program to ensure that the Flash Memory contents are correctly updated.

Flash Memory Erase/Write Flow Descriptions

1. Activate the "Flash Memory Erase/Write function enable procedure" first. When the Flash Memory Erase/Write function is successfully enabled, the CFWEN bit in the FC0 register will automatically be set high by hardware. After this, Erase or Write operations can be executed on the Flash memory. Refer to the "Flash Memory Erase/Write Function Enable Procedure" for details.
2. Configure the Flash memory address to select the desired erase page and then erase this page.
3. Execute a Blank Check operation to ensure whether the page erase operation is successful or not. The "TABRD" instruction should be executed to read the Flash memory contents and to check if the contents is 0000h or not. If the Flash memory page erase operation fails, users should go back to Step 2 and execute the page erase operation again.
4. Write data into the specific page. Refer to the "Flash Memory Write Procedure" for details.
5. Execute the "TABRD" instruction to read the Flash memory contents and check if the written data is correct or not. If the data read from the Flash memory is different from the written data, it means that the page write operation has failed. The CLWB bit should be set high to clear the write buffer and then write the data into the specific page again if the write operation has failed.
6. Clear the CFWEN bit to disable the Flash Memory Erase/Write function enable mode if the current page Erase and Write operations are completed and no more pages need to be erased or written.



Flash Memory Erase/Write Flow

Note: The Flash Memory Erase/Write Function Enable Procedure and Flash Memory Write Procedure will be described in the following sections.

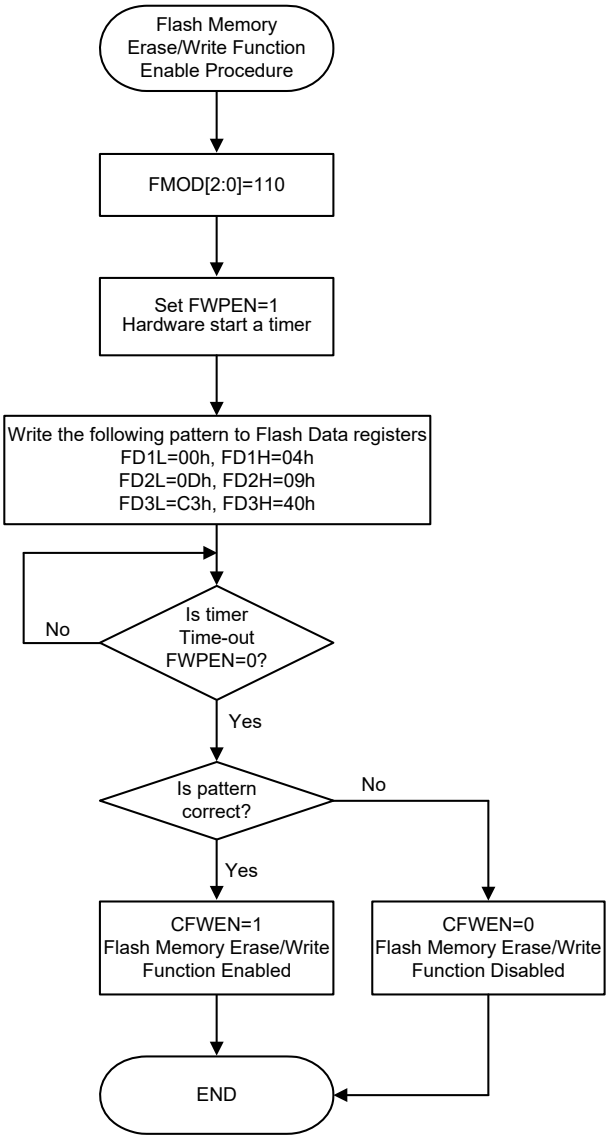
Flash Memory Erase/Write Function Enable Procedure

The Flash Memory Erase/Write Function Enable Mode is specially designed to prevent the Flash memory contents from being wrongly modified. In order to allow users to change the Flash memory data using the IAP control registers, users must first enable the Flash Memory Erase/Write function.

Flash Memory Erase/Write Function Enable Procedure Description

1. Write data "110" to the FMOD[2:0] bits in the FC0 register to select the Flash Memory Erase/Write Function Enable Mode.
2. Set the FWPEN bit in the FC0 register to "1" to activate the Flash Memory Erase/Write Function Enable Procedure. This will also activate an internal timer.
3. Write the correct data pattern into the Flash data registers, FD1L~FD3L and FD1H~FD3H, as soon as possible after the FWPEN bit is set high. The data pattern used to enable the Flash memory erase/write function is 00h, 0Dh, C3h, 04h, 09h and 40h corresponding to the FD1L~FD3L and FD1H~FD3H registers respectively.
4. Once the timer has timed out, the FWPEN bit will automatically be cleared to 0 by hardware regardless of the input data pattern.
5. If the written data pattern is incorrect, the Flash memory erase/write function will not be enabled successfully and the above steps should be repeated. If the written data pattern is correct, the Flash memory erase/write function will be enabled successfully.
6. Once the Flash memory erase/write function is enabled, the Flash memory contents can be updated by executing the page erase and write operations using the IAP control registers.

To disable the Flash memory erase/write function, the CFWEN bit in the FC0 register can be cleared. There is no need to execute the above procedure.



Flash Memory Erase/Write Function Enable Procedure

Flash Memory Write Procedure

After the Flash memory erase/write function has been successfully enabled as the CFWEN bit is set high, the data to be written into the Flash memory can be loaded into the write buffer. The selected Flash memory page data should be erased by properly configuring the IAP control registers before the data write procedure is executed.

The write buffer size is 32 words, known as a page, whose address is mapped to a specific Flash memory page specified by the memory address bits, FA11~FA5. It is important to ensure that the page where the write buffer data is located is the same one which the memory address bits, FA11~FA5, specify.

Flash Memory Consecutive Write Description

The maximum amount of data to be written is 32 words for each write operation. The write buffer address will be automatically increased by one when consecutive write operations are executed. The start address of a specific page should first be written into the FARL and FARH registers. Then the data word should first be written into the FD0L register and then the FD0H register. At the same time the write buffer address will be increased by one and then the next data word can be written into the FD0L and FD0H registers for the next address without modifying the address register pair, FARH and FARL. When the write buffer address reaches the page boundary, the address will not be further increased but will stop at the last address of the page.

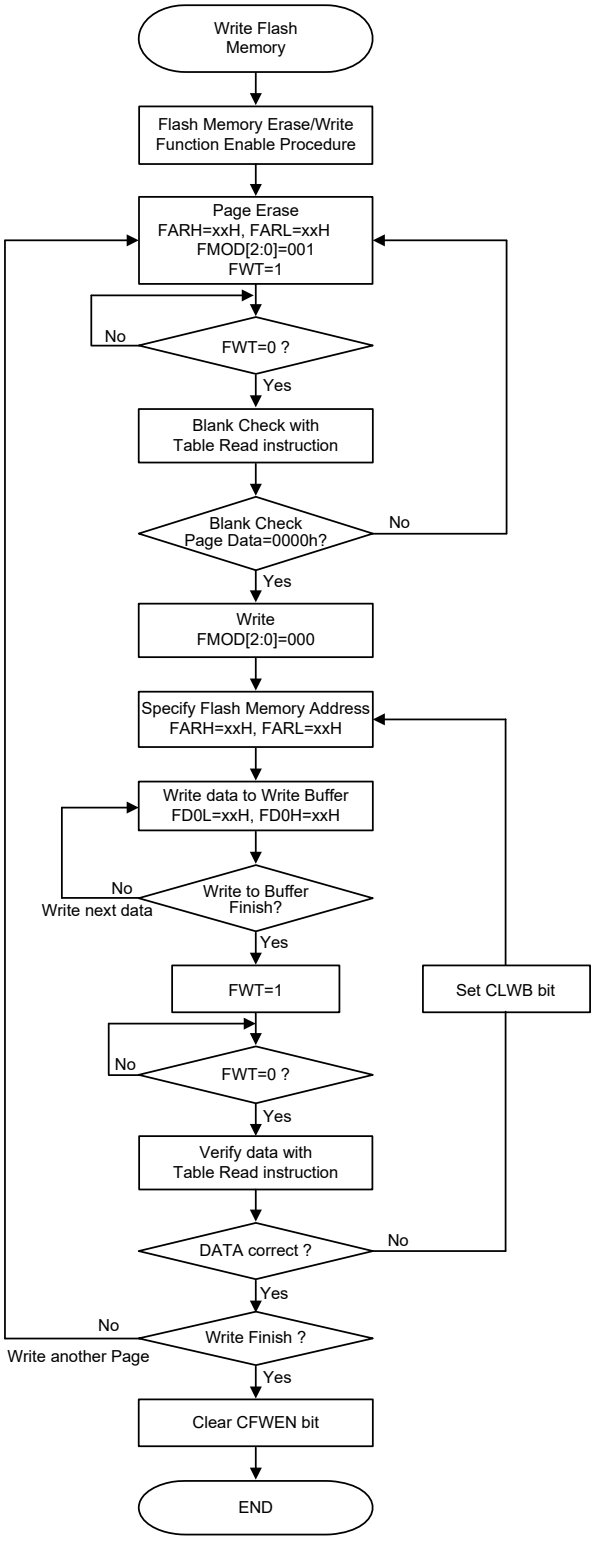
1. Activate the “Flash Memory Erase/Write function enable procedure”. Check the CFWEN bit value and then execute the erase/write operations if the CFWEN bit is set high. Refer to the “Flash Memory Erase/Write function enable procedure” for more details.
2. Set the FMOD field to “001” to select the erase operation. Set the FWT bit high to erase the desired page which is specified by the FARH and FARL registers. Wait until the FWT bit goes low.
3. Execute a Blank Check operation using the table read instruction to ensure that the erase operation has successfully completed.

   Go to step 2 if the erase operation is not successful.

   Go to step 4 if the erase operation is successful.
4. Set the FMOD field to “000” to select the write operation.
5. Set the desired start address in the FARH and FARL registers. Write the desired data words consecutively into the FD0L and FD0H registers within a page as specified by their consecutive addresses. The maximum amount of data could be written is 32 words.
6. Set the FWT bit high to write the data words from the write buffer to the Flash memory. Wait until the FWT bit goes low.

   Verify the data using the table read instruction to ensure that the write operation has successfully completed.

   If the write operation has not successfully completed, set the CLWB bit high to clear the write buffer and then go to step 5.
7. Go to step 8 if the write operation is successful.
8. Clear the CFWEN bit low to disable the Flash memory erase/write function.



Flash Memory Consecutive Write Procedure

Note: 1. When the erase or write operation is successfully activated, all CPU operations will temporarily cease.
2. It will take a typical time of 2.2ms for the FWT bit state changing from high to low.

Flash Memory Non-Consecutive Write Description

The main difference between Flash Memory Consecutive and Non-Consecutive Write operations is whether the data words to be written are located in consecutive addresses or not. If the data to be written is not located in consecutive addresses the desired address should be re-assigned after a data word is successfully written into the Flash memory.

A two data word non-consecutive write operation is taken as an example here and described as follows:

1. Activate the "Flash Memory Erase/Write function enable procedure". Check the CFWEN bit value and then execute the erase/write operation if the CFWEN bit is set high. Refer to the "Flash Memory Erase/Write function enable procedure" for more details.
2. Set the FMOD field to "001" to select the erase operation. Set the FWT bit high to erase the desired page which is specified by the FARH and FARL registers. Wait until the FWT bit goes low.
3. Execute a Blank Check operation using the table read instruction to ensure that the erase operation has successfully completed.

   Go to step 2 if the erase operation is not successful.

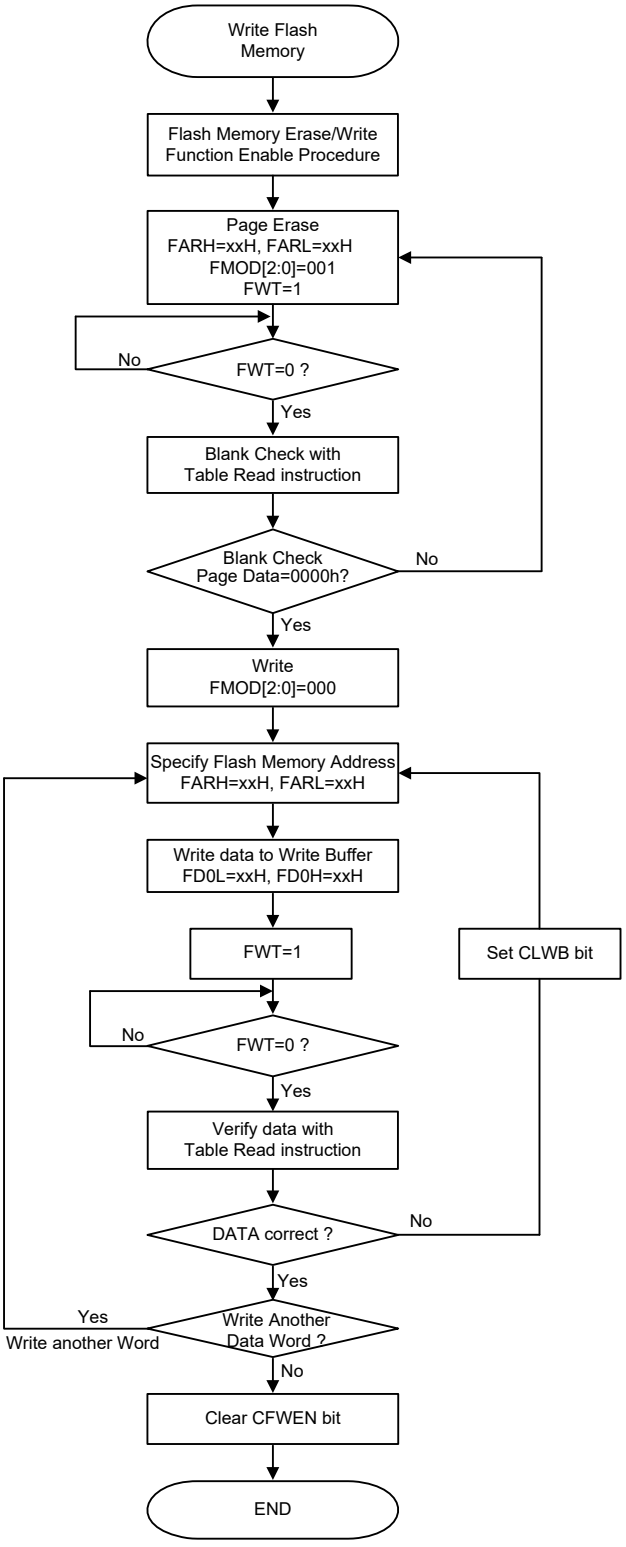
   Go to step 4 if the erase operation is successful.
4. Set the FMOD field to "000" to select the write operation.
5. Set the desired address ADDR1 in the FARH and FARL registers. Write the desired data word DATA1 first into the FD0L register and then into the FD0H register.
6. Set the FWT bit high to transfer the data word from the write buffer to the Flash memory. Wait until the FWT bit goes low.
7. Verify the data using the table read instruction to ensure that the write operation has successfully completed.

   If the write operation has not successfully completed, set the CLWB bit high to clear the write buffer and then go to step 5.

   Go to step 8 if the write operation is successful.
8. Set the desired address ADDR2 in the FARH and FARL registers. Write the desired data word DATA2 first into the FD0L register and then into the FD0H register.
9. Set the FWT bit high to transfer the data word from the write buffer to the Flash memory. Wait until the FWT bit goes low.
10. Verify the data using the table read instruction to ensure that the write operation has successfully completed.

    If the write operation has not successfully completed, set the CLWB bit high to clear the write buffer and then go to step 8.

    Go to step 11 if the write operation is successful.
11. Clear the CFWEN bit low to disable the Flash memory erase/write function.



Flash Memory Non-Consecutive Write Procedure

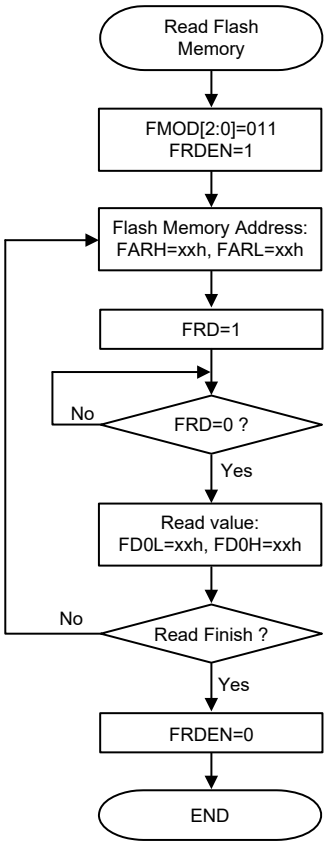
Note: 1. When the erase or write operation is successfully activated, all CPU operations will temporarily cease.
2. It will take a typical time of 2.2ms for the FWT bit state changing from high to low.

Important Points to Note for Flash Memory Write Operations

1. The “Flash Memory Erase/Write Function Enable Procedure” must be successfully activated before the Flash Memory erase/write operation is executed.
2. The Flash Memory erase operation is executed to erase a whole page.
3. The whole write buffer data will be written into the Flash memory in a page format. The corresponding address cannot exceed the page boundary.
4. After the data is written into the Flash memory, the Flash memory contents must be read out using the table read instruction, TABRD, and checked if it is correct or not. If the data written into the Flash memory is incorrect, the write buffer should be cleared by setting the CLWB bit high and then write the data again into the write buffer. Then activate a write operation on the same Flash memory page without erasing it. The data check, buffer clear and data re-write steps should be repeatedly executed until the data written into the Flash memory is correct.
5. The system frequency should be set to the maximum application frequency when data write and data check operations are executed using the IAP function.

Flash Memory Read Procedure

To activate the Flash Memory Read procedure, the FMOD field should be set to "011" to select the Flash memory read mode and the FRDEN bit should be set high to enable the read function. The desired Flash memory address should be written into the FARH and FARL registers and then the FRD bit should be set high. After this the Flash memory read operation will be activated. The data stored in the specified address can be read from the data registers, FD0H and FD0L, when the FRD bit goes low. There is no need to first activate the Flash Memory Erase/Write Function Enable Procedure before the Flash memory read operation is executed.



Flash Memory Read Procedure

Note: 1. When the read operation is successfully activated, all CPU operations will temporarily cease.
2. It will take a typical time of three instruction cycles for the FRD bit state changing from high to low.

Data Memory

The Data Memory is a volatile area of 8-bit wide RAM internal memory and is the location where temporary information is stored.

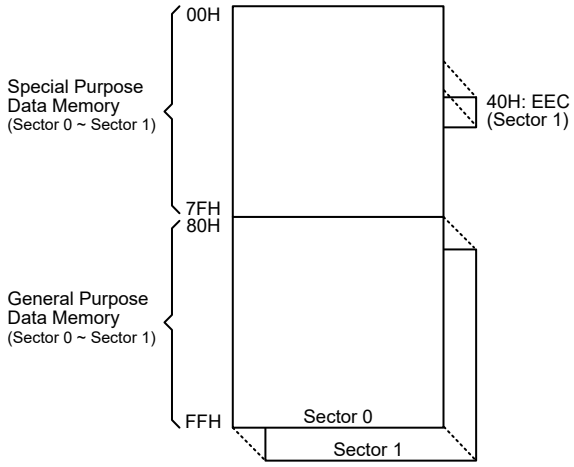
Categorized into two types, the first of these is an area of RAM where special function registers are located. These registers have fixed locations and are necessary for correct operation of the device. Many of these registers can be read from and written to directly under program control, however, some remain protected from user manipulation. The second area of Data Memory is reserved for general purpose use. All locations within this area are read and write accessible under program control.

Structure

The overall Data Memory is subdivided into several sectors, all of which are implemented in 8-bit wide RAM. Each of the Data Memory Sector is categorized into two types, the special Purpose Data Memory and the General Purpose Data Memory. The address range of the Special Purpose Data Memory for the device is from 00H to 7FH while the General Purpose Data Memory address range is from 80H to FFH. Switching between the different Data Memory sectors is achieved by setting the Memory Pointers to the correct value if using the indirect addressing method.

Special Purpose Data Memory	General Purpose Data Memory	
Located Sectors	**Capacity**	**Sector: Address**
Sector 0, Sector 1	256×8	Sector 0: 80H~FFH Sector 1: 80H~FFH

Data Memory Summary



Data Memory Structure

Data Memory Addressing

For this device that supports the extended instructions, there is no Bank Pointer for Data Memory addressing. For Data Memory the desired Sector is pointed by the MP1H or MP2H register and the certain Data Memory address in the selected sector is specified by the MP1L or MP2L register when using indirect addressing access.

Direct Addressing can be used in all sectors using the extended instruction which can address all available data memory space. For the accessed data memory which is located in any data memory sectors except sector 0, the extended instructions can be used to access the data memory instead of using the indirect addressing access. The main difference between standard instructions and extended instructions is that the data memory address “m” in the extended instructions has 9 valid bits for the device, the high byte indicates a sector and the low byte indicates a specific address.

General Purpose Data Memory

All microcontroller programs require an area of read/write memory where temporary data can be stored and retrieved for use later. It is this area of RAM memory that is known as General Purpose Data Memory. This area of Data Memory is fully accessible by the user programing for both reading and writing operations. By using the bit operation instructions individual bits can be set or reset under program control giving the user a large range of flexibility for bit manipulation in the Data Memory.

Special Purpose Data Memory

This area of Data Memory is where registers, necessary for the correct operation of the microcontroller, are stored. Most of the registers are both readable and writeable but some are protected and are readable only, the details of which are located under the relevant Special Function Register section. Note that for locations that are unused, any read instruction to these addresses will return the value “00H”.

	Sector 0	Sector 1
00H	IAR0	
01H	MP0	
02H	IAR1	
03H	MP1L	
04H	MP1H	
05H	ACC	
06H	PCL	
07H	TBLP	
08H	TBLH	
09H	TBHP	
0AH	STATUS	
0BH		
0CH	IAR2	
0DH	MP2L	
0EH	MP2H	
0FH	RSTFC	
10H	PB	
11H	PBC	
12H	PBPU	
13H	PBS0	
14H	PA	
15H	PAC	
16H	PAPU	
17H	PAWU	
18H	PAS0	
19H	PAS1	
1AH	SCC	
1BH	HIRCC	
1CH	SADC0	
1DH	SADC1	
1EH		
1FH	SADOL	
20H	SADOH	
21H	INTEG	
22H	LVRC	
23H	LVDC	
24H	OCPC0	
25H	OCPC1	
26H	OCPDA	
27H	OCPOCAL	
28H	OCPCCAL	
29H	IICC0	
2AH	IICC1	
2BH	IICD	
2CH	IICA	
2DH	IICTOC	
2EH	INTC0	
2FH	INTC1	
30H	INTC2	
31H	MFI0	
32H	MFI1	
33H	PSCR	
34H	TB0C	
35H	TB1C	
36H	WDTC	
37H	PTM0C0	
38H	PTM0C1	
39H	PTM0DL	
3AH	PTM0DH	
3BH	PTM0AL	
3CH	PTM0AH	
3DH	PTM0RPL	
3EH	PTM0RPH	
3FH	IECC	

	Sector 0	Sector 1
40H	SLEDC	EEC
41H	EEA	
42H	EED	
43H	PTM1C0	
44H	PTM1C1	
45H	PTM1DL	
46H	PTM1DH	
47H	PTM1AL	
48H	PTM1AH	
49H	PTM1RPL	
4AH	PTM1RPH	
4BH	HVIOC	
4CH	HVIOPC	
4DH		
4EH	STKPTR	
4FH		
50H	FC0	
51H	FC1	
52H	FC2	
53H	FARL	
54H	FARH	
55H	FD0L	
56H	FD0H	
57H	FD1L	
58H	FD1H	
59H	FD2L	
5AH	FD2H	
5BH	FD3L	
5CH	FD3H	
5DH		
5EH		
5FH		
60H	CRCCR	
61H	CRCIN	
62H	CRCDL	
63H	CRCDH	
64H		
65H		
66H		
67H		
68H		
69H		
6AH		
6BH		
6CH		
6DH		
6EH		
6FH		
70H		
71H		
72H		
73H		
74H		
75H		
76H		
77H		
78H		
79H		
7AH		
7BH		
7CH		
7DH		
7EH		
7FH		

: Unused, read as 00H

: Reserved, cannot be changed

Special Purpose Data Memory Structure

Special Function Register Description

Most of the Special Function Register details will be described in the relevant functional sections. However, several registers require a separate description in this section.

Indirect Addressing Registers – IAR0, IAR1, IAR2

The Indirect Addressing Registers, IAR0, IAR1 and IAR2, although having their locations in normal RAM register space, do not actually physically exist as normal registers. The method of indirect addressing for RAM data manipulation uses these Indirect Addressing Registers and Memory Pointers, in contrast to direct memory addressing, where the actual memory address is specified. Actions on the IAR0, IAR1 and IAR2 registers will result in no actual read or write operation to these registers but rather to the memory location specified by their corresponding Memory Pointers, MP0, MP1L/MP1H or MP2L/MP2H. Acting as a pair, IAR0 and MP0 can together access data only from Sector 0 while the IAR1 register together with the MP1L/MP1H register pair and IAR2 register together with the MP2L/MP2H register pair can access data from any Data Memory Sector. As the Indirect Addressing Registers are not physically implemented, reading the Indirect Addressing Registers will return a result of "00H" and writing to the registers will result in no operation.

Memory Pointers – MP0, MP1L/MP1H, MP2L/MP2H

Five Memory Pointers, known as MP0, MP1L, MP1H, MP2L, MP2H, are provided. These Memory Pointers are physically implemented in the Data Memory and can be manipulated in the same way as normal registers providing a convenient way with which to address and track data. When any operation to the relevant Indirect Addressing Registers is carried out, the actual address that the microcontroller is directed to is the address specified by the related Memory Pointer. MP0, together with Indirect Addressing Register, IAR0, are used to access data from Sector 0, while MP1L/MP1H together with IAR1 and MP2L/MP2H together with IAR2 are used to access data from all sectors according to the corresponding MP1H or MP2H register. Direct Addressing can be used in all sectors using the extended instruction which can address all available Data Memory space.

The following example shows how to clear a section of four Data Memory locations already defined as locations adres1 to adres4.

Indirect Addressing Program Example 1

```
data .section 'data'
adres1 db ?
adres2 db ?
adres3 db ?
adres4 db ?
block  db ?
code .section at 0 'code'
org 00h
start:
     mov a, 04h              ; set size of block
     mov block, a
     mov a, offset adres1    ; Accumulator loaded with first RAM address
     mov mp0, a              ; set memory pointer with first RAM address
loop:
     clr IAR0                ; clear the data at address defined by MP0
     inc mp0                 ; increase memory pointer
     sdz block               ; check if last memory location has been cleared
     jmp loop
continue:
```

Indirect Addressing Program Example 2

```
data .section ′data′
adres1 db ?
adres2 db ?
adres3 db ?
adres4 db ?
block  db ?
code .section at 0 ′code′
org 00h
start:
     mov a, 04h              ; set size of block
     mov block, a
     mov a, 01h              ; set the memory sector
     mov mp1h, a
     mov a, offset adres1    ; Accumulator loaded with first RAM address
     mov mp1l, a             ; set memory pointer with first RAM address
loop:
     clr IAR1                ; clear the data at address defined by MP1L
     inc mp1l                ; increase memory pointer MP1L
     sdz block               ; check if last memory location has been cleared
     jmp loop
continue:
```

The important point to note here is that in the example shown above, no reference is made to specific Data Memory addresses.

Direct Addressing Program Example using extended instructions

```
data .section ′data′
temp db ?
code .section at 0 ′code′
org 00h
start:
     lmov a, [m]             ; move [m] data to acc
     lsub a, [m+1]           ; compare [m] and [m+1] data
     snz  c                  ; [m]>[m+1]?
     jmp  continue           ; no
     lmov a, [m]             ; yes, exchange [m] and [m+1] data
     mov  temp, a
     lmov a, [m+1]
     lmov [m], a
     mov  a, temp
     lmov [m+1], a
continue:
```

Note: here “m” is a data memory address located in any data memory sectors. For example, m=1F0H, it indicates address 0F0H in Sector 1.

Accumulator – ACC

The Accumulator is central to the operation of any microcontroller and is closely related with operations carried out by the ALU. The Accumulator is the place where all intermediate results from the ALU are stored. Without the Accumulator it would be necessary to write the result of each calculation or logical operation such as addition, subtraction, shift, etc., to the Data Memory resulting in higher programming and timing overheads. Data transfer operations usually involve the temporary storage function of the Accumulator; for example, when transferring data between one user-defined register and another, it is necessary to do this by passing the data through the Accumulator as no direct transfer between two registers is permitted.

Program Counter Low Byte Register – PCL

To provide additional program control functions, the low byte of the Program Counter is made accessible to programmers by locating it within the Special Purpose area of the Data Memory. By manipulating this register, direct jumps to other program locations are easily implemented. Loading a value directly into this PCL register will cause a jump to the specified Program Memory location, however, as the register is only 8-bit wide, only jumps within the current Program Memory page are permitted. When such operations are used, note that a dummy cycle will be inserted.

Look-up Table Registers – TBLP, TBHP, TBLH

These three special function registers are used to control operation of the look-up table which is stored in the Program Memory. TBLP and TBHP are the table pointers and indicate the location where the table data is located. Their value must be set before any table read commands are executed. Their value can be changed, for example using the "INC" or "DEC" instructions, allowing for easy table data pointing and reading. TBLH is the location where the high order byte of the table data is stored after a table read data instruction has been executed. Note that the lower order table data byte is transferred to a user defined location.

Status Register – STATUS

This 8-bit register contains the SC flag, CZ flag, zero flag (Z), carry flag (C), auxiliary carry flag (AC), overflow flag (OV), power down flag (PDF), and watchdog time-out flag (TO). These arithmetic/logical operation and system management flags are used to record the status and operation of the microcontroller.

With the exception of the TO and PDF flags, bits in the status register can be altered by instructions like most other registers. Any data written into the status register will not change the TO or PDF flag. In addition, operations related to the status register may give different results due to the different instruction operations. The TO flag can be affected only by a system power-up, a WDT time-out or by executing the "CLR WDT" or "HALT" instruction. The PDF flag is affected only by executing the "HALT" or "CLR WDT" instruction or during a system power-up.

The Z, OV, AC, C, SC and CZ flags generally reflect the status of the latest operations.

- C is set if an operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation; otherwise C is cleared. C is also affected by a rotate through carry instruction.
- AC is set if an operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction; otherwise AC is cleared.
- Z is set if the result of an arithmetic or logical operation is zero; otherwise Z is cleared.
- OV is set if an operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa; otherwise OV is cleared.
- PDF is cleared by a system power-up or executing the "CLR WDT" instruction. PDF is set by executing the "HALT" instruction.
- TO is cleared by a system power-up or executing the "CLR WDT" or "HALT" instruction. TO is set by a WDT time-out.
- CZ is the operational result of different flags for different instructions. Refer to register definitions for more details.
- SC is the result of the "XOR" operation which is performed by the OV flag and the MSB of the current instruction operation result.

In addition, on entering an interrupt sequence or executing a subroutine call, the status register will not be pushed onto the stack automatically. If the contents of the status register are important and if the subroutine can corrupt the status register, precautions must be taken to correctly save it.

• **STATUS Register**

Bit	7	6	5	4	3	2	1	0
Name	SC	CZ	TO	PDF	OV	Z	AC	C
R/W	R/W	R/W	R	R	R/W	R/W	R/W	R/W
POR	x	x	0	0	x	x	x	x

"x": unknown

Bit 7 **SC**: The result of the "XOR" operation which is performed by the OV flag and the MSB of the instruction operation result.

Bit 6 **CZ**: The operational result of different flags for different instructions.
For SUB/SUBM/LSUB/LSUBM instructions, the CZ flag is equal to the Z flag.
For SBC/SBCM/LSBC/LSBCM instructions, the CZ flag is the "AND" operation result which is performed by the previous operation CZ flag and current operation zero flag.
For other instructions, the CZ flag will not be affected.

Bit 5 **TO**: Watchdog Time-out flag
0: After power up or executing the "CLR WDT" or "HALT" instruction
1: A watchdog time-out occurred

Bit 4 **PDF**: Power down flag
0: After power up or executing the "CLR WDT" instruction
1: By executing the "HALT" instruction

Bit 3 **OV**: Overflow flag
0: No overflow
1: An operation results in a carry into the highest-order bit but not a carry out of the highest-order bit or vice versa

Bit 2 **Z**: Zero flag
0: The result of an arithmetic or logical operation is not zero
1: The result of an arithmetic or logical operation is zero

Bit 1 **AC**: Auxiliary flag
0: No auxiliary carry
1: An operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction

Bit 0 **C**: Carry flag
0: No carry-out
1: An operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation
The "C" flag is also affected by a rotate through carry instruction.

EEPROM Data Memory

The device contains an area of internal EEPROM Data Memory. EEPROM is by its nature a non-volatile form of re-programmable memory, with data retention even when its power supply is removed. By incorporating this kind of data memory, a whole new host of application possibilities are made available to the designer. The availability of EEPROM storage allows information such as product identification numbers, calibration values, specific user data, system setup data or other product information to be stored directly within the product microcontroller. The process of reading and writing data to the EEPROM memory has been reduced to a very trivial affair.

EEPROM Data Memory Structure

The EEPROM Data Memory capacity is 32×8 bits for the device. Unlike the Program Memory and RAM Data Memory, the EEPROM Data Memory is not directly mapped into memory space and is therefore not directly addressable in the same way as the other types of memory. Read and Write operations to the EEPROM are carried out in single byte operations using an address and a data register in Sector 0 and a single control register in Sector 1.

EEPROM Registers

Three registers control the overall operation of the internal EEPROM Data Memory. These are the address register, EEA, the data register, EED and a single control register, EEC. As both the EEA and EED registers are located in Sector 0, they can be directly accessed in the same way as any other Special Function Register. The EEC register however, being located in only Sector 1, can only be read from or written to indirectly using the MP1L/MP1H or MP2L/MP2H Memory Pointer and Indirect Addressing Register, IAR1/IAR2. As it is located at address 40H in Sector 1, the MP1L or MP2L Memory Pointer must first be set to the value 40H and the MP1H or MP2H Memory Pointer high byte set to the value, 01H, before any operations on the EEC register are executed.

Register Name	Bit							
	7	6	5	4	3	2	1	0
EEA	—	—	—	EEA4	EEA3	EEA2	EEA1	EEA0
EED	EED7	EED6	EED5	EED4	EED3	EED2	EED1	EED0
EEC	—	—	—	—	WREN	WR	RDEN	RD

EEPROM Register List

- **EEA Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	EEA4	EEA3	EEA2	EEA1	EEA0
R/W	—	—	—	R/W	R/W	R/W	R/W	R/W
POR	—	—	—	0	0	0	0	0

Bit 7~5 Unimplemented, read as "0"

Bit 4~0 **EEA4~EEA0**: Data EEPROM address bit 4 ~ bit 0

- **EED Register**

Bit	7	6	5	4	3	2	1	0
Name	EED7	EED6	EED5	EED4	EED3	EED2	EED1	EED0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **EED7~EED0**: Data EEPROM data bit 7 ~ bit 0

• **EEC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	WREN	WR	RDEN	RD
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3 **WREN**: Data EEPROM Write Enable
0: Disable
1: Enable
This is the Data EEPROM Write Enable Bit which must be set high before Data EEPROM write operations are carried out. Clearing this bit to zero will inhibit Data EEPROM write operations.

Bit 2 **WR**: EEPROM Write Control
0: Write cycle has finished
1: Activate a write cycle
This is the Data EEPROM Write Control Bit and when set high by the application program will activate a write cycle. This bit will be automatically reset to zero by the hardware after the write cycle has finished. Setting this bit high will have no effect if the WREN has not first been set high.

Bit 1 **RDEN**: Data EEPROM Read Enable
0: Disable
1: Enable
This is the Data EEPROM Read Enable Bit which must be set high before Data EEPROM read operations are carried out. Clearing this bit to zero will inhibit Data EEPROM read operations.

Bit 0 **RD**: EEPROM Read Control
0: Read cycle has finished
1: Activate a read cycle
This is the Data EEPROM Read Control Bit and when set high by the application program will activate a read cycle. This bit will be automatically reset to zero by the hardware after the read cycle has finished. Setting this bit high will have no effect if the RDEN has not first been set high.

Note: 1. The WREN, WR, RDEN and RD bits cannot be set high at the same time in one instruction. The WR and RD bits cannot be set high at the same time.
2. Ensure that the f_{SUB} clock is stable before executing the write operation.
3. Ensure that the write operation is totally complete before changing the contents of the EEPROM related registers.

Reading Data from the EEPROM

To read data from the EEPROM, the EEPROM address of the data to be read must first be placed in the EEA register. The read enable bit, RDEN, in the EEC register must then be set high to enable the read function. If the RD bit in the EEC register is now set high, a read cycle will be initiated. Setting the RD bit high will not initiate a read operation if the RDEN bit has not been set. When the read cycle terminates, the RD bit will be automatically cleared to zero, after which the data can be read from the EED register. The data will remain in the EED register until another read or write operation is executed. The application program can poll the RD bit to determine when the data is valid for reading.

Writing Data to the EEPROM

To write data to the EEPROM, the EEPROM address of the data to be written must first be placed in the EEA register and the data placed in the EED register. To initiate a write cycle the write enable bit, WREN, in the EEC register must first be set high to enable the write function. After this, the WR bit in the EEC register must be immediately set high to initiate a write cycle successfully. These two instructions must be executed in two consecutive instruction cycles. The global interrupt bit EMI should also first be cleared before implementing any write operations, and then set high again after the write cycle has started. Note that setting the WR bit high will not initiate a write cycle if the WREN bit has not been set. As the EEPROM write cycle is controlled using an internal timer whose operation is asynchronous to microcontroller system clock, a certain time will elapse before the data will have been written into the EEPROM. Detecting when the write cycle has finished can be implemented either by polling the WR bit in the EEC register or by using the EEPROM interrupt. When the write cycle terminates, the WR bit will be automatically cleared to zero by the microcontroller, informing the user that the data has been written to the EEPROM. The application program can therefore poll the WR bit to determine when the write cycle has ended.

Write Protection

Protection against inadvertent write operation is provided in several ways. After the device is powered-on the Write Enable bit in the control register will be cleared preventing any write operations. Also at power-on the Memory Pointer high byte register, MP1H or MP2H, will be reset to zero, which means that Data Memory Sector 0 will be selected. As the EEPROM control register is located in Sector 1, this adds a further measure of protection against spurious write operations. During normal program operation, ensuring that the Write Enable bit in the control register is cleared will safeguard against incorrect write operations.

EEPROM Interrupt

The EEPROM write interrupt is generated when an EEPROM write cycle has ended. The EEPROM interrupt must first be enabled by setting the DEE bit in the relevant interrupt register. When an EEPROM write cycle ends, the DEF request flag will be set. If the global and EEPROM interrupts are enabled and the stack is not full, a jump to the EEPROM Interrupt vector will take place. When the interrupt is serviced the EEPROM Interrupt flag, DEF, will be automatically reset. More details can be obtained in the Interrupt section.

Programming Considerations

Care must be taken that data is not inadvertently written to the EEPROM. Protection can be enhanced by ensuring that the Write Enable bit is normally cleared to zero when not writing. Also the Memory Pointer high byte register, MP1H or MP2H, could be normally cleared to zero as this would inhibit access to Sector 1 where the EEPROM control register exists. Although certainly not necessary, consideration might be given in the application program to the checking of the validity of new write data by a simple read back process.

When writing data the WR bit must be set high immediately after the WREN bit has been set high, to ensure the write cycle executes correctly. The global interrupt bit EMI should also be cleared before a write cycle is executed and then re-enabled after the write cycle starts. Note that the device should not enter the IDLE or SLEEP mode until the EEPROM read or write operation is totally complete. Otherwise, the EEPROM read or write operation will fail.

Programming Examples

Reading Data from the EEPROM – Polling Method

```
MOV  A, EEPROM_ADRES          ; user defined address
MOV  EEA, A
MOV  A, 40H                   ; set memory pointer MP1L
MOV  MP1L, A                  ; MP1L points to EEC register
MOV  A, 01H                   ; set memory pointer MP1H
MOV  MP1H, A
SET  IAR1.1                   ; set RDEN bit, enable read operations
SET  IAR1.0                   ; start Read Cycle - set RD bit
BACK:
SZ   IAR1.0                   ; check for read cycle end
JMP  BACK
CLR  IAR1                     ; disable EEPROM read if no more read operations are required
CLR  MP1H
MOV  A, EED                   ; move read data to register
MOV  READ_DATA, A
```

Note: For each read operation, the address register should be re-specified followed by setting the RD bit high to activate a read cycle even if the target address is consecutive.

Writing Data to the EEPROM – Polling Method

```
MOV  A, EEPROM_ADRES          ; user defined address
MOV  EEA, A
MOV  A, EEPROM_DATA           ; user defined data
MOV  EED, A
MOV  A, 40H                   ; set memory pointer MP1L
MOV  MP1L, A                  ; MP1L points to EEC register
MOV  A, 01H                   ; set memory pointer MP1H
MOV  MP1H, A
CLR  EMI
SET  IAR1.3                   ; set WREN bit, enable write operations
SET  IAR1.2                   ; start Write Cycle - set WR bit - executed immediately
                              ; after setting WREN bit
SET  EMI
BACK:
SZ   IAR1.2                   ; check for write cycle end
JMP  BACK
CLR  MP1H
```

Oscillators

Various oscillator types offer the user a wide range of functions according to their various application requirements. The flexible features of the oscillator functions ensure that the best optimisation can be achieved in terms of speed and power saving. Oscillator selections and operation are selected through the relevant control registers.

Oscillator Overview

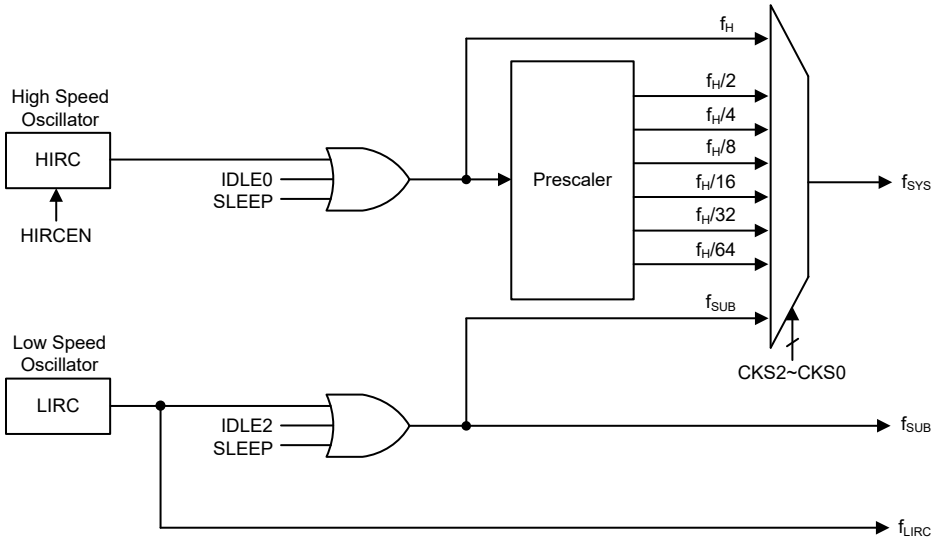
In addition to being the source of the main system clock the oscillators also provide clock sources for the Watchdog Timer and Time Base Interrupts. Fully integrated internal oscillators requiring no external components, are provided to form a wide range of both fast and slow system oscillators. The higher frequency oscillator provides higher performance but carry with it the disadvantage of higher power requirements, while the opposite is of course true for the lower frequency oscillator. With the capability of dynamically switching between fast and slow system clock, the device has the flexibility to optimize the performance/power ratio, a feature especially important in power sensitive portable applications.

Type	Name	Frequency
Internal High Speed RC	HIRC	8MHz
Internal Low Speed RC	LIRC	32kHz

Oscillator Types

System Clock Configurations

There are two oscillator sources, one high speed oscillator and one low speed oscillator. The high speed oscillator is the internal 8MHz RC oscillator, HIRC. The low speed oscillator is the internal 32kHz RC oscillator, LIRC. Selecting whether the low or high speed oscillator is used as the system oscillator is implemented using the CKS2~CKS0 bits in the SCC register and as the system clock can be dynamically selected.



System Clock Configurations

Internal High Speed RC Oscillator – HIRC

The internal RC oscillator is a fully integrated system oscillator requiring no external components and has a fixed frequency of 8MHz. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised.

Internal 32kHz Oscillator – LIRC

The Internal 32kHz System Oscillator is a fully integrated low frequency RC oscillator with a typical frequency of 32kHz, requiring no external components for its implementation. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised.

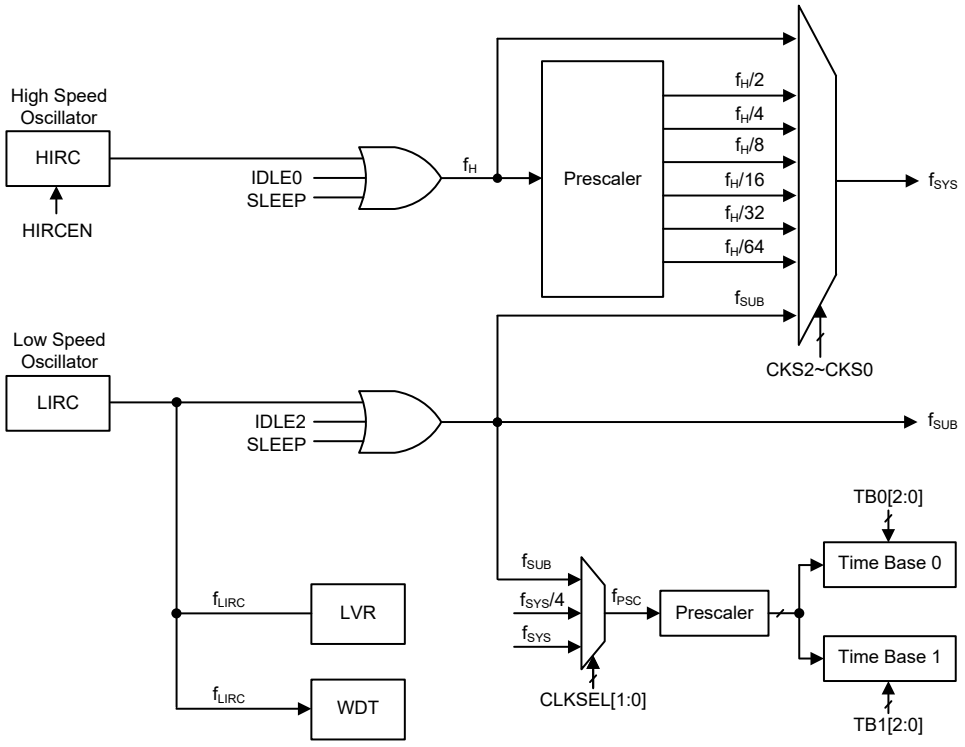
Operating Modes and System Clocks

Present day applications require that their microcontrollers have high performance but often still demand that they consume as little power as possible, conflicting requirements that are especially true in battery powered portable applications. The fast clocks required for high performance will by their nature increase current consumption and of course vice versa, lower speed clocks reduce current consumption. As Holtek has provided the device with both high and low speed clock sources and the means to switch between them dynamically, the user can optimise the operation of their microcontroller to achieve the best performance/power ratio.

System Clocks

The device has many different clock sources for both the CPU and peripheral function operation. By providing the user with a wide range of clock options using register programming, a clock system can be configured to obtain maximum application performance.

The main system clock can come from a high frequency f_H or low frequency f_{SUB} source, and is selected using the CKS2~CKS0 bits in the SCC register. The high speed system clock can be sourced from the HIRC oscillator. The low speed system clock comes from the internal clock f_{SUB} which is sourced from the LIRC oscillator. The other choice, which is a divided version of the high speed system oscillator has a range of $f_H/2$~$f_H/64$.



Device Clock Configurations

Note: When the system clock source f_{SYS} is switched to f_{SUB} from f_H, the high speed oscillator can be stopped to conserve the power or continue to oscillate to provide the clock source, f_H~$f_H/64$, for peripheral circuits to use, which is determined by configuring the corresponding high speed oscillator enable control bit.

System Operation Modes

There are six different modes of operation for the microcontroller, each one with its own special characteristics and which can be chosen according to the specific performance and power requirements of the application. There are two modes allowing normal operation of the microcontroller, the FAST Mode and SLOW Mode. The remaining four modes, the SLEEP, IDLE0, IDLE1 and IDLE2 Mode are used when the microcontroller CPU is switched off to conserve power.

Operation Mode	CPU	Register Setting			f_{SYS}	f_H	f_{SUB}	f_{LIRC}
		FHIDEN	FSIDEN	CKS2~CKS0				
FAST	On	x	x	000~110	f_H~$f_H/64$	On	On	On
SLOW	On	x	x	111	f_{SUB}	On/Off (1)	On	On
IDLE0	Off	0	1	000~110	Off	Off	On	On
				111	On			
IDLE1	Off	1	1	xxx	On	On	On	On
IDLE2	Off	1	0	000~110	On	On	Off	On
				111	Off			
SLEEP	Off	0	0	xxx	Off	Off	Off	On/Off (2)

"x": don't care

Note: 1. The f_H clock will be switched on or off by configuring the corresponding oscillator enable bit in the SLOW mode.

2. The f_{LIRC} clock can be on or off which is controlled by the WDT function being enabled or disabled in the SLEEP mode.

FAST Mode

This is one of the main operating modes where the microcontroller has all of its functions operational and where the system clock is provided by the high speed oscillator. This mode operates allowing the microcontroller to operate normally with a clock source coming from the HIRC oscillator. The high speed oscillator will however first be divided by a ratio ranging from 1 to 64, the actual ratio being selected by the CKS2~CKS0 bits in the SCC register. Although a high speed oscillator is used, running the microcontroller at a divided clock ratio reduces the operating current.

SLOW Mode

This is also a mode where the microcontroller operates normally although now with a slower speed clock source. The clock source used will be from f_{SUB}. The f_{SUB} clock is derived from the LIRC oscillator.

SLEEP Mode

The SLEEP Mode is entered when a HALT instruction is executed and when the FHIDEN and FSIDEN bit are low. In the SLEEP mode the CPU will be stopped. The f_{SUB} clock provided to the peripheral function will also be stopped, too. However the f_{LIRC} clock will continue to operate if the WDT function is enabled by the WDTC register.

IDLE0 Mode

The IDLE0 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is low and the FSIDEN bit in the SCC register is high. In the IDLE0 Mode the CPU will be switched off but the low speed oscillator will be on to drive some peripheral functions.

IDLE1 Mode

The IDLE1 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is high. In the IDLE1 Mode the CPU will be switched off but both the high and low speed oscillators will be on to provide a clock source to keep some peripheral functions operational.

IDLE2 Mode

The IDLE2 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is low. In the IDLE2 Mode the CPU will be switched off but the high speed oscillator will be on to provide a clock source to keep some peripheral functions operational.

Control Registers

The registers, SCC and HIRCC, are used to control the system clock and the corresponding oscillator configurations.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SCC	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
HIRCC	—	—	—	—	—	—	HIRCF	HIRCEN

System Operating Mode Control Register List

• **SCC Register**

Bit	7	6	5	4	3	2	1	0
Name	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
R/W	R/W	R/W	R/W	—	—	—	R/W	R/W
POR	0	0	0	—	—	—	0	0

Bit 7~5 **CKS2~CKS0**: System clock selection
000: f_H
001: $f_H/2$
010: $f_H/4$
011: $f_H/8$
100: $f_H/16$
101: $f_H/32$
110: $f_H/64$
111: f_{SUB}
These three bits are used to select which clock is used as the system clock source. In addition to the system clock source directly derived from f_H or f_{SUB}, a divided version of the high speed system oscillator can also be chosen as the system clock source.

Bit 4~2 Unimplemented, read as "0"

Bit 1 **FHIDEN**: High frequency oscillator control when CPU is switched off
0: Disable
1: Enable
This bit is used to control whether the high speed oscillator is activated or stopped when the CPU is switched off by executing a "HALT" instruction.

Bit 0 **FSIDEN**: Low frequency oscillator control when CPU is switched off
0: Disable
1: Enable
This bit is used to control whether the low speed oscillator is activated or stopped when the CPU is switched off by executing a "HALT" instruction.

Note: A certain delay is required before the relevant clock is successfully switched to the target clock source after any clock switching setup using the CKS2~CKS0 bits. A proper delay time must be arranged before executing the following operations which require immediate reaction with the target clock source.

$$\text{Clock switching delay time} = 4\times t_{SYS} + [0\sim(1.5\times t_{Curr.}+0.5\times t_{Tar.})]$$

Where $t_{Curr.}$ indicates the current clock period, $t_{Tar.}$ indicates the target clock period and t_{SYS} indicates the current system clock period.

• **HIRCC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	HIRCF	HIRCEN
R/W	—	—	—	—	—	—	R	R/W
POR	—	—	—	—	—	—	0	1

Bit 7~2 Unimplemented, read as "0"

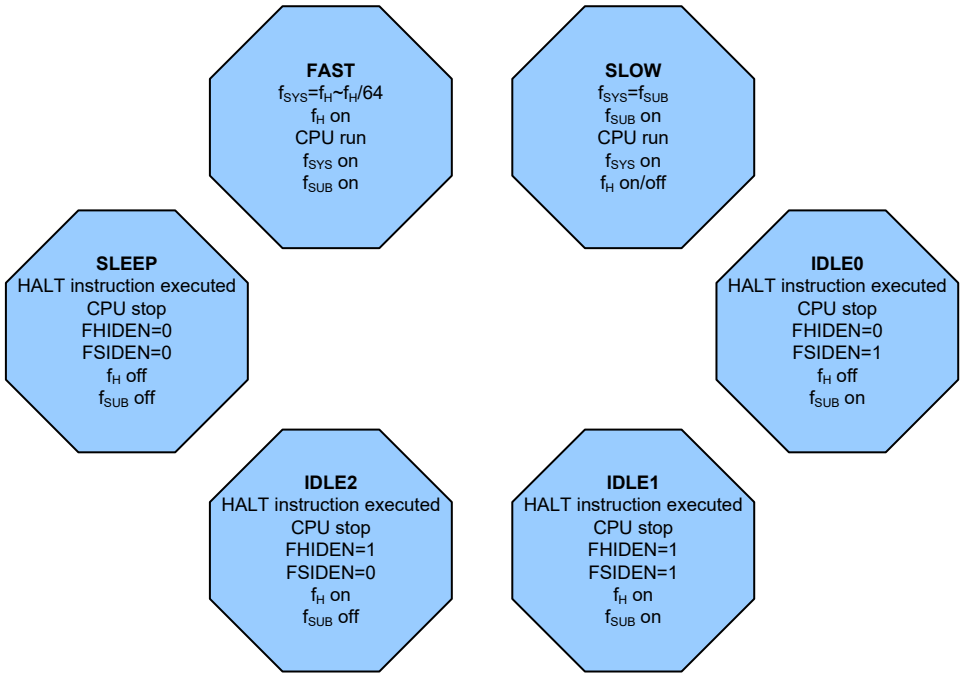
Bit 1 **HIRCF**: HIRC oscillator stable flag
0: Unstable
1: Stable
This bit is used to indicate whether the HIRC oscillator is stable or not. When the HIRCEN bit is set to 1 to enable the HIRC oscillator, the HIRCF bit will first be cleared to 0 and then set to 1 after the HIRC oscillator is stable.

Bit 0 **HIRCEN**: HIRC oscillator enable control
0: Disable
1: Enable

Operating Mode Switching

The device can switch between operating modes dynamically allowing the user to select the best performance/power ratio for the present task in hand. In this way microcontroller operations that do not require high performance can be executed using slower clocks thus requiring less operating current and prolonging battery life in portable applications.

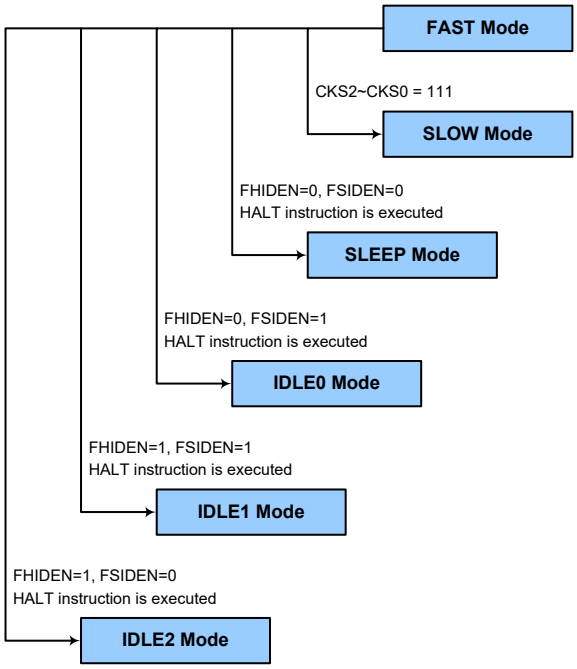
In simple terms, mode switching between the FAST Mode and SLOW Mode is executed using the CKS2~CKS0 bits in the SCC register while mode switching from the FAST/SLOW Mode to the SLEEP/IDLE Mode is executed via the HALT instruction. When a HALT instruction is executed, whether the device enters the IDLE Mode or the SLEEP Mode is determined by the condition of the FHIDEN and FSIDEN bits in the SCC register.



FAST Mode to SLOW Mode Switching

When running in the FAST Mode, which uses the high speed system oscillator, and therefore consumes more power, the system clock can switch to run in the SLOW Mode by setting the CKS2~CKS0 bits to "111" in the SCC register. This will then use the low speed system oscillator which will consume less power. Users may decide to do this for certain operations which do not require high performance and can subsequently reduce power consumption.

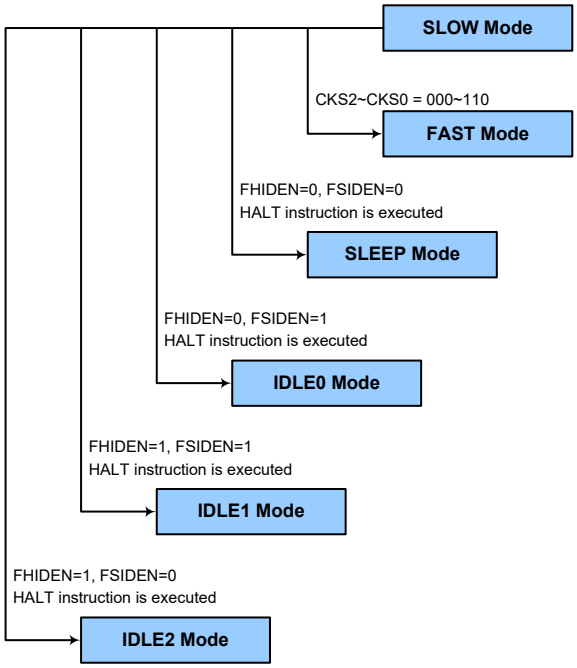
The SLOW Mode is sourced from the LIRC oscillator and therefore requires this oscillator to be stable before full mode switching occurs.



SLOW Mode to FAST Mode Switching

In the SLOW mode the system clock is derived from f_{SUB}. When system clock is switched back to the FAST mode from f_{SUB}, the CKS2~CKS0 bits should be set to "000"~"110" and then the system clock will respectively be switched to f_H~f_H/64.

However, if f_H is not used in the SLOW mode and thus switched off, it will take some time to re-oscillate and stabilise when switching to the FAST mode from the SLOW Mode. This is monitored using the HIRCF bit. The time duration required for the high speed system oscillator stabilization is specified in the System Start Up Time Characteristics.



Entering the SLEEP Mode

There is only one way for the device to enter the SLEEP Mode and that is to execute the "HALT" instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to "0". In this mode all the clocks and functions will be switched off except the WDT function. When this instruction is executed under the conditions described above, the following will occur:

- The system clock will be stopped and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and then stopped.

Entering the IDLE0 Mode

There is only one way for the device to enter the IDLE0 Mode and that is to execute the "HALT" instruction in the application program with the FHIDEN bit in the SCC register equal to "0" and the FSIDEN bit in the SCC register equal to "1". When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be stopped and the application program will stop at the "HALT" instruction, but the f_{SUB} clock will be on.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and then stopped.

Entering the IDLE1 Mode

There is only one way for the device to enter the IDLE1 Mode and that is to execute the "HALT" instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to "1". When this instruction is executed under the conditions described above, the following will occur:

- The f_H and f_{SUB} clocks will be on but the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and then stopped.

Entering the IDLE2 Mode

There is only one way for the device to enter the IDLE2 Mode and that is to execute the "HALT" instruction in the application program with the FHIDEN bit in the SCC register equal to "1" and the FSIDEN bit in the SCC register equal to "0". When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be on but the f_{SUB} clock will be off and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and then stopped.

Standby Current Considerations

As the main reason for entering the SLEEP or IDLE Mode is to keep the current consumption of the device to as low a value as possible, perhaps only in the order of several micro-amps except in the IDLE1 and IDLE2 Mode, there are other considerations which must also be taken into account by the circuit designer if the power consumption is to be minimised. Special attention must be made to the I/O pins on the device. All high-impedance input pins must be connected to either a fixed high or low level as any floating input pins could create internal oscillations and result in increased current consumption. This also applies to the device which has different package types, as there may be unbonded pins. These must either be set as outputs or if set as inputs must have pull-high resistors connected.

Care must also be taken with the loads, which are connected to I/O pins, which are set as outputs. These should be placed in a condition in which minimum current is drawn or connected only to external circuits that do not draw current, such as other CMOS inputs. Also note that additional standby current will also be required if the LIRC oscillator has been enabled.

In the IDLE1 and IDLE2 Mode the high speed oscillator is on and if the system clock is from the high speed system oscillator, the additional standby current will also be perhaps in the order of several hundred micro-amps.

Wake-up

To minimise power consumption the device can enter the SLEEP or any IDLE Mode, where the CPU will be switched off. However, when the device is woken up again, it will take a considerable time for the original system oscillator to restart, stabilise and allow normal operation to resume.

After the system enters the SLEEP or IDLE Mode, it can be woken up from one of various sources listed as follows:

- An external falling edge on Port A
- A system interrupt
- A WDT overflow

When the device executes the "HALT" instruction, it will enter the SLEEP or IDLE mode and the PDF flag will be set high. The PDF flag will be cleared to 0 if the device experiences a system power-up or executes the clear Watchdog Timer instruction. If the system is woken up by a WDT overflow, a Watchdog Time-out hardware reset will be initiated and the TO flag will be set to 1. The TO flag is set if a WDT time-out occurs and causes a wake-up that only resets the Program Counter and Stack Pointer, other flags remain in their original status.

Each pin on Port A can be set using the PAWU register to permit a negative transition on the pin to wake up the system. When a pin wake-up occurs, the program will resume execution at the instruction following the "HALT" instruction. If the system is woken up by an interrupt, then two possible situations may occur. The first is where the related interrupt is disabled or the interrupt is enabled but the stack is full, in which case the program will resume execution at the instruction following the "HALT" instruction. In this situation, the interrupt which woke-up the device will not be immediately serviced, but will rather be serviced later when the related interrupt is finally enabled or when a stack level becomes free. The other situation is where the related interrupt is enabled and the stack is not full, in which case the regular interrupt response takes place. If an interrupt request flag is set high before entering the SLEEP or IDLE Mode, the wake-up function of the related interrupt will be disabled.

Watchdog Timer

The Watchdog Timer is provided to prevent program malfunctions or sequences from jumping to unknown locations, due to certain uncontrollable external events such as electrical noise.

Watchdog Timer Clock Source

The Watchdog Timer clock source is provided by the internal clock, f_{LIRC} which is sourced from the LIRC oscillator. The LIRC internal oscillator has an approximate frequency of 32kHz and this specified internal clock period can vary with V_{DD}, temperature and process variations. The Watchdog Timer source clock is then subdivided by a ratio of 2^8 to 2^{18} to give longer time-outs, the actual value being chosen using the WS2~WS0 bits in the WDTC register.

Watchdog Timer Control Register

A single register, WDTC, controls the required time-out period as well as the Watchdog Timer enable/disable and MCU reset operations.

• **WDTC Register**

Bit	7	6	5	4	3	2	1	0
Name	WE4	WE3	WE2	WE1	WE0	WS2	WS1	WS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	0	1	1

Bit 7~3 **WE4~WE0**: WDT function control
10101: Disable
01010: Enable
Other values: Reset MCU
When these bits are changed to any other values due to environmental noise the microcontroller will be reset; this reset operation will be activated after a delay time, t_{SRESET}, and the WRF bit in the RSTFC register will be set high.

Bit 2~0 **WS2~WS0**: WDT time-out period selection
000: $2^8/f_{LIRC}$
001: $2^{10}/f_{LIRC}$
010: $2^{12}/f_{LIRC}$
011: $2^{14}/f_{LIRC}$
100: $2^{15}/f_{LIRC}$
101: $2^{16}/f_{LIRC}$
110: $2^{17}/f_{LIRC}$
111: $2^{18}/f_{LIRC}$
These three bits determine the division ratio of the Watchdog Timer source clock, which in turn determines the time-out period.

• **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

"x": unknown

Bit 7~3 Unimplemented, read as "0"

Bit 2 **LVRF**: LVR function reset flag
Refer to the Low Voltage Reset section.

Bit 1 **LRF**: LVRC register software reset flag
Refer to the Low Voltage Reset section.

Bit 0 **WRF**: WDTC register software reset flag
0: Not occurred
1: Occurred
This bit is set high by the WDTC register software reset and cleared to zero by the application program. Note that this bit can only be cleared to zero by the application program.

Watchdog Timer Operation

The Watchdog Timer operates by providing a device reset when its timer overflows. This means that in the application program and during normal operation the user has to strategically clear the Watchdog Timer before it overflows to prevent the Watchdog Timer from executing a reset. This is done using the clear watchdog instruction. If the program malfunctions for whatever reason, jumps to an unknown location, or enters an endless loop, the clear instruction will not be executed in the correct manner, in which case the Watchdog Timer will overflow and reset the device. There are five bits, WE4~WE0, in the WDTC register to offer the Watchdog Timer enable/disable control and the MCU reset. The WDT function will be enabled when the WE4~WE0 bits are set to a value of 01010B while the WDT function will be disabled if the WE4~WE0 bits are equal to 10101B. If the WE4~WE0 bits are set to any other values, other than 01010B and 10101B, it will reset the device after a delay time, t_{SRESET}. After power on these bits will have a value of 01010B.

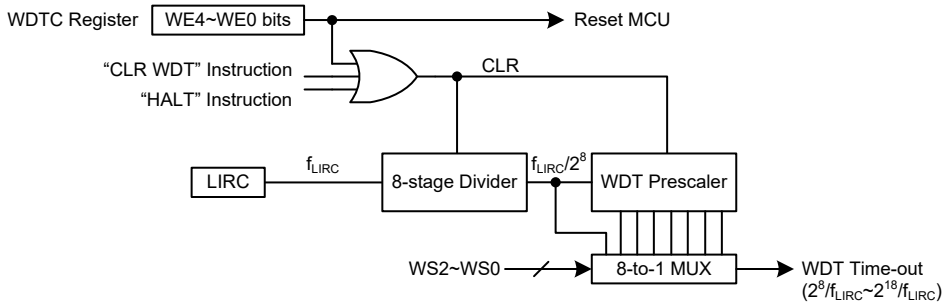
WE4~WE0 Bits	WDT Function
10101B	Disable
01010B	Enable
Any other value	Reset MCU

Watchdog Timer Enable/Disable Control

Under normal program operation, a Watchdog Timer time-out will initialise a device reset and set the status bit TO. However, if the system is in the SLEEP or IDLE Mode, when a Watchdog Timer time-out occurs, the TO bit in the STATUS register will be set and only the Program Counter and Stack Pointer will be reset. Three methods can be adopted to clear the contents of the Watchdog Timer. The first is a WDTC register software reset, which means a certain value except 01010B and 10101B written into the WE4~WE0 bits, the second is using the Watchdog Timer software clear instruction and the third is via a HALT instruction.

There is only one method of using software instruction to clear the Watchdog Timer. That is to use the single "CLR WDT" instruction to clear the WDT.

The maximum time-out period is when the 2^{18} division ratio is selected. As an example, with a 32kHz LIRC oscillator as its source clock, this will give a maximum watchdog period of around 8s for the 2^{18} division ratio, and a minimum time-out of 8ms for the 2^{8} division ration.



Watchdog Timer

Reset and Initialisation

A reset function is a fundamental part of any microcontroller ensuring that the device can be set to some predetermined condition irrespective of outside parameters. The most important reset condition is after power is first applied to the microcontroller. In this case, internal circuitry will ensure that the microcontroller, after a short delay, will be in a well-defined state and ready to execute the first program instruction. After this power-on reset, certain important internal registers will be set to defined states before the program commences. One of these registers is the Program Counter, which will be reset to zero forcing the microcontroller to begin program execution from the lowest Program Memory address.

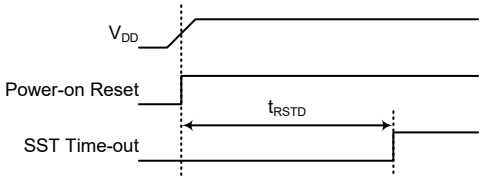
In addition to the power-on reset, another reset exists in the form of a Low Voltage Reset, LVR, where a full reset is implemented in situations where the power supply voltage falls below a certain threshold. Another type of reset is when the Watchdog Timer overflows and resets the microcontroller. All types of reset operations result in different register conditions being set.

Reset Functions

There are several ways in which a microcontroller reset can occur, through events occurring internally.

Power-on Reset

The most fundamental and unavoidable reset is the one that occurs after power is first applied to the microcontroller. As well as ensuring that the Program Memory begins execution from the first memory address, a power-on reset also ensures that certain other registers are preset to known conditions. All the I/O port and port control registers will power up in a high condition ensuring that all pins will be first set to inputs.

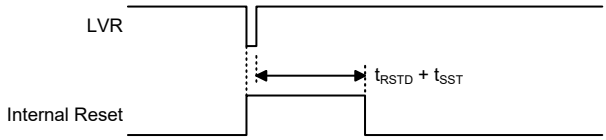


Power-On Reset Timing Chart

Low Voltage Reset – LVR

The microcontroller contains a low voltage reset circuit in order to monitor the supply voltage of the device and provides an MCU reset should the value fall below a certain predefined level. If the supply voltage of the device drops to within a range of 0.9V~V_{LVR} such as might occur when changing the battery, the LVR will automatically reset the device internally and the LVRF bit in the RSTFC

register will also be set to 1. For a valid LVR signal, a low supply voltage, i.e., a voltage in the range between 0.9V~V_{LVR} must exist for a time greater than that specified by t_{LVR} in the LVR/LVD Electrical Characteristics. If the duration of the low supply voltage state does not exceed this value, the LVR circuit will ignore the low supply voltage and will not perform a reset function. The LVR function will be always enabled except in the SLEEP or IDLE mode. The actual V_{LVR} value is selected by the LVS7~LVS0 bits. If the LVS7~LVS0 bits have any other undefined values, which may perhaps occur due to adverse environmental conditions such as noise, the LVR will reset the device after a delay time, t_{SRESET}. When this happens, the LRF bit in the RSTFC register will be set to 1. Note that the LVR function will be automatically disabled when the device enters the SLEEP/IDLE mode.



Low Voltage Reset Timing Chart

• **LVRC Register**

Bit	7	6	5	4	3	2	1	0
Name	LVS7	LVS6	LVS5	LVS4	LVS3	LVS2	LVS1	LVS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	1	0	1

Bit 7~0 **LVS7~LVS0**: LVR voltage selection
01010101: 2.1V
00110011: 2.55V
10011001: 3.15V
10101010: 3.8V
Other values: Generates a MCU reset – register is reset to POR value

When a low voltage condition as specified above occurs, an MCU reset will be generated. The reset operation will be activated after the low voltage condition keeps for greater than a t_{LVR} time. In this situation the register contents will remain the same after such a reset occurs.

Any register value, other than the four defined register values above, will also result in the generation of an MCU reset. The reset operation will be activated after a delay time, t_{SRESET}. However in this situation the register contents will be reset to the POR value.

• **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

"x": unknown

Bit 7~3 Unimplemented, read as "0"

Bit 2 **LVRF**: LVR function reset flag
0: Not occurred
1: Occurred

This bit is set to 1 when a specific low voltage reset condition occurs. Note that this bit can only be cleared to 0 by the application program.

Bit 1 **LRF**: LVRC register software reset flag
0: Not occurred
1: Occurred
This bit is set to 1 if the LVRC register contains any undefined values. This in effect acts like a software-reset function. Note that this bit can only be cleared to 0 by the application program.

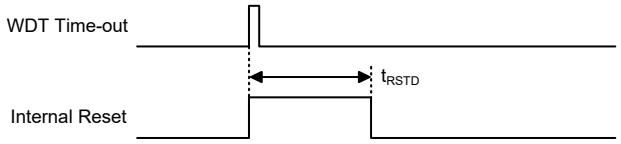
Bit 0 **WRF**: WDTC register software reset flag
Refer to the Watchdog Timer Control Register section.

In Application Programming Reset

The device contains an IAP function, therefore an IAP reset exists to reset the whole chip, which is caused by writing data 55H to the FC1 register.

Watchdog Time-out Reset during Normal Operation

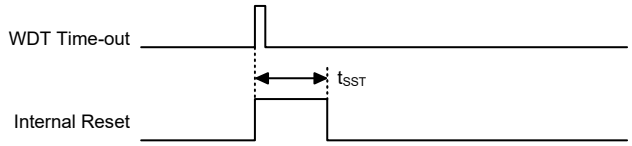
When the Watchdog Time-out Reset during normal operation in the FAST or SLOW mode occurs, the Watchdog time-out flag TO will be set to "1".



WDT Time-out Reset during Normal Operation Timing Chart

Watchdog Time-out Reset during SLEEP or IDLE Mode

The Watchdog time-out Reset during SLEEP or IDLE Mode is a little different from other kinds of reset. Most of the conditions remain unchanged except that the Program Counter and the Stack Pointer will be cleared to "0" and the TO flag will be set to "1". Refer to the System Start Up Time Characteristics for t_{SST} details.



WDT Time-out Reset during SLEEP or IDLE Mode Timing Chart

Reset Initial Conditions

The different types of reset described affect the reset flags in different ways. These flags, known as PDF and TO are located in the status register and are controlled by various microcontroller operations, such as the SLEEP or IDLE Mode function or Watchdog Timer. The reset flags are shown in the table:

TO	PDF	Reset Conditions
0	0	Power-on reset
u	u	LVR reset during FAST or SLOW Mode operation
1	u	WDT time-out reset during FAST or SLOW Mode operation
1	1	WDT time-out reset during IDLE or SLEEP Mode operation

"u" stands for unchanged

The following table indicates the way in which the various components of the microcontroller are affected after a power-on reset occurs.

Item	Condition after Reset
Program Counter	Reset to zero
Interrupts	All interrupts will be disabled
WDT, Time Bases	Cleared after reset, WDT begins counting
Timer Modules	Timer Modules will be turned off
Input/Output Ports	I/O ports will be set as inputs
Stack Pointer	Stack Pointer will point to the top of the stack

The different kinds of resets all affect the internal registers of the microcontroller in different ways. To ensure reliable continuation of normal program execution after a reset occurs, it is important to know what condition the microcontroller is in after a particular reset occurs. The following table describes how each type of reset affects the microcontroller internal registers. Note that where more than one package type exists the table will reflect the situation for the larger package type.

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
IAR0	0000 0000	0000 0000	uuuu uuuu
MP0	0000 0000	0000 0000	uuuu uuuu
IAR1	0000 0000	0000 0000	uuuu uuuu
MP1L	0000 0000	0000 0000	uuuu uuuu
MP1H	0000 0000	0000 0000	uuuu uuuu
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBLH	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBHP	---- xxxx	---- uuuu	---- uuuu
STATUS	xx00 xxxx	uu1u uuuu	uu11 uuuu
IAR2	0000 0000	0000 0000	uuuu uuuu
MP2L	0000 0000	0000 0000	uuuu uuuu
MP2H	0000 0000	0000 0000	uuuu uuuu
RSTFC	---- -x00	---- -uuu	---- -uuu
PB	-111 1111	-111 1111	-uuu uuuu
PBC	-111 1111	-111 1111	-uuu uuuu
PBPU	-000 0000	-000 0000	-uuu uuuu
PBS0	0000 0000	0000 0000	uuuu uuuu
PA	1111 1111	1111 1111	uuuu uuuu
PAC	1111 1111	1111 1111	uuuu uuuu
PAPU	0000 0000	0000 0000	uuu uuuu
PAWU	0000 0000	0000 0000	uuu uuuu
PAS0	0000 0000	0000 0000	uuu uuuu
PAS1	0000 0000	0000 0000	uuu uuuu
SCC	000- --00	000- --00	uuu- --uu
HIRCC	---- --01	---- --01	---- --uu
SADC0	0000 0000	0000 0000	uuuu uuuu
SADC1	0000 0000	0000 0000	uuuu uuuu
SADOL	xxxx ----	xxxx ----	uuuu ---- (ADRFS=0) uuuu uuuu (ADRFS=1)

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
SADOH	xxxx xxxx	xxxx xxxx	uuuu uuuu (ADRFS=0)
			---- uuuu (ADRFS=1)
INTEG	---- 0000	---- 0000	---- uuuu
LVRC	0101 0101	0101 0101	uuuu uuuu
LVDC	--00 0000	--00 0000	--uu uuuu
OCPC0	0000 0--0	0000 0--0	uuuu u--u
OCPC1	--00 0000	--00 0000	--uu uuuu
OCPDA	0000 0000	0000 0000	uuuu uuuu
OCPOCAL	0010 0000	0010 0000	uuuu uuuu
OCPCCAL	0001 0000	0001 0000	uuuu uuuu
IICC0	---- 000-	---- 000-	---- uuu-
IICC1	1000 0001	1000 0001	uuuu uuuu
IICD	xxxx xxxx	xxxx xxxx	uuuu uuuu
IICA	0000 000-	0000 000-	uuuu uuu-
IICTOC	0000 0000	0000 0000	uuuu uuuu
INTC0	-000 0000	-000 0000	-uuu uuuu
INTC1	0000 0000	0000 0000	uuuu uuuu
INTC2	0000 0000	0000 0000	uuuu uuuu
MFI0	--00 --00	--00 --00	--uu --uu
MFI1	--00 --00	--00 --00	--uu --uu
PSCR	---- --00	---- --00	---- --uu
TB0C	0--- -000	0--- -000	u--- -uuu
TB1C	0--- -000	0--- -000	u--- -uuu
WDTC	0101 0011	0101 0011	uuuu uuuu
PTM0C0	0000 0---	0000 0---	uuuu u---
PTM0C1	0000 0000	0000 0000	uuuu uuuu
PTM0DL	0000 0000	0000 0000	uuuu uuuu
PTM0DH	---- --00	---- --00	---- --uu
PTM0AL	0000 0000	0000 0000	uuuu uuuu
PTM0AH	---- --00	---- --00	---- --uu
PTM0RPL	0000 0000	0000 0000	uuuu uuuu
PTM0RPH	---- --00	---- --00	---- --uu
IECC	0000 0000	0000 0000	uuuu uuuu
SLEDC	0000 0000	0000 0000	uuuu uuuu
EEA	---0 0000	---0 0000	---u uuuu
EED	0000 0000	0000 0000	uuuu uuuu
PTM1C0	0000 0---	0000 0---	uuuu u---
PTM1C1	0000 0000	0000 0000	uuuu uuuu
PTM1DL	0000 0000	0000 0000	uuuu uuuu
PTM1DH	---- --00	---- --00	---- --uu
PTM1AL	0000 0000	0000 0000	uuuu uuuu
PTM1AH	---- --00	---- --00	---- --uu
PTM1RPL	0000 0000	0000 0000	uuuu uuuu
PTM1RPH	---- --00	---- --00	---- --uu
HVIOC	0000 0000	0000 0000	uuuu uuuu
HVIOPC	0x00 0x00	0x00 0x00	uuuu uuuu

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
STKPTR	0000 0000	0000 0000	uuuu uuuu
FC0	0000 0000	0000 0000	uuuu uuuu
FC1	0000 0000	0000 0000	uuuu uuuu
FC2	---- ---0	---- ---0	---- ---u
FARL	0000 0000	0000 0000	uuuu uuuu
FARH	---- 0000	---- 0000	---- uuuu
FD0L	0000 0000	0000 0000	uuuu uuuu
FD0H	0000 0000	0000 0000	uuuu uuuu
FD1L	0000 0000	0000 0000	uuuu uuuu
FD1H	0000 0000	0000 0000	uuuu uuuu
FD2L	0000 0000	0000 0000	uuuu uuuu
FD2H	0000 0000	0000 0000	uuuu uuuu
FD3L	0000 0000	0000 0000	uuuu uuuu
FD3H	0000 0000	0000 0000	uuuu uuuu
CRCCR	---- ---0	---- ---0	---- ---u
CRCIN	0000 0000	0000 0000	uuuu uuuu
CRCDL	0000 0000	0000 0000	uuuu uuuu
CRCDH	0000 0000	0000 0000	uuuu uuuu
EEC	---- 0000	---- 0000	---- uuuu

Note: “u” stands for unchanged
“x” stands for unknown
“-” stands for unimplemented

Input/Output Ports

Holtek microcontrollers offer considerable flexibility on their I/O ports. With the input or output designation of every pin fully under user program control, pull-high selections for all ports and wake-up selections on certain pins, the user is provided with an I/O structure to meet the needs of a wide range of application possibilities.

This device provides bidirectional input/output lines labeled with port names PA~PB. These I/O ports are mapped to the RAM Data Memory with specific addresses as shown in the Special Purpose Data Memory table. All of these I/O ports can be used for input and output operations. For input operation, these ports are non-latching, which means the inputs must be ready at the T2 rising edge of instruction “MOV A, [m]”, where “m” denotes the port address. For output operation, all the data is latched and remains unchanged until the output latch is rewritten.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PA	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
PAC	PAC7	PAC6	PAC5	PAC4	PAC3	PAC2	PAC1	PAC0
PAPU	PAPU7	PAPU6	PAPU5	PAPU4	PAPU3	PAPU2	PAPU1	PAPU0
PAWU	PAWU7	PAWU6	PAWU5	PAWU4	PAWU3	PAWU2	PAWU1	PAWU0
PB	—	PB6	PB5	PB4	PB3	PB2	PB1	PB0
PBC	—	PBC6	PBC5	PBC4	PBC3	PBC2	PBC1	PBC0
PBPU	—	PBPU6	PBPU5	PBPU4	PBPU3	PBPU2	PBPU1	PBPU0

“—”: Unimplemented, read as “0”

I/O Logic Function Register List

Pull-high Resistors

Many product applications require pull-high resistors for their switch inputs usually requiring the use of an external resistor. To eliminate the need for these external resistors, all I/O pins, when configured as a digital input have the capability of being connected to an internal pull-high resistor. These pull-high resistors are selected using the relevant pull-high control registers and are implemented using weak PMOS transistors.

Note that the pull-high resistor can be controlled by the relevant pull-high control register only when the pin-shared functional pin is selected as a digital input or NMOS output. Otherwise, the pull-high resistors cannot be enabled.

• **PxPU Register**

Bit	7	6	5	4	3	2	1	0
Name	PxPU7	PxPU6	PxPU5	PxPU4	PxPU3	PxPU2	PxPU1	PxPU0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

PxPUn: I/O Port x pin pull-high function control
0: Disable
1: Enable

The PxPUn bit is used to control the pin pull-high function. Here the "x" is the Port name which can be A or B. However, the actual available bits for each I/O Port may be different.

Port A Wake-up

The HALT instruction forces the microcontroller into the SLEEP or IDLE Mode which preserves power, a feature that is important for battery and other low-power applications. Various methods exist to wake up the microcontroller, one of which is to change the logic condition on one of the Port A pins from high to low. This function is especially suitable for applications that can be woken up via external switches. Each pin on Port A can be selected individually to have this wake-up feature using the PAWU register.

Note that the wake-up function can be controlled by the wake-up control registers only when the pin is selected as a general purpose input and the MCU enters the IDLE or SLEEP mode.

• **PAWU Register**

Bit	7	6	5	4	3	2	1	0
Name	PAWU7	PAWU6	PAWU5	PAWU4	PAWU3	PAWU2	PAWU1	PAWU0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **PAWU7~PAWU0**: PA7~PA0 pin wake-up function control
0: Disable
1: Enable

I/O Port Control Registers

Each I/O Port has its own control register to control the input/output configuration. With this control register, each CMOS output or input can be reconfigured dynamically under software control. Each pin of the I/O ports is directly mapped to a bit in its associated port control register. For the I/O pin to function as an input, the corresponding bit of the control register must be written as a "1". This will then allow the logic state of the input pin to be directly read by instructions. When the corresponding bit of the control register is written as a "0", the I/O pin will be set as a CMOS output. If the pin is currently set as an output, instructions can still be used to read the output register. However, it should be noted that the program will in fact only read the status of the output data latch and not the actual logic status of the output pin.

• **PxC Register**

Bit	7	6	5	4	3	2	1	0
Name	PxC7	PxC6	PxC5	PxC4	PxC3	PxC2	PxC1	PxC0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	1	1	1	1	1	1	1	1

PxCn: I/O Port x pin type selection
0: Output
1: Input
The PxCn bit is used to control the pin type selection. Here the "x" is the Port name which can be A or B. However, the actual available bits for each I/O Port may be different.

I/O Port Source Current Selection

The device supports different output source current driving capability for PA~PB ports. With the selection register, SLEDC, specific I/O port can support four levels of the source current driving capability. These source current selection bits are available only when the corresponding pin is configured as a CMOS output. Otherwise, these select bits have no effect. Users should refer to the Input/Output Characteristics section to select the desired output source current for different applications.

• **SLEDC Register**

Bit	7	6	5	4	3	2	1	0
Name	SLEDC7	SLEDC6	SLEDC5	SLEDC4	SLEDC3	SLEDC2	SLEDC1	SLEDC0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **SLEDC7~SLEDC6**: PB6~PB4 source current selection
00: Source current = Level 0 (Min.)
01: Source current = Level 1
10: Source current = Level 2
11: Source current = Level 3 (Max.)

Bit 5~4 **SLEDC5~SLEDC4**: PB3~PB0 source current selection
00: Source current = Level 0 (Min.)
01: Source current = Level 1
10: Source current = Level 2
11: Source current = Level 3 (Max.)

Bit 3~2 **SLEDC3~SLEDC2**: PA7~PA4 source current selection
00: Source current = Level 0 (Min.)
01: Source current = Level 1
10: Source current = Level 2
11: Source current = Level 3 (Max.)

Bit 1~0 **SLEDC1~SLEDC0**: PA3~PA0 source current selection
00: Source current = Level 0 (Min.)
01: Source current = Level 1
10: Source current = Level 2
11: Source current = Level 3 (Max.)

Pin-shared Functions

The flexibility of the microcontroller range is greatly enhanced by the use of pins that have more than one function. Limited numbers of pins can force serious design constraints on designers but by supplying pins with multi-functions, many of these difficulties can be overcome. For these pins, the desired function of the multi-function I/O pins is selected by a series of registers via the application program control.

Pin-shared Function Selection Registers

The limited number of supplied pins in a package can impose restrictions on the amount of functions a certain device can contain. However by allowing the same pins to share several different functions and providing a means of function selection, a wide range of different functions can be incorporated into even relatively small package sizes. The device includes Port "x" Output Function Selection register "n", labeled as PxSn, which can select the desired functions of the multi-function pin-shared pins.

The most important point to note is to make sure that the desired pin-shared function is properly selected and also deselected. For most pin-shared functions, to select the desired pin-shared function, the pin-shared function should first be correctly selected using the corresponding pin-shared control register. After that the corresponding peripheral functional setting should be configured and then the peripheral function can be enabled. However, a special point must be noted for some digital input pins, such as INTn, PTCKn, etc, which share the same pin-shared control configuration with their corresponding general purpose I/O functions when setting the relevant pin-shared control bits. To select these pin functions, in addition to the necessary pin-shared control and peripheral functional setup aforementioned, they must also be set as an input by setting the corresponding bit in the I/O port control register. To correctly deselect the pin-shared function, the peripheral function should first be disabled and then the corresponding pin-shared function control register can be modified to select other pin-shared functions.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PAS0	PAS07	PAS06	PAS05	PAS04	PAS03	PAS02	PAS01	PAS00
PAS1	PAS17	PAS16	PAS15	PAS14	PAS13	PAS12	PAS11	PAS10
PBS0	PBS07	PBS06	PBS05	PBS04	PBS03	PBS02	PBS01	PBS00

Pin-shared Function Selection Register List

- **PAS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PAS07	PAS06	PAS05	PAS04	PAS03	PAS02	PAS01	PAS00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PAS07~PAS06**: PA3 pin-shared function selection
00: PA3
01: PA3
10: VREF
11: AN3

Bit 5~4 **PAS05~PAS04**: PA2 pin-shared function selection
00: PA2
01: PA2
10: PA2
11: AN2

Bit 3~2 **PAS03~PAS02**: PA1 pin-shared function selection
00: PA1/PTCK0
01: PTP0B
10: OCPI
11: AN1

Bit 1~0 **PAS01~PAS00**: PA0 pin-shared function selection
00: PA0
01: PTP0
10: PA0
11: AN0

• **PAS1 Register**

Bit	7	6	5	4	3	2	1	0
Name	PAS17	PAS16	PAS15	PAS14	PAS13	PAS12	PAS11	PAS10
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PAS17~PAS16**: PA7 pin-shared function selection
00: PA7
01: PA7
10: PA7
11: AN7

Bit 5~4 **PAS15~PAS14**: PA6 pin-shared function selection
00: PA6/PTCK1
01: PA6/PTCK1
10: PA6/PTCK1
11: AN6

Bit 3~2 **PAS13~PAS12**: PA5 pin-shared function selection
00: PA5
01: PA5
10: PA5
11: AN5

Bit 1~0 **PAS11~PAS10**: PA4 pin-shared function selection
00: PA4/INT0
01: PA4/INT0
10: PA4/INT0
11: AN4

• **PBS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PBS07	PBS06	PBS05	PBS04	PBS03	PBS02	PBS01	PBS00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PBS07~PBS06**: PB3 pin-shared function selection
00: PB3
01: SCL
10: PB3
11: PB3

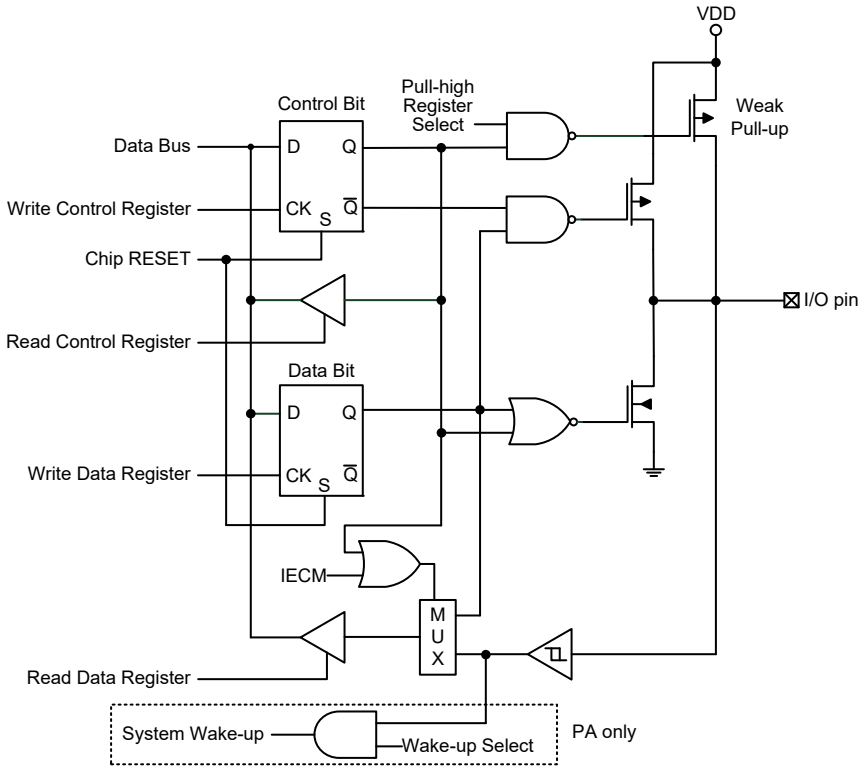
Bit 5~4 **PBS05~PBS04**: PB2 pin-shared function selection
00: PB2
01: SDA
10: PB2
11: PB2

Bit 3~2 **PBS03~PBS02**: PB1 pin-shared function selection
00: PB1
01: PTP1B
10: PB1
11: PB1

Bit 1~0 **PBS01~PBS00**: PB0 pin-shared function selection
00: PB0/INT1
01: PTP1
10: PB0/INT1
11: PB0/INT1

I/O Pin Structures

The accompanying diagram illustrates the internal structure of the I/O logic function. As the exact logical construction of the I/O pin will differ from this drawing, it is supplied as a guide only to assist with the functional understanding of the I/O logic function. The wide range of pin-shared structures does not permit all types to be shown.



Logic Function Input/Output Structure

READ PORT Function

The READ PORT function is used to manage the reading of the output data from the data latch or I/O pin, which is specially designed for the IEC60730 self-diagnostic test on the I/O function and A/D paths. There is a register, IECC, which is used to control the READ PORT function. If the READ PORT function is disabled, the pin function will operate as the selected pin-shared function. When a specific data pattern, "11001010", is written into the IECC register, the internal signal named IECM will be set high to enable the READ PORT function. If the READ PORT function is enabled, the value on the corresponding pins will be passed to the accumulator ACC when the read port instruction "mov acc, Px" is executed where the "x" stands for the corresponding I/O port name.

- **IECC Register**

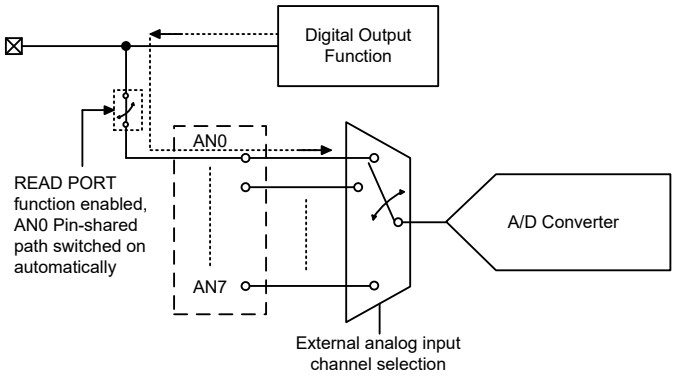
Bit	7	6	5	4	3	2	1	0
Name	IECS7	IECS6	IECS5	IECS4	IECS3	IECS2	IECS1	IECS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **IECS7~IECS0**: READ PORT function enable control bit 7 ~ bit 0
11001010: IECM=1 – READ PORT function is enabled
Others: IECM=0 – READ PORT function is disabled

READ PORT Function	Disabled		Enabled	
Port Control Register Bit – PxC.n	1	0	1	0
I/O Function	Pin value	Data latch value	Pin value	
Digital Input Function				
Digital Output Function (except SDA/SCL of I²C)	0			
I²C: SDA, SCL	Pin value			
Analog Function	0			

Note: The value on the above table is the content of the ACC register after "mov a, Px" instruction is executed where "x" means the relevant port name.

The additional function of the READ PORT mode is to check the A/D path. When the READ PORT function is disabled, the A/D path from the external pin to the internal analog input will be switched off if the A/D input pin function is not selected by the corresponding selection bits. For the MCU with A/D converter channels, such as A/D AN7~AN0, the desired A/D channel can be switched on by properly configuring the external analog input channel selection bits in the A/D Control Register together with the corresponding analog input pin function is selected. However, the additional function of the READ PORT mode is to force the A/D path to be switched on. For example, when the AN0 is selected as the analog input channel as the READ PORT function is enabled, the AN0 analog input path will be switched on even if the AN0 analog input pin function is not selected. In this way, the AN0 analog input path can be examined by internally connecting the digital output on this shared pin with the AN0 analog input pin switch and then converting the corresponding digital data without any external analog input voltage connected.



A/D Channel Input Path Internally Connection

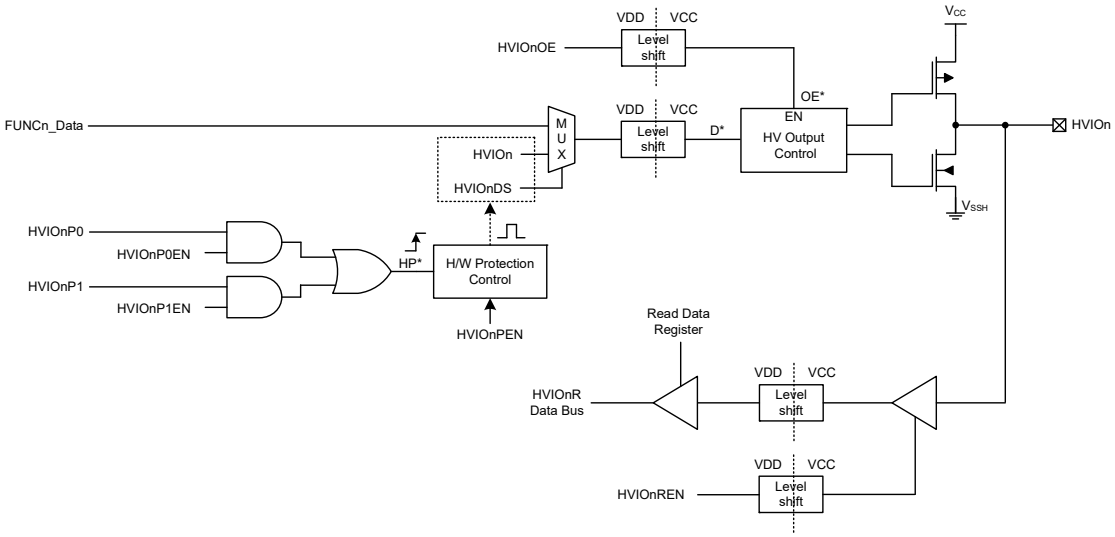
Programming Considerations

Within the user program, one of the things first to consider is port initialisation. After a reset, all of the I/O data and port control registers will be set high. This means that all I/O pins will be defaulted to an input state, the level of which depends on the other connected circuitry and whether pull-high selections have been chosen. If the port control registers are then programmed to set some pins as outputs, these output pins will have an initial high output value unless the associated port data registers are first programmed. Selecting which pins are inputs and which are outputs can be achieved byte-wide by loading the correct values into the appropriate port control register or by programming individual bits in the port control register using the "SET [m].i" and "CLR [m].i" instructions. Note that when using these bit control instructions, a read-modify-write operation takes place. The microcontroller must first read in the data on the entire port, modify it to the required new bit values and then rewrite this data back to the output ports.

Port A has the additional capability of providing wake-up functions. When the device is in the SLEEP or IDLE Mode, various methods are available to wake the device up. One of these is a high to low transition of any of the Port A pins. Single or multiple pins on Port A can be set to have this function.

High Voltage Input/Output Ports

The device provides two high voltage input/output ports, known as HVIO0 and HVIO1. These high voltage ports can be used to drive the external power MOS.



High Voltage Input/Output Block Diagram (n=0~1)

Note: 1. "*" is the circuit node name and not the Special Function Register bit.

2. FUNCn_Data is sourced from PTP0 for n=0 and from PTP1 for n=1.
   HVIOnP0 is sourced from OCPO for n=0~1.
   HVIOnP1 is sourced from INT0 for n=0 and from INT1 for n=1.
3. The HVIOn Truth Table is shown below:

OE	D	HVIOn
0	0	Floating
0	1	
1	0	V_{SS}
1	1	V_{CC}

Functional Description

The high voltage output on the HVIOn pin is used to directly drive the external power MOS and is controlled by the HVIOn bit high/low or FUNCn_Data output, which can be selected by the HVIOnDS bit.

The HVIOn pin read function is controlled by the HVIOnREN bit and the pin status can be read from the HVIOnR bit if the read function has been enabled.

Protection Mechanism

There is a protection mechanism provided for high voltage output. The control signal HP comes from HVIOnP0 or HVIOnP1, the trigger function of which are controlled by the HVIOnP0EN and HVIOnP1EN bits respectively.

- If HVIOnPEN=0, the HVIOnOE bit is used to determine whether the HVIOn pin is floating or normally output (HVIOn bit or FUNCn_Data).

- If HVIOnPEN=1, when the control signal HP trigger (from low to high) occurs, the HVIOn and HVIOnDS bits will be forced to zero by the hardware to implement the purposes as follows.
  - When OE=1, the HVIOn pin output status is low.
  - When OE=0, the HVIOn pin output status is floating
- Where the OE value is decided by the HVIOnOE bit.
- Then the subsequent action of the HVIOC register is determined by the software.
- If HVIOnPEN=1, when the control signal HP trigger does not occur, the HVIOn and HVIOnDS bits will not be affected.

Control Registers

The overall operation of high voltage input/output ports is controlled using two registers.

Register Name	Bit							
	7	6	5	4	3	2	1	0
HVIOC	HVIO1PEN	HVIO1OE	HVIO1DS	HVIO1	HVIO0PEN	HVIO0OE	HVIO0DS	HVIO0
HVIOPC	HVIO1REN	HVIO1R	HVIO1P1EN	HVIO1P0EN	HVIO0REN	HVIO0R	HVIO0P1EN	HVIO0P0EN

High Voltage Input/Output Control Register List

• HVIOC Register

Bit	7	6	5	4	3	2	1	0
Name	HVIO1PEN	HVIO1OE	HVIO1DS	HVIO1	HVIO0PEN	HVIO0OE	HVIO0DS	HVIO0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **HVIO1PEN**: HVIO1 pin hardware protection control
0: Disable
1: Enable

Bit 6 **HVIO1OE**: HVIO1 pin output control
0: Output disable
1: Output enable

Bit 5 **HVIO1DS**: HVIO1 pin output data selection
0: Output decided by the HVIO1 bit
1: Output decided by FUNC1_Data

Bit 4 **HVIO1**: HVIO1 pin output control
0: Output low
1: Output high

Bit 3 **HVIO0PEN**: HVIO0 pin hardware protection control
0: Disable
1: Enable

Bit 2 **HVIO0OE**: HVIO0 pin output control
0: Output disable
1: Output enable

Bit 1 **HVIO0DS**: HVIO0 pin output data selection
0: Output decided by HVIO0 bit
1: Output decided by FUNC0_Data

Bit 0 **HVIO0**: HVIO0 pin output control
0: Output low
1: Output high

• **HVIOPC Register**

Bit	7	6	5	4	3	2	1	0
Name	HVIO1REN	HVIO1R	HVIO1P1EN	HVIO1P0EN	HVIO0REN	HVIO0R	HVIO0P1EN	HVIO0P0EN
R/W	R/W	R	R/W	R/W	R/W	R	R/W	R/W
POR	0	x	0	0	0	x	0	0

"x": unknown

Bit 7 **HVIO1REN**: HVIO1 pin read control
0: Disable
1: Enable

Bit 6 **HVIO1R**: HVIO1 pin read data

Bit 5 **HVIO1P1EN**: HVIO1P1 hardware protection trigger control
0: Disable
1: Enable

Bit 4 **HVIO1P0EN**: HVIO1P0 hardware protection trigger control
0: Disable
1: Enable

Bit 3 **HVIO0REN**: HVIO0 pin read control
0: Disable
1: Enable

Bit 2 **HVIO0R**: HVIO0 pin read data

Bit 1 **HVIO0P1EN**: HVIO0P1 hardware protection trigger control
0: Disable
1: Enable

Bit 0 **HVIO0P0EN**: HVIO0P0 hardware protection trigger control
0: Disable
1: Enable

Timer Modules – TM

One of the most fundamental functions in any microcontroller device is the ability to control and measure time. To implement time related functions the device includes several Timer Modules, generally abbreviated to the name TM. The TMs are multi-purpose timing units and serve to provide operations such as Timer/Counter, Compare Match Output and Single Pulse Output as well as being the functional unit for the generation of PWM signals. Each of the TMs has two interrupts. The addition of input and output pins for each TM ensures that users are provided with timing units with a wide and flexible range of features.

Introduction

The device contains two Periodic Type TMs, namely PTMs. The main features of the PTMs are summarised in the accompanying table and the detailed operation regarding the PTMs will be described in its separate section.

TM Function	PTM
Timer/Counter	√
Compare Match Output	√
PWM Output	√
Single Pulse Output	√
PWM Alignment	Edge
PWM Adjustment Period & Duty	Duty or Period

TM Function Summary

TM Operation

The Periodic Type TMs offer a diverse range of functions, from simple timing operations to PWM signal generation. The key to understanding how the PTM operates is to see it in terms of a free running count-up counter whose value is then compared with the value of pre-programmed internal comparators. When the free running count-up counter has the same value as the pre-programmed comparator, known as a compare match situation, a PTM interrupt signal will be generated which can clear the counter and perhaps also change the condition of the PTM output pin. The internal PTM counter is driven by a user selectable clock source, which can be an internal clock or an external pin.

TM Clock Source

The clock source which drives the main counter in each PTM can originate from various sources. The selection of the required clock source is implemented using the PTnCK2~PTnCK0 bits in the PTMn control registers, where “n” stands for the specific PTM serial number. The clock source can be a ratio of the system clock, f_{SYS}, or the internal high clock, f_H, the f_{SUB} clock source or the external PTCKn pin. The PTCKn pin clock source is used to allow an external signal to drive the PTM as an external clock source for event counting.

TM Interrupts

Each Periodic Type TM has two internal interrupts, one for each of the internal comparator A or comparator P, which generates a PTM interrupt when a compare match condition occurs. When a PTM interrupt is generated, it can be used to clear the counter and also to change the state of the PTM output pin.

TM External Pins

Each of the TMs has one input pin with the label PTCKn. The PTMn input pin, PTCKn, is essentially a clock source for the PTMn and is selected using the PTnCK2~PTnCK0 bits in the

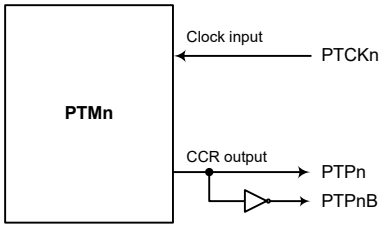
PTMnC0 register. This external PTMn input pin allows an external clock source to drive the internal PTM. The PTCKn input pin can be chosen to have either a rising or falling active edge. The PTCKn pin is also used as the external trigger input pin in single pulse output mode for the PTMn.

The PTMs each have two output pins with the label PTPn and PTPnB. When the PTM is in the Compare Match Output Mode, the PTPn pin can be controlled by the PTMn to switch to a high or low level or to toggle when a compare match situation occurs. The PTPnB pin outputs the inverted signal of the PTPn. The external PTPn and PTPnB output pins are also the pins where the PTMn generates the PWM output waveform.

As the PTM input and output pins are pin-shared with other functions, the PTM input and output functions must first be configured using the relevant pin-shared function selection bits. The details of the pin-shared function selection are described in the pin-shared function section.

PTM0		PTM1	
Input	Output	Input	Output
PTCK0	PTP0, PTP0B	PTCK1	PTP1, PTP1B

TM External Pins

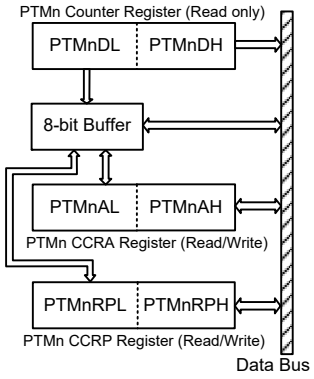


PTM Function Pin Block Diagram (n=0~1)

Programming Considerations

The PTMn Counter Registers and the Compare CCRA and CCRP registers, all have a low and high byte structure. The high bytes can be directly accessed, but as the low bytes can only be accessed via an internal 8-bit buffer, reading or writing to these register pairs must be carried out in a specific way. The important point to note is that data transfer to and from the 8-bit buffer and its related low byte only takes place when a write or read operation to its corresponding high byte is executed.

As the CCRA and CCRP registers are implemented in the way shown in the following diagram and accessing these register pairs is carried out in a specific way as described above, it is recommended to use the "MOV" instruction to access the CCRA and CCRP low byte registers, named PTMnAL and PTMnRPL, using the following access procedures. Accessing the CCRA or CCRP low byte registers without following these access procedures will result in unpredictable values.

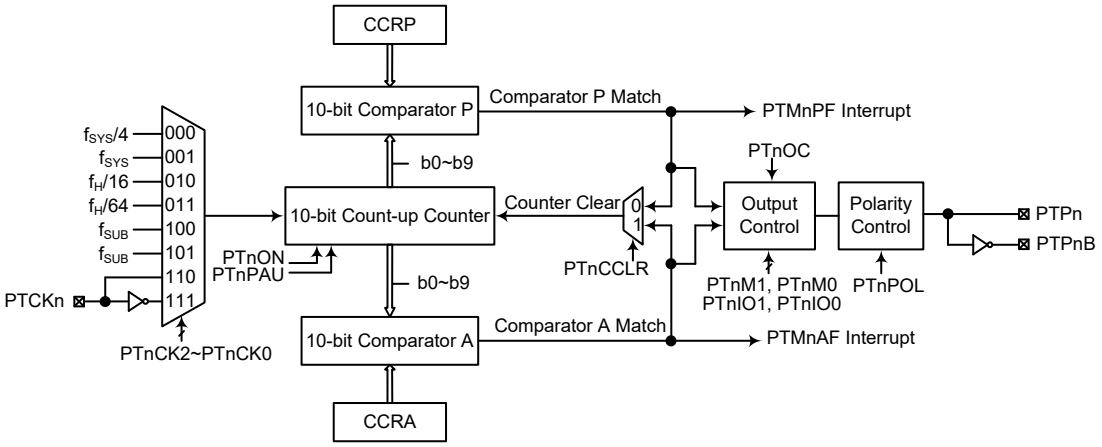


The following steps show the read and write procedures:

- Writing Data to CCRA or CCRP
  - Step 1. Write data to Low Byte PTMnAL or PTMnRPL
    – Note that here data is only written to the 8-bit buffer.
  - Step 2. Write data to High Byte PTMnAH or PTMnRPH
    – Here data is written directly to the high byte registers and simultaneously data is latched from the 8-bit buffer to the Low Byte registers.
- Reading Data from the Counter Registers, CCRA or CCRP
  - Step 1. Read data from the High Byte PTMnDH, PTMnAH or PTMnRPH
    – Here data is read directly from the High Byte registers and simultaneously data is latched from the Low Byte register into the 8-bit buffer.
  - Step 2. Read data from the Low Byte PTMnDL, PTMnAL or PTMnRPL
    – This step reads data from the 8-bit buffer.

Periodic Type TM – PTM

The Periodic Type TMs contain four operating modes, which are Compare Match Output, Timer/Event Counter, Single Pulse Output and PWM Output modes. The Periodic TMs can also be controlled with one external input pin and can drive two external output pins.



Note: 1. As the PTMn external pins are pin-shared with other functions, the relevant pin-shared control bits should be properly configured before using these pins. The PTCKn pin, if used, must also be set as an input by setting the corresponding bit in the port control register.
2. The PTPnB is the inverted signal of the PTPn.

10-bit Periodic Type TM Block Diagram (n=0~1)

Periodic Type TM Operation

The size of Periodic Type TM is 10-bit wide and its core is a 10-bit count-up counter which is driven by a user selectable internal or external clock source. There are also two internal comparators with the names, Comparator A and Comparator P. These comparators will compare the value in the counter with CCRP and CCRA registers. The CCRP and CCRA comparators are 10-bit wide whose value is respectively compared with all counter bits.

The only way of changing the value of the 10-bit counter using the application program is to clear the counter by changing the PTnON bit from low to high. The counter will also be cleared automatically by a counter overflow or a compare match with one of its associated comparators.

When these conditions occur, a PTMn interrupt signal will also usually be generated. The Periodic Type TM can operate in a number of different operational modes, can be driven by different clock sources including an input pin and can also control two output pins. All operating setup conditions are selected using relevant internal registers.

Periodic Type TM Register Description

Overall operation of the Periodic TM is controlled using a series of registers. A read only register pair exists to store the internal counter 10-bit value, while two read/write register pairs exist to store the internal 10-bit CCRA and CCRP values. The remaining two registers are control registers which set the different operating and control modes.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PTMnC0	PTnPAU	PTnCK2	PTnCK1	PTnCK0	PTnON	—	—	—
PTMnC1	PTnM1	PTnM0	PTnIO1	PTnIO0	PTnOC	PTnPOL	D1	PTnCCLR
PTMnDL	D7	D6	D5	D4	D3	D2	D1	D0
PTMnDH	—	—	—	—	—	—	D9	D8
PTMnAL	D7	D6	D5	D4	D3	D2	D1	D0
PTMnAH	—	—	—	—	—	—	D9	D8
PTMnRPL	D7	D6	D5	D4	D3	D2	D1	D0
PTMnRPH	—	—	—	—	—	—	D9	D8

10-bit Periodic TM Register List (n=0~1)

- **PTMnC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PTnPAU	PTnCK2	PTnCK1	PTnCK0	PTnON	—	—	—
R/W	R/W	R/W	R/W	R/W	R/W	—	—	—
POR	0	0	0	0	0	—	—	—

Bit 7 **PTnPAU**: PTMn counter pause control
0: Run
1: Pause
The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the PTMn will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

Bit 6~4 **PTnCK2~PTnCK0**: PTMn counter clock selection
000: $f_{SYS}/4$
001: f_{SYS}
010: $f_H/16$
011: $f_H/64$
100: f_{SUB}
101: f_{SUB}
110: PTCKn rising edge clock
111: PTCKn falling edge clock
These three bits are used to select the clock source for the PTMn. The external pin clock source can be chosen to be active on the rising or falling edge. The clock source f_{SYS} is the system clock, while f_H and f_{SUB} are other internal clocks, the details of which can be found in the Operating Modes and System Clocks section.

Bit 3 **PTnON**: PTMn counter on/off control
0: Off
1: On
This bit controls the overall on/off function of the PTMn. Setting the bit high enables the counter to run while clearing the bit disables the PTMn. Clearing this bit to zero will stop the counter from counting and turn off the PTMn which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again. If the PTMn is in the Compare Match Output Mode, PWM output Mode or Single Pulse Output Mode then the PTMn output pin will be reset to its initial condition, as specified by the PTnOC bit, when the PTnON bit changes from low to high.

Bit 2~0 Unimplemented, read as "0"

- **PTMnC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	PTnM1	PTnM0	PTnIO1	PTnIO0	PTnOC	PTnPOL	D1	PTnCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PTnM1~PTnM0**: PTMn operating mode selection
00: Compare Match Output Mode
01: Undefined
10: PWM Output Mode or Single Pulse Output Mode
11: Timer/Counter Mode
These bits set the required operating mode for the PTMn. To ensure reliable operation the PTMn should be switched off before any changes are made to the PTnM1 and PTnM0 bits. In the Timer/Counter Mode, the PTMn output pin state is undefined.

Bit 5~4 **PTnIO1~PTnIO0**: PTMn external pin function selection
Compare Match Output Mode
00: No change
01: Output low
10: Output high
11: Toggle output
PWM Output Mode/Single Pulse Output Mode
00: PWM output inactive state
01: PWM output active state
10: PWM output
11: Single Pulse Output
Timer/Counter Mode
Unused
These two bits are used to determine how the PTMn external pin changes state when a certain condition is reached. The function that these bits select depends upon in which mode the PTMn is running.
In the Compare Match Output Mode, the PTnIO1 and PTnIO0 bits determine how the PTMn output pin changes state when a compare match occurs from the Comparator A. The PTMn output pin can be set to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the bits are both zero, then no change will take place on the output. The initial value of the PTMn output pin should be set using the PTnOC bit in the PTMnC1 register. Note that the output level requested by the PTnIO1 and PTnIO0 bits must be different from the initial value setup using the PTnOC bit otherwise no change will occur on the PTMn output pin when a compare match occurs. After the PTMn output pin changes state, it can be reset to its initial level by changing the level of the PTnON bit from low to high.

In the PWM Output Mode, the PTnIO1 and PTnIO0 bits determine how the PTMn output pin changes state when a certain compare match condition occurs. The PTMn output function is modified by changing these two bits. It is necessary to only change the values of the PTnIO1 and PTnIO0 bits after the PTMn has been switched off. Unpredictable PWM outputs will occur if the PTnIO1 and PTnIO0 bits are changed when the PTMn is running.

Bit 3 **PTnOC**: PTMn PTPn output control

Compare Match Output Mode
0: Initial low
1: Initial high

PWM Output Mode/Single Pulse Output Mode
0: Active low
1: Active high

This is the output control bit for the PTPn output pin. Its operation depends upon whether PTMn is being used in the Compare Match Output Mode or in the PWM Output Mode/Single Pulse Output Mode. It has no effect if the PTMn is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the PTMn output pin before a compare match occurs. In the PWM Output Mode it determines if the PWM signal is active high or active low. In the Single Pulse Output Mode it determines the logic level of the PTMn output pin when the PTnON bit changes from low to high.

Bit 2 **PTnPOL**: PTMn PTPn output polarity control
0: Non-invert
1: Invert

This bit controls the polarity of the PTPn output pin. When the bit is set high the PTMn output pin will be inverted and not inverted when the bit is zero. It has no effect if the PTMn is in the Timer/Counter Mode.

Bit 1 **D1**: Reserved, must be fixed at "0"

Bit 0 **PTnCCLR**: PTMn counter clear condition selection
0: Comparator P match
1: Comparator A match

This bit is used to select the method which clears the counter. Remember that the Periodic TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the PTnCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The PTnCCLR bit is not used in the PWM Output or Single Pulse Output Mode.

- **PTMnDL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTMn Counter Low Byte Register bit 7 ~ bit 0
PTMn 10-bit Counter bit 7 ~ bit 0

• **PTMnDH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R	R
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTMn Counter High Byte Register bit 1 ~ bit 0
PTMn 10-bit Counter bit 9 ~ bit 8

• **PTMnAL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTMn CCRA Low Byte Register bit 7 ~ bit 0
PTMn 10-bit CCRA bit 7 ~ bit 0

• **PTMnAH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTMn CCRA High Byte Register bit 1 ~ bit 0
PTMn 10-bit CCRA bit 9 ~ bit 8

• **PTMnRPL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTMn CCRP Low Byte Register bit 7 ~ bit 0
PTMn 10-bit CCRP bit 7 ~ bit 0

• **PTMnRPH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTMn CCRP High Byte Register bit 1 ~ bit 0
PTMn 10-bit CCRP bit 9 ~ bit 8

Periodic Type TM Operation Modes

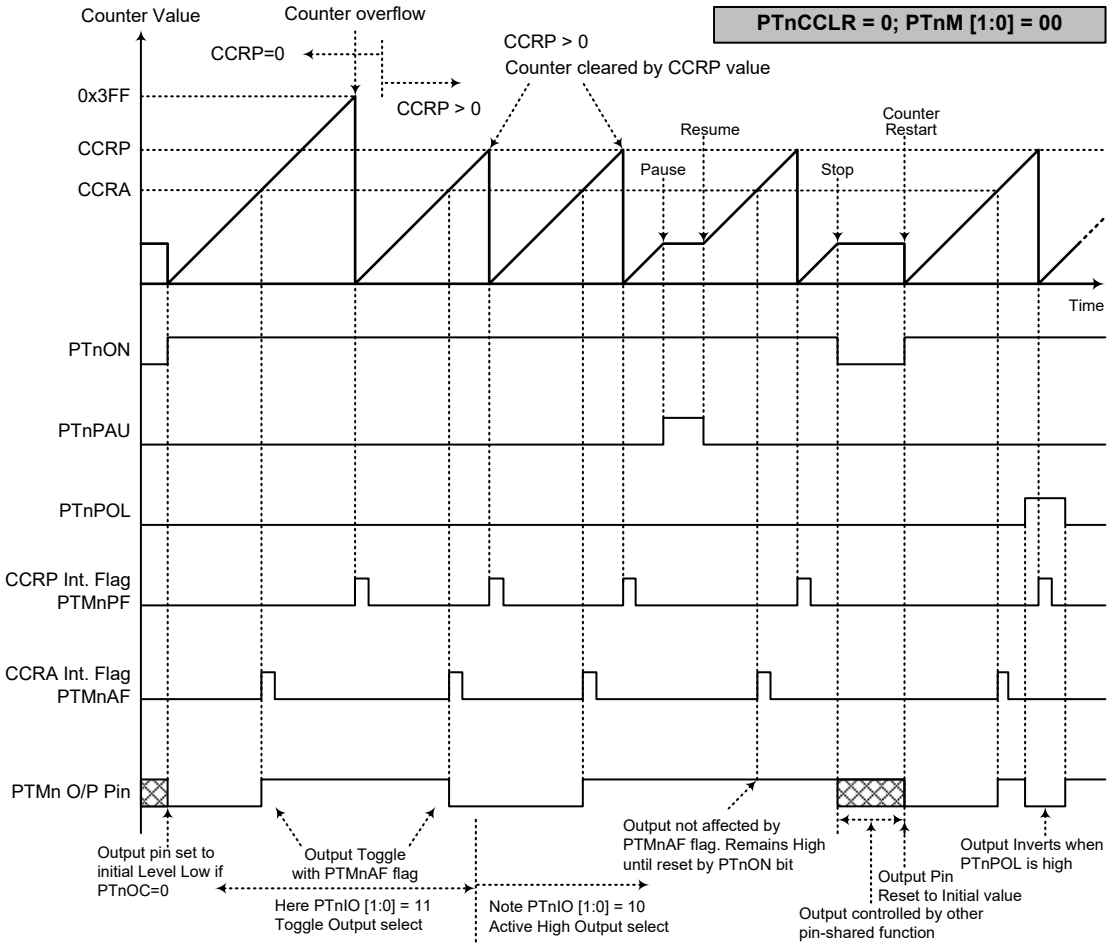
The Periodic Type TMs can operate in one of four operating modes, Compare Match Output Mode, PWM Output Mode, Single Pulse Output Mode or Timer/Counter Mode. The operating mode is selected using the PTnM1 and PTnM0 bits in the PTMnC1 register.

Compare Match Output Mode

To select this mode, bits PTnM1 and PTnM0 in the PTMnC1 register, should be set to "00" respectively. In this mode once the counter is enabled and running it can be cleared by three methods. These are a counter overflow, a compare match from Comparator A and a compare match from Comparator P. When the PTnCCLR bit is low, there are two ways in which the counter can be cleared. One is when a compare match from Comparator P, the other is when the CCRP bits are all zero which allows the counter to overflow. Here both PTMnAF and PTMnPF interrupt request flags for Comparator A and Comparator P respectively, will both be generated.

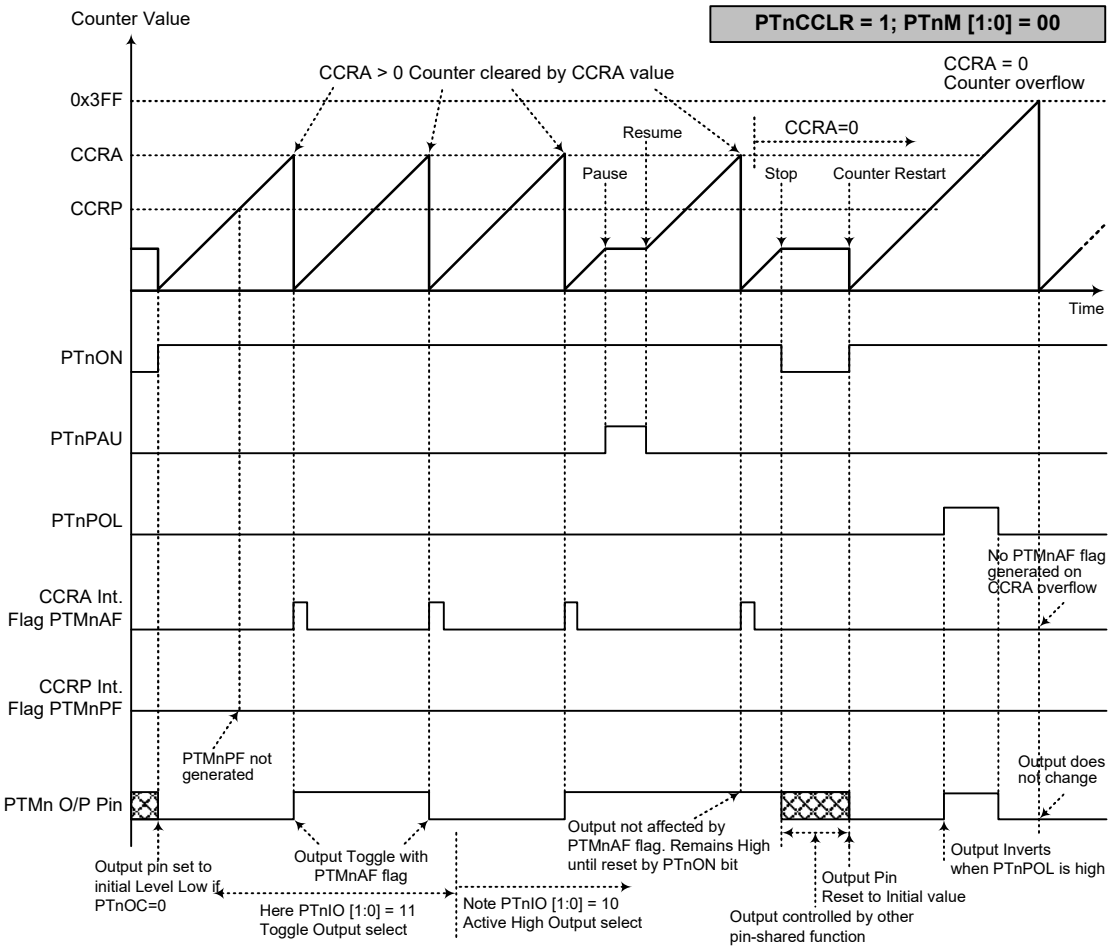
If the PTnCCLR bit in the PTMnC1 register is high then the counter will be cleared when a compare match occurs from Comparator A. However, here only the PTMnAF interrupt request flag will be generated even if the value of the CCRP bits is less than that of the CCRA registers. Therefore when PTnCCLR is high no PTMnPF interrupt request flag will be generated. In the Compare Match Output Mode, the CCRA cannot be cleared to zero. If the CCRA bits are all zero, the counter will overflow when it reaches its maximum 10-bit, 3FF Hex, value, however here the PTMnAF interrupt request flag will not be generated.

As the name of the mode suggests, after a comparison is made, the PTMn output pin will change state. The PTMn output pin condition however only changes state when a PTMnAF interrupt request flag is generated after a compare match occurs from Comparator A. The PTMnPF interrupt request flag, generated from a compare match occurs from Comparator P, will have no effect on the PTMn output pin. The way in which the PTMn output pin changes state are determined by the condition of the PTnIO1 and PTnIO0 bits in the PTMnC1 register. The PTMn output pin can be selected using the PTnIO1 and PTnIO0 bits to go high, to go low or to toggle from its present condition when a compare match occurs from Comparator A. The initial condition of the PTMn output pin, which is set after the PTnON bit changes from low to high, is set using the PTnOC bit. Note that if the PTnIO1 and PTnIO0 bits are zero then no pin change will take place.



Compare Match Output Mode – PTnCCLR=0 (n=0~1)

Note: 1. With PTnCCLR=0, a Comparator P match will clear the counter
2. The PTMn output pin is controlled only by the PTMnAF flag
3. The output pin is reset to its initial state by a PTnON bit rising edge



Compare Match Output Mode – PTnCCLR=1 (n=0~1)

Note: 1. With PTnCCLR=1, a Comparator A match will clear the counter
2. The PTM output pin is controlled only by the PTMnAF flag
3. The output pin is reset to its initial state by a PTnON bit rising edge
4. A PTMnPF flag is not generated when PTnCCLR=1

Timer/Counter Mode

To select this mode, bits PTnM1 and PTnM0 in the PTMnC1 register should be set to "11" respectively. The Timer/Counter Mode operates in an identical way to the Compare Match Output Mode generating the same interrupt flags. The exception is that in the Timer/Counter Mode the PTMn output pins are not used. Therefore the above description and Timing Diagrams for the Compare Match Output Mode can be used to understand its function. As the PTMn output pin is not used in this mode, the pin can be used as a normal I/O pin or other pin-shared functions.

PWM Output Mode

To select this mode, bits PTnM1 and PTnM0 in the PTMnC1 register should be set to "10" respectively and also the PTnIO1 and PTnIO0 bits should be set to "10" respectively. The PWM function within the PTMn is useful for applications which require functions such as motor control, heating control, illumination control, etc. By providing a signal of fixed frequency but of varying duty cycle on the PTMn output pin, a square wave AC waveform can be generated with varying equivalent DC RMS values.

As both the period and duty cycle of the PWM waveform can be controlled, the choice of generated waveform is extremely flexible. In the PWM Output Mode, the PTnCCLR bit has no effect as the PWM period. Both of the CCRP and CCRA registers are used to generate the PWM waveform, one register is used to clear the internal counter and thus control the PWM waveform frequency, while the other one is used to control the duty cycle. The PWM waveform frequency and duty cycle can therefore be controlled by the values in the CCRA and CCRP registers.

An interrupt flag, one for each of the CCRA and CCRP, will be generated when a compare match occurs from either Comparator A or Comparator P. The PTnOC bit in the PTMnC1 register is used to select the required polarity of the PWM waveform while the two PTnIO1 and PTnIO0 bits are used to enable the PWM output or to force the PTMn output pin to a fixed high or low level. The PTnPOL bit is used to reverse the polarity of the PWM output waveform.

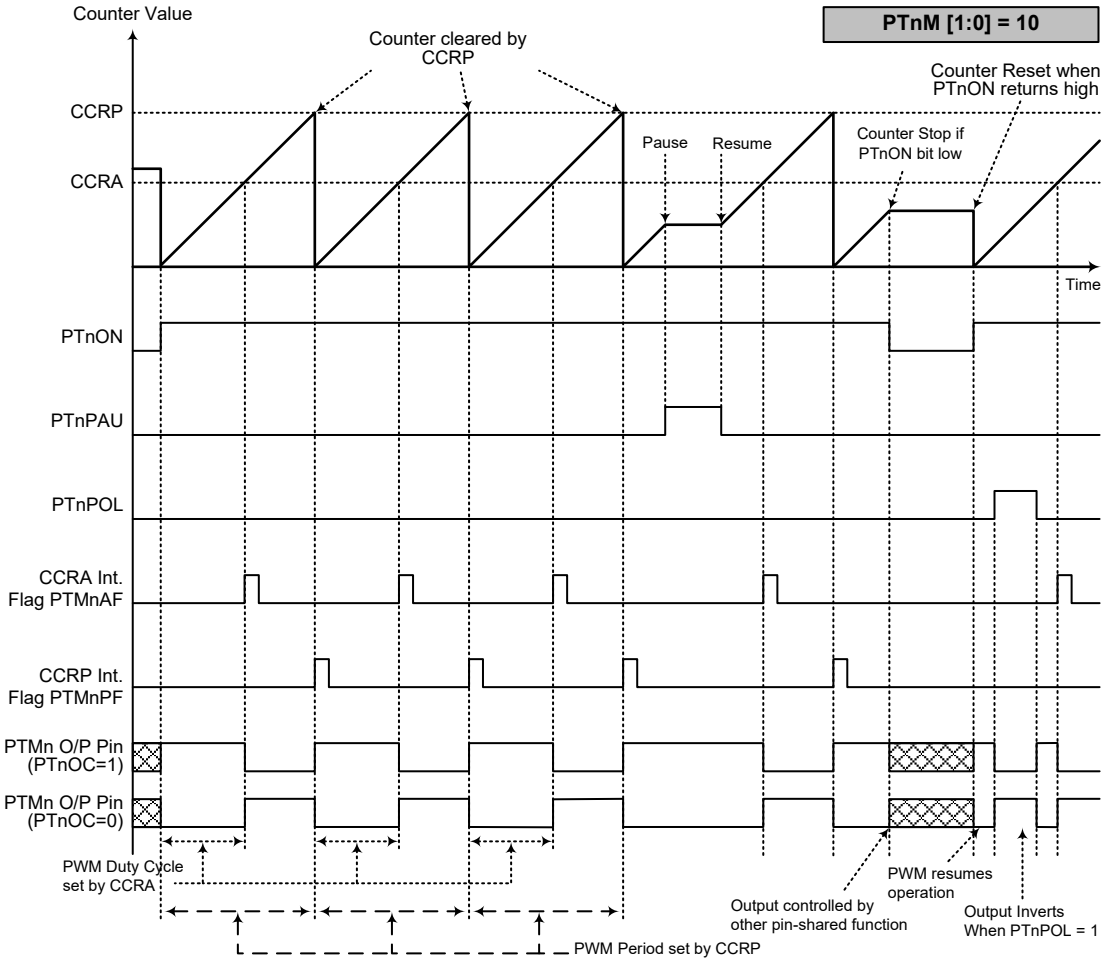
- **10-bit PTMn, PWM Output Mode, Edge-aligned Mode**

CCRP	1~1023	0
Period	1~1023	1024
Duty	CCRA	

If f_{SYS} = 8MHz, PTMn clock source select $f_{SYS}/4$, CCRP=512 and CCRA = 128,

The PTMn PWM output frequency = $(f_{SYS}/4)/512 = f_{SYS}/2048$ = 4kHz, duty = 128/512 = 25%.

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.



PWM Output Mode (n=0~1)

Note: 1. The counter is cleared by CCRP

2. A counter clear sets the PWM Period

3. The internal PWM function continues running even when PTnIO[1:0]=00 or 01

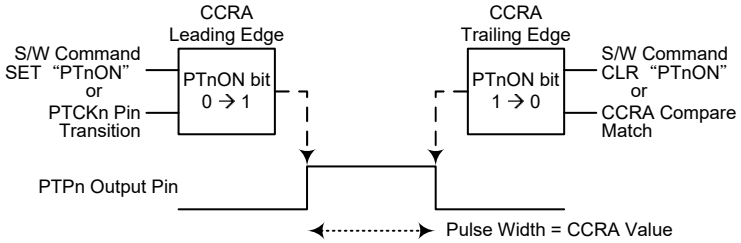
4. The PTnCCLR bit has no influence on PWM operation

Single Pulse Output Mode

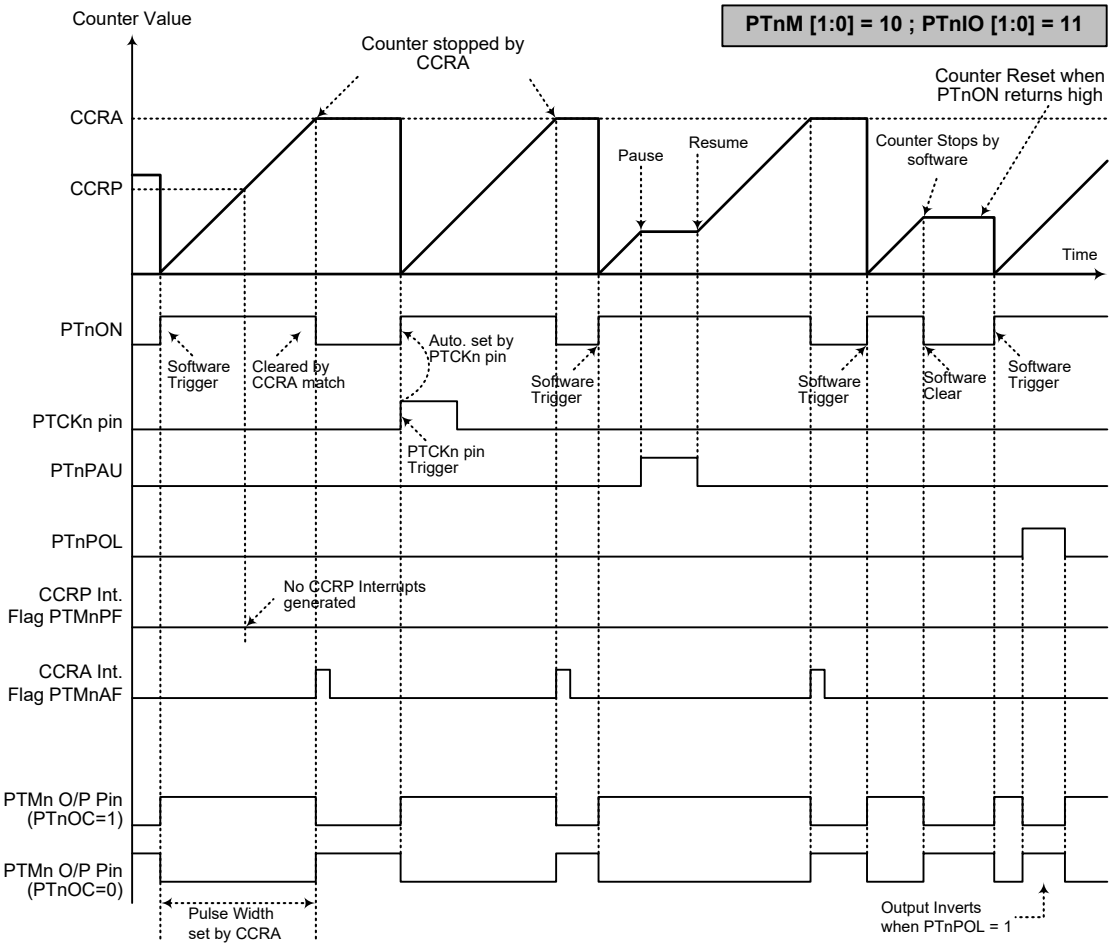
To select this mode, bits PTnM1 and PTnM0 in the PTMnC1 register should be set to "10" respectively and also the PTnIO1 and PTnIO0 bits should be set to "11" respectively. The Single Pulse Output Mode, as the name suggests, will generate a single shot pulse on the PTMn output pin.

The trigger for the pulse output leading edge is a low to high transition of the PTnON bit, which can be implemented using the application program. However in the Single Pulse Output Mode, the PTnON bit can also be made to automatically change from low to high using the external PTCKn pin, which will in turn initiate the Single Pulse output. When the PTnON bit transitions to a high level, the counter will start running and the pulse leading edge will be generated. The PTnON bit should remain high when the pulse is in its active state. The generated pulse trailing edge will be generated when the PTnON bit is cleared to zero, which can be implemented using the application program or when a compare match occurs from Comparator A.

However a compare match from Comparator A will also automatically clear the PTnON bit and thus generate the Single Pulse output trailing edge. In this way the CCRA value can be used to control the pulse width. A compare match from Comparator A will also generate a PTMn interrupt. The counter can only be reset back to zero when the PTnON bit changes from low to high when the counter restarts. In the Single Pulse Output Mode CCRP is not used. The PTnCCLR is not used in this mode.



Single Pulse Generation (n=0~1)



Single Pulse Output Mode (n=0~1)

Note: 1. Counter stopped by CCRA
2. CCRP is not used
3. The pulse triggered by the PTCKn pin or by setting the PTnON bit high
4. A PTCKn pin active edge will automatically set the PTnON bit high
5. In the Single Pulse Output Mode, PTnIO[1:0] must be set to “11” and cannot be changed

Analog to Digital Converter

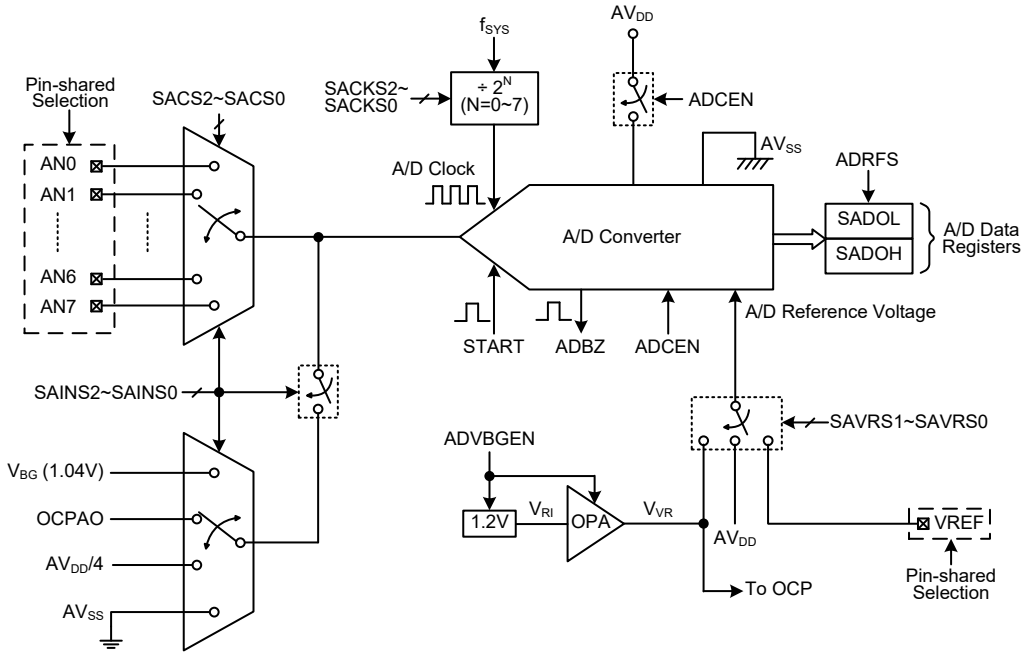
The need to interface to real world analog signals is a common requirement for many electronic systems. However, to properly process these signals by a microcontroller, they must first be converted into digital signals by A/D converters. By integrating the A/D conversion electronic circuitry into the microcontroller, the need for external components is reduced significantly with the corresponding follow-on benefits of lower costs and reduced component space requirements.

A/D Converter Overview

The device contains a multi-channel analog to digital converter which can directly interface to external analog signals, such as that from sensors or other control signals and convert these signals directly into a 12-bit digital value. It also can convert the internal signals, such as the OCP operational amplifier output OCPAO, Bandgap reference voltage V_{BG}, and A/D converter power divided by 4, into a 12-bit digital value. The external or internal analog signal to be converted is determined by the SAINS and SACS bit fields. More detailed information about the A/D input signal selection will be described in the "A/D converter Control Registers" and "A/D Converter Input Signals" section respectively.

External Input Channels	Internal Signals	A/D Signal Select Bits
8: AN0~AN7	4: V_{BG}, OCPAO, $AV_{DD}/4$, AV_{SS}	SAINS2~SAINS0, SACS2~SACS0

The accompanying block diagram shows the internal structure of the A/D converter together with its associated registers and control bits.



A/D Converter Structure

A/D Converter Register Description

Overall operation of the A/D converter is controlled using five registers. A read only register pair exists to store the A/D Converter data 12-bit value. The remaining two registers, SADC0 and SADC1, are control registers which set the operating conditions and control function of the A/D converter.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SADOL (ADRFS=0)	D3	D2	D1	D0	—	—	—	—
SADOL (ADRFS=1)	D7	D6	D5	D4	D3	D2	D1	D0
SADOH (ADRFS=0)	D11	D10	D9	D8	D7	D6	D5	D4
SADOH (ADRFS=1)	—	—	—	—	D11	D10	D9	D8
SADC0	START	ADBZ	ADCEN	ADRFS	ADVBGEN	SACS2	SACS1	SACS0
SADC1	SAINS2	SAINS1	SAINS0	SAVRS1	SAVRS0	SACKS2	SACKS1	SACKS0

A/D Converter Register List

A/D Converter Data Registers – SADOL, SADOH

As the device contains an internal 12-bit A/D converter, it requires two data registers to store the converted value. These are a high byte register, known as SADOH, and a low byte register, known as SADOL. After the conversion process takes place, these registers can be directly read by the microcontroller to obtain the digitised conversion value. As only 12 bits of the 16-bit register space is utilised, the format in which the data is stored is controlled by the ADRFS bit in the SADC0 register as shown in the accompanying table. D0~D11 are the A/D conversion result data bits. Any unused bits will be read as zero. The A/D data registers contents will be cleared if the A/D converter is disabled.

ADRFS	SADOH								SADOL							
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
0	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	0	0	0	0
1	0	0	0	0	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

A/D Converter Data Registers

A/D Converter Control Registers – SADC0, SADC1

To control the function and operation of the A/D converter, two control registers known as SADC0 and SADC1 are provided. These 8-bit registers define functions such as the selection of which analog signal is connected to the internal A/D converter, the digitised data format, the A/D clock source as well as controlling the start function and monitoring the A/D converter busy status. As the device contains only one actual analog to digital converter hardware circuit, each of the external and internal analog signals must be routed to the converter. The SACS2~SACS0 bits in the SADC0 register are used to determine which external channel input is selected to be converted. The SAINS2~SAINS0 bits in the SADC1 register are used to determine that the analog signal to be converted comes from the internal analog signal or external analog channel input.

The relevant pin-shared function selection bits determine which pins on I/O Ports are used as analog inputs for the A/D converter input and which pins are not to be used as the A/D converter input. When the pin is selected to be an A/D input, its original function whether it is an I/O or other pin-shared function will be removed. In addition, any internal pull-high resistor connected to the pin will be automatically removed if the pin is selected to be an A/D converter input.

• **SADC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	START	ADBZ	ADCEN	ADRFS	ADVBGEN	SACS2	SACS1	SACS0
R/W	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **START**: Start the A/D conversion
0→1→0: Start
This bit is used to initiate an A/D conversion process. The bit is normally low but if set high and then cleared low again, the A/D converter will initiate a conversion process.

Bit 6 **ADBZ**: A/D converter busy flag
0: No A/D conversion is in progress
1: A/D conversion is in progress
This read only flag is used to indicate whether the A/D conversion is in progress or not. When the START bit is set from low to high and then to low again, the ADBZ flag will be set to 1 to indicate that the A/D conversion is initiated. The ADBZ flag will be cleared to 0 after the A/D conversion is complete.

Bit 5 **ADCEN**: A/D converter function enable control
0: Disable
1: Enable
This bit controls the A/D internal function. This bit should be set to one to enable the A/D converter. If the bit is set low, then the A/D converter will be switched off reducing the device power consumption. When the A/D converter function is disabled, the contents of the A/D data register pair known as SADOH and SADOL will be cleared.

Bit 4 **ADRFS**: A/D conversion data format selection
0: A/D converter data format → SADOH = D[11:4]; SADOL = D[3:0]
1: A/D converter data format → SADOH = D[11:8]; SADOL = D[7:0]
This bit controls the format of the 12-bit converted A/D value in the two A/D data registers. Details are provided in the A/D converter data register section.

Bit 3 **ADVBGEN**: A/D converter internal 1.2V bandgap and OPA (gain=2) function enable control
0: Disable
1: Enable
This bit must be set high to enable the A/D converter internal bandgap and OPA if the A/D converter OPA output V_{VR} is selected to be used as the reference voltage.

Bit 2~0 **SACS2~SACS0**: A/D converter external analog input channel selection
000: AN0
001: AN1
010: AN2
011: AN3
100: AN4
101: AN5
110: AN6
111: AN7

• **SADC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	SAINS2	SAINS1	SAINS0	SAVRS1	SAVRS0	SACKS2	SACKS1	SACKS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~5 **SAINS2~SAINS0**: A/D converter input signal selection
000: External source – External analog channel intput, ANn
001: Internal source – Bandgap reference voltage, V_{BG} (1.04V)
010: Internal source – OCP operational amplifier output, OCPAO
011/100: Internal source – Ground, AV_{SS}
101: Internal source – A/D converter power supply voltage divided by 4, $AV_{DD}/4$
110/111: External source – External analog channel input, ANn

When the internal analog signal is selected to be converted, the external channel input will automatically be switched off regardless of the SACS bit field value. It will prevent the external channel input from being connected together with the internal analog signal. Note that when the V_{BG} signal is selected to be converted, the VBGEN bit in the LVDC register should be set high.

Bit 4~3 **SAVRS1~SAVRS0**: A/D converter reference voltage selection
00: Internal A/D converter power, AV_{DD}
01: External VREF pin
10: Internal A/D converter OPA output, V_{VR}
11: Internal A/D converter power, AV_{DD}

These bits are used to select the A/D converter reference voltage source. When the internal reference voltage source is selected, the reference voltage derived from the external VREF pin will automatically be switched off.

Bit 2~0 **SACKS2~SACKS0**: A/D conversion clock source selection
000: f_{SYS}
001: $f_{SYS}/2$
010: $f_{SYS}/4$
011: $f_{SYS}/8$
100: $f_{SYS}/16$
101: $f_{SYS}/32$
110: $f_{SYS}/64$
111: $f_{SYS}/128$

A/D Converter Reference Voltage

The actual reference voltage supply to the A/D converter can be supplied from the positive power supply, AV_{DD}, or the A/D converter OPA output, V_{VR}, or an external reference source supplied on pin VREF, determined by the SAVRS bit field in the SADC1 register. When the SAVRS bit field is set to “00/11” or “10”, the A/D converter reference voltage will come from the internal A/D converter power AV_{DD} or the A/D converter OPA output V_{VR} respectively. Otherwise, the A/D converter reference voltage will come from the VREF pin. When the VREF pin is selected as the reference voltage supply pin, the relevant pin-shared control bits should first be properly configured to enable the VREF pin function as it is pin-shared with other functions. However, if the AV_{DD} or V_{VR} is selected as the reference voltage, the external reference input from the VREF pin will automatically be switched off by hardware.

Note that the analog input values must not be allowed to exceed the value of the selected reference voltage.

SAVRS[1:0]	Reference	Description
00, 11	AV_{DD}	Internal A/D converter power supply voltage
01	VREF pin	External A/D converter reference pin VREF
10	V_{VR}	Internal A/D converter OPA output voltage

A/D Converter Reference Voltage Selection

A/D Converter Input Signals

All of the external A/D analog input pins are pin-shared with the I/O pins as well as other functions. The corresponding pin-shared function control bits in the PxSn registers determine whether the external input pins are set as A/D converter analog channel inputs or whether they have other functions. If the corresponding pin is set to be an A/D converter analog channel input, the original pin function will be disabled. In this way, pins can be changed under program control to change their function between A/D inputs and other functions. All pull-high resistors, which are set through register programming, will be automatically disconnected if the pins are set as A/D inputs. Note that it is not necessary to first set the A/D pin as an input in the port control register to enable the A/D input as when the relevant A/D input function selection bits enable an A/D input, the status of the port control register will be overridden.

The A/D converter also has several internal analog input options, such as the OCP operational amplifier output OCPAO, Bandgap reference voltage V_{BG}, and A/D converter power divided by 4. The internal analog input signal is selected by setting the SAINS2~SAINS0 bits. If the SAINS2~SAINS0 bits are set to “000”, “110” or “111”, the external channel input will be selected to be converted and the SACS2~SACS0 bits can determine which external channel is selected. If the internal analog signal is selected to be converted, the external channel signal input will automatically be switched off regardless of the SACS bit field value. It will prevent the external channel input from being connected together with the internal analog signal.

SAINS[2:0]	SACS[2:0]	Input Signals	Description
000, 110, 111	000~111	AN0~AN7	External channel analog input ANn
001	xxx	V_{BG}	Bandgap reference voltage (1.04V)
010	xxx	OCPAO	OCP operational amplifier output
011, 100	xxx	AV_{SS}	Connected to ground
101	xxx	$AV_{DD}/4$	A/D converter power supply divided by 4

“x”: Don’t care

A/D Converter Input Signal Selection

A/D Converter Operation

The START bit in the SADC0 register is used to start the AD conversion. When the microcontroller sets this bit from low to high and then low again, an analog to digital conversion cycle will be initiated.

The ADBZ bit in the SADC0 register is used to indicate whether the analog to digital conversion process is in progress or not. This bit will be automatically set to 1 by the microcontroller after an A/D conversion is successfully initiated. When the A/D conversion is complete, the ADBZ bit will be cleared to 0. In addition, the corresponding A/D interrupt request flag in the interrupt control register will be set, and an internal A/D interrupt signal will be generated. If the A/D interrupt is enabled, this A/D internal interrupt signal will direct the program flow to the associated A/D internal interrupt address for processing. If the A/D internal interrupt is disabled, the microcontroller can poll the ADBZ bit in the SADC0 register to check whether it has been cleared as an alternative method of detecting the end of an A/D conversion cycle.

The clock source for the A/D converter, which originates from the system clock f_{SYS}, can be chosen to be either f_{SYS} or a subdivided version of f_{SYS}. The division ratio value is determined by the SACKS bit field in the SADC1 register. Although the A/D clock source is determined by the system clock f_{SYS} and by bits SACKS2~SACKS0, there are some limitations on the A/D clock source speed that can be selected. As the recommended range of permissible A/D clock period, t_{ADCK}, is from 0.5μs to 10μs, care must be taken for system clock frequencies. For example, if the system clock operates at a frequency of 8MHz, the SACKS2~SACKS0 bits should not be set to 000, 001 or 111. Doing so will give A/D clock periods that are less than the minimum A/D clock period or greater than the maximum A/D clock period which may result in inaccurate A/D conversion values. Refer to the following table for examples, where values marked with an asterisk * show where, special care must be taken, as the values may be beyond the specified A/D Clock Period range.

f_{SYS}	A/D Clock Period (t_{ADCK})							
	SACKS[2:0] = 000 (f_{SYS})	SACKS[2:0] = 001 (f_{SYS}/2)	SACKS[2:0] = 010 (f_{SYS}/4)	SACKS[2:0] = 011 (f_{SYS}/8)	SACKS[2:0] = 100 (f_{SYS}/16)	SACKS[2:0] = 101 (f_{SYS}/32)	SACKS[2:0] = 110 (f_{SYS}/64)	SACKS[2:0] = 111 (f_{SYS}/128)
1MHz	1μs	2μs	4μs	8μs	16μs *	32μs *	64μs *	128μs *
2MHz	500ns	1μs	2μs	4μs	8μs	16μs *	32μs *	64μs *
4MHz	250ns *	500ns	1μs	2μs	4μs	8μs	16μs *	32μs *
8MHz	125ns *	250ns *	500ns	1μs	2μs	4μs	8μs	16μs *

A/D Clock Period Examples

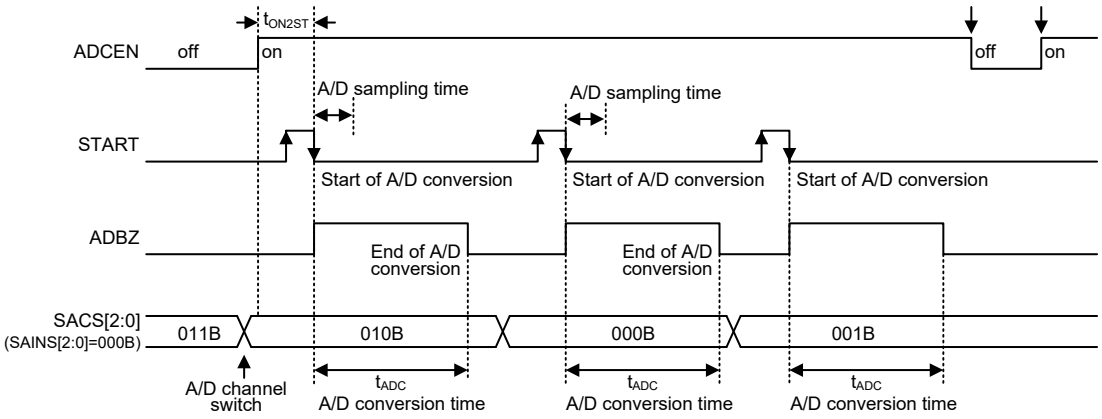
Controlling the power on/off function of the A/D converter circuitry is implemented using the ADCEN bit in the SADC0 register. This bit must be set high to power on the A/D converter. When the ADCEN bit is set high to power on the A/D converter internal circuitry, a certain delay, as indicated in the timing diagram, must be allowed before an A/D conversion is initiated. Even if no pins are selected for use as A/D inputs by configuring the relevant pin-shared control bits, if the ADCEN bit is high, then some power will still be consumed. In power conscious applications it is therefore recommended that the ADCEN is set low to reduce power consumption when the A/D converter function is not being used.

Conversion Rate and Timing Diagram

A complete A/D conversion contains two parts, data sampling and data conversion. The data sampling takes 4 A/D clock periods and the data conversion takes 12 A/D clock periods. Therefore a total of 16 A/D clock periods for an analog signal A/D conversion which is defined as t_{ADC} are necessary.

$$\text{Maximum single A/D conversion rate} = 1 \div (\text{A/D clock period} \times 16)$$

The accompanying diagram shows graphically the various stages involved in an external channel input signal analog to digital conversion process and its associated timing. After an A/D conversion process has been initiated by the application program, the microcontroller internal hardware will begin to carry out the conversion, during which time the program can continue with other functions. The time taken for an A/D conversion is 16 t_{ADCK} where t_{ADCK} is equal to the A/D clock period.



A/D Conversion Timing – External Channel Input

Summary of A/D Conversion Steps

The following summarises the individual steps that should be executed in order to implement an A/D conversion process.

- Step 1
  Select the required A/D conversion clock by properly programming the SACKS2~SACKS0 bits in the SADC1 register.
- Step 2
  Enable the A/D converter by setting the ADCEN bit in the SADC0 register to one.
- Step 3
  Select which signal is to be connected to the internal A/D converter by correctly configuring the SAINS bit field.
  Selecting the external channel input to be converted, go to Step 4.
  Selecting the internal analog signal to be converted, go to Step 5.
- Step 4
  If the SAINS bit field is set to select the external channel input, the corresponding pin should be configured as an A/D input function by selecting the relevant pin-shared control bits. Then the desired external channel input is selected by configuring the SACS bit field. Then go to Step 6.
- Step 5
  If the SAINS bit field is set to "001"~"101", the relevant internal analog signal will be selected. When the internal analog signal is selected to be converted, the external channel analog input will automatically be disconnected. Then go to Step 6.
- Step 6
  Select the A/D converter reference voltage source by configuring the SAVRS bit field in the SADC1 register. If the internal reference voltage is selected, the external reference voltage supplied on the VREF pin will be automatically disconnected. Set the ADVBGEN bit high if the OPA output voltage, V_{VR}, is selected as the A/D conversion reference voltage.
- Step 7
  Select the A/D converter output data format by configuring the ADRFS bit in the SADC0 register.
- Step 8
  If A/D conversion interrupt is used, the interrupt control registers must be correctly configured to ensure the A/D interrupt function is active. The master interrupt control bit, EMI, and the A/D conversion interrupt control bit, ADE, must both be set high in advance.

- Step 9
  The A/D conversion procedure can now be initialized by setting the START bit from low to high and then low again.
- Step 10
  If A/D conversion is in progress, the ADBZ flag will be set high. After the A/D conversion process is complete, the ADBZ flag will go low and then the output data can be read from SADOH and SADOL registers.

Note: When checking for the end of the conversion process, if the method of polling the ADBZ bit in the SADC0 register is used, the interrupt enable step above can be omitted.

Programming Considerations

During microcontroller operations where the A/D converter is not being used, the A/D internal circuitry can be switched off to reduce power consumption, by clearing bit ADCEN to zero in the SADC0 register. When this happens, the internal A/D converter circuits will not consume power irrespective of what analog voltage is applied to their input lines. If the A/D converter input lines are used as normal I/Os, then care must be taken as if the input voltage is not at a valid logic level, then this may lead to some increase in power consumption.

A/D Conversion Function

As the device contains a 12-bit A/D converter, its full-scale converted digitised value is equal to FFFH. Since the full-scale analog input value is equal to the actual A/D converter reference voltage, V_{REF}, this gives a single bit analog input value of reference voltage value divided by 4096.

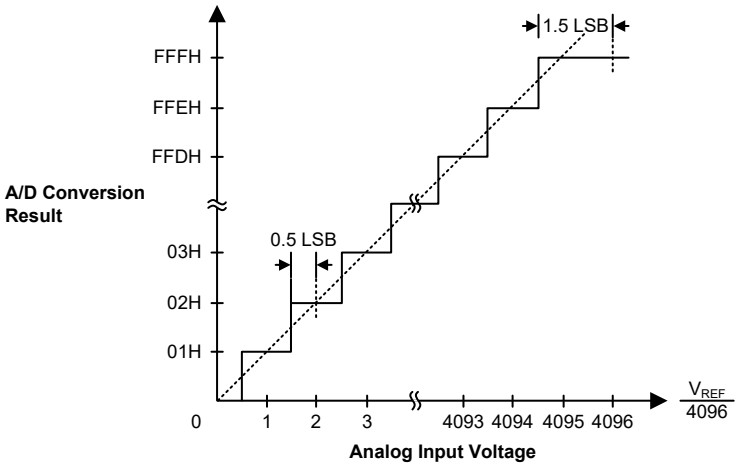
$$1\ LSB = V_{REF} \div 4096$$

The A/D Converter input voltage value cn be calculated using the following equation:

$$A/D\ input\ voltage = A/D\ output\ digital\ value \times (V_{REF} \div 4096)$$

The diagram shows the ideal transfer function between the analog input value and the digitised output value for the A/D converter. Except for the digitised zero value, the subsequent digitised values will change at a point 0.5 LSB below where they would change without the offset, and the last full scale digitised value will change at a point 1.5 LSB below the V_{REF} level.

Note that here the V_{REF} voltage is the actual A/D converter reference voltage source determined by the SAVRS field.



Ideal A/D Transfer Function

A/D Conversion Programming Examples

The following two programming examples illustrate how to set and implement an A/D conversion. In the first example, the method of polling the ADBZ bit in the SADC0 register is used to detect when the conversion cycle is complete, whereas in the second example, the A/D interrupt is used to determine when the conversion is complete.

Example: using an ADBZ polling method to detect the end of conversion

```
clr ADE               ; disable ADC interrupt
mov a,03h             ; select A/D input signal from external channel, reference voltage
mov SADC1,a           ; from AVDD, and fSYS/8 as A/D clock
mov a,03h
mov PAS0,a            ; set PAS0 to configure pin AN0
mov a,20h
mov SADC0,a           ; enable the A/D converter and connect AN0 channel to A/D converter
:
start_conversion:
clr START             ; high pulse on start bit to initiate conversion
set START             ; reset A/D
clr START             ; start A/D
polling_EOC:
sz  ADBZ              ; poll the SADC0 register ADBZ bit to detect end of A/D conversion
jmp polling_EOC       ; continue polling
mov a,SADOL           ; read low byte conversion result value
mov SADOL_buffer,a    ; save result to user defined register
mov a,SADOH           ; read high byte conversion result value
mov SADOH_buffer,a    ; save result to user defined register
:
:
jmp start_conversion  ; start next A/D conversion
```

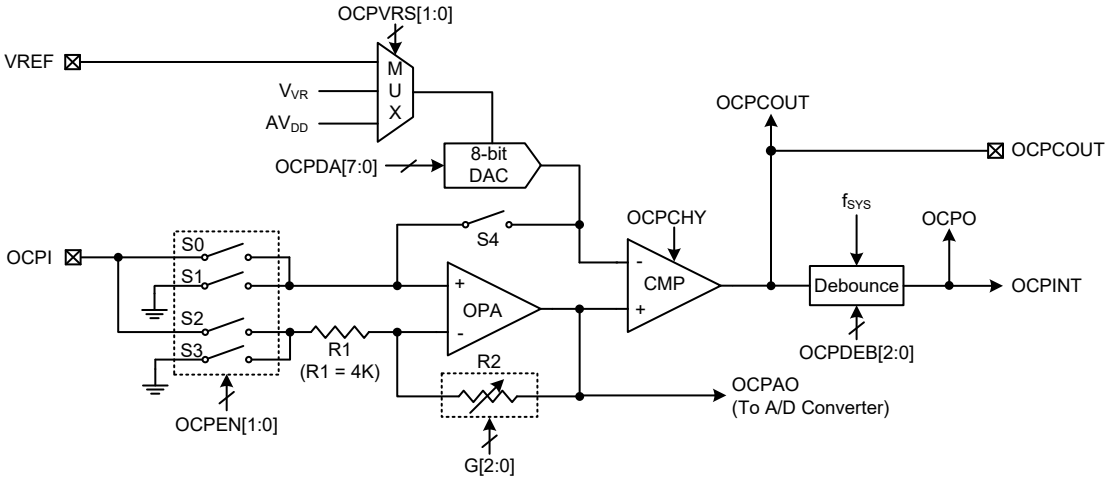
Example: using the interrupt method to detect the end of conversion

```
clr ADE               ; disable ADC interrupt
mov a,03h             ; select A/D input signal from external channel, reference voltage
mov SADC1,a           ; from AVDD, and fSYS/8 as A/D clock
mov a,03h
mov PAS0,a            ; set PAS0 to configure pin AN0
mov a,20h
mov SADC0,a           ; enable the A/D converter and connect AN0 channel to A/D converter
:
start_conversion:
clr START             ; high pulse on START bit to initiate conversion
set START             ; reset A/D
clr START             ; start A/D
clr ADF               ; clear ADC interrupt request flag
set ADE               ; enable ADC interrupt
set EMI               ; enable global interrupt
:
:
                      ; ADC interrupt service routine
ADC_ISR:
mov acc_stack,a       ; save ACC to user defined memory
mov a,STATUS
mov status_stack,a    ; save STATUS to user defined memory
:
:
```

```
mov a,SADOL           ; read low byte conversion result value
mov SADOL_buffer,a    ; save result to user defined register
mov a,SADOH           ; read high byte conversion result value
mov SADOH_buffer,a    ; save result to user defined register
:
:
EXIT_INT_ISR:
mov a,status_stack
mov STATUS,a          ; restore STATUS from user defined memory
mov a,acc_stack       ; restore ACC from user defined memory
reti
```

Over Current Protection – OCP

The device includes an over current protection function which provides a current protection mechanism for applications. The current on the OCPI pin is converted to a relevant voltage level according to the current value using the OCP operational amplifier. It is then compared with a reference voltage generated by an 8-bit D/A converter. When an over current event occurs, an OCP interrupt will be generated.



Note: 1. As the OCP function relevant external pins are pin-shared with general I/O or other functions, ensure that the corresponding pin-shared function registers has been configured properly before using the OCP function.

2. V_{VR} is sourced from the A/D converter OPA output.

Over Current Protection Circuit

Over Current Protection Operation

The OCP circuit is used to prevent the input current from exceeding a specific level. The current on the OCPI input is converted to a voltage and then amplified by the OCP Programmable Gain Amplifier (PGA) with a programmable gain from 1 to 50 selected by the G2~G0 bits in the OCPC1 register. The PGA is consisted of an operational amplifier and two resistors; the PGA gain can be positive or negative determined by input voltage connecting to positive input or negative input of the PGA. This PGA can also be configured to operate in the non-inverting, inverting or input offset calibration mode determined by the OCPEN1~OCPEN0 bits in the OCPC0 register. After the current is converted and amplified to a specific voltage level, it will be compared with a reference voltage provided by an 8-bit D/A converter. The 8-bit D/A converter reference voltage can be supplied by AV_{DD}, V_{VR} or the external VREF pin, which is selected by the OCPVRS1~OCPVRS0 bits in the OCPC0 register. The

comparator output, OCPCOUT, will first be filtered with a certain de bounce time period selected by the OCPDEB2~OCPDEB0 bits in the OCPC1 register. Then a filtered OCP comparator digital comparator output, OCPO, is obtained to indicate whether an over current condition occurs or not. The OCPO bit will be set to 1 if an over current condition occurs. Otherwise, the OCPO bit is zero. Once an over current event occurs, i.e., the converted voltage of the OCPI input current is greater than the reference voltage, the corresponding interrupt will be generated.

Note that the debounce clock, f_{DEB}, comes from the system clock, f_{SYS}. The operational amplifier output voltage can be read out by the A/D converter through an A/D internal input channel. The D/A converter output voltage is controlled by the OCPDA register.

Over Current Protection Registers

Overall operation of the over current protection is controlled using several registers. The OCPDA register is used to provide the reference voltage for the over current protection circuit. The OCPOCAL and OCPCCAL registers are used to cancel out the operational amplifier and comparator input offset. The OCPC0 and OCPC1 registers are control registers which control the OCP function, D/A converter reference voltage selection, PGA gain selection, comparator debounce time together with the hysteresis function.

Register Name	Bit							
	7	6	5	4	3	2	1	0
OCPC0	OCPEN1	OCPEN0	OCPVRS1	OCPVRS0	OCPCHY	—	—	OCPO
OCPC1	—	—	G2	G1	G0	OCPDEB2	OCPDEB1	OCPDEB0
OCPDA	D7	D6	D5	D4	D3	D2	D1	D0
OCPOCAL	OCPOOFM	OCPORSP	OCPOOF5	OCPOOF4	OCPOOF3	OCPOOF2	OCPOOF1	OCPOOF0
OCPCCAL	OCPCOUT	OCPCOFM	OCPCRSP	OCPCOF4	OCPCOF3	OCPCOF2	OCPCOF1	OCPCOF0

Over Current Protection Register List

• OCPC0 Register

Bit	7	6	5	4	3	2	1	0
Name	OCPEN1	OCPEN0	OCPVRS1	OCPVRS0	OCPCHY	—	—	OCPO
R/W	R/W	R/W	R/W	R/W	R/W	—	—	R
POR	0	0	0	0	0	—	—	0

Bit 7~6 **OCPEN1~OCPEN0**: OCP function operating mode selection
00: OCP function is disabled, S1and S3 on, S0 and S2 off
01: Non-inverting mode, S0 and S3 on, S1 and S2 off
10: Inverting mode, S1 and S2 on, S0 and S3 off
11: Calibration mode, S1 and S3 on, S0 and S2 off

Bit 5~4 **OCPVRS1~OCPVRS0**: OCP D/A converter reference voltage selection
00: From AV_{DD}
01: From VREF pin
10: From V_{VR}
11: From AV_{DD}

Bit 3 **OCPCHY**: OCP comparator hysteresis function control
0: Disable
1: Enable

Bit 2~1 Unimplemented, read as "0"

Bit 0 **OCPO**: OCP comparator digital output bit (after debounce)
0: No over current situation occurred
1: Over current situation occurred

• **OCPC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	G2	G1	G0	OCPDEB2	OCPDEB1	OCPDEB0
R/W	—	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5~3 **G2~G0**: OCP PGA R2/R1 ratio selection
000: Unity gain buffer (non-inverting mode) or R2/R1=1 (inverting mode)
001: R2/R1=5
010: R2/R1=10
011: R2/R1=15
100: R2/R1=20
101: R2/R1=30
110: R2/R1=40
111: R2/R1=50
These bits are used to select the R2/R1 ratio to obtain various gain values for inverting and non-inverting mode. The calculating formula of the PGA gain for the inverting and non-inverting mode is described in the "Input Voltage Range" section.

Bit 2~0 **OCPDEB2~OCPDEB0**: OCP output filter debounce time selection
000: Bypass, without debounce
001: (1~2)×t_{DEB}
010: (3~4)×t_{DEB}
011: (7~8)×t_{DEB}
100: (15~16)×t_{DEB}
101: (31~32)×t_{DEB}
110: (63~64)×t_{DEB}
111: (127~128)×t_{DEB}
Note: $t_{DEB}=1/f_{SYS}$.

• **OCPDA Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: OCP D/A converter output voltage control bits
DAC Output = (D/A converter reference voltage/256) × OCPDA[7:0]

• **OCPOCAL Register**

Bit	7	6	5	4	3	2	1	0
Name	OCPOOFM	OCPORSP	OCPOOF5	OCPOOF4	OCPOOF3	OCPOOF2	OCPOOF1	OCPOOF0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	1	0	0	0	0	0

Bit 7 **OCPOOFM**: OCP Operational Amplifier Input Offset Calibration Mode enable control
0: Input Offset Calibration Mode disable
1: Input Offset Calibration Mode enable
This bit is used to control the OCP operational amplifier input offset Calibration function. The OCPEN1 and OCPEN0 bits must first be set to "11" and then the OCPOOFM bit must be set to 1 followed by the OCPCOFM bit being setting to 0, then the operational amplifier input offset Calibration mode will be enabled. Refer to the "Operational Amplifier Input Offset Calibration" section for the detailed offset Calibration procedures.

Bit 6 **OCPORSP**: OCP Operational Amplifier Input Offset Calibration Reference selection
0: Select negative input as the reference input
1: Select positive input as the reference input

Bit 5~0 **OCPOOF5~OCPOOF0**: OCP Operational Amplifier Input Offset Calibration value
This 6-bit field is used to perform the operational amplifier input offset Calibration operation and the value for the OCP operational amplifier input offset Calibration can be restored into this bit field. More detailed information is described in the "Operational Amplifier Input Offset Calibration" section.

• OCPCCAL Register

Bit	7	6	5	4	3	2	1	0
Name	OCPCOUT	OCPCOFM	OCPCRSP	OCPCOF4	OCPCOF3	OCPCOF2	OCPCOF1	OCPCOF0
R/W	R	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	1	0	0	0	0

Bit 7 **OCPCOUT**: OCP comparator output, positive logic (before debounce)
0: Positive input voltage < Negative input voltage
1: Positive input voltage > Negative input voltage

Bit 6 **OCPCOFM**: OCP Comparator Input Offset Calibration Mode enable control
0: Input Offset Calibration Mode disable
1: Input Offset Calibration Mode enable
This bit is used to control the OCP comparator input offset Calibration function. The OCPEN1 and OCPEN0 bits must first be set to "11" and then the OCPCOFM bit must be set to 1 followed by the OCPOOFM bit being setting to 0, then the comparator input offset calibration mode will be enabled. Refer to the "Comparator Input Offset Calibration" section for the detailed offset calibration procedures.

Bit 5 **OCPCRSP**: OCP Comparator Input Offset Calibration Reference selection
0: Select negative input as the reference input
1: Select positive input as the reference input

Bit 4~0 **OCPCOF4~OCPCOF0**: OCP Comparator Input Offset Calibration value
This 5-bit field is used to perform the comparator input offset calibration operation and the value for the OCP comparator input offset calibration can be restored into this bit field. More detailed information is described in the "Comparator Input Offset Calibration" section.

Input Voltage Range

Together with different PGA operating modes, the input voltage can be positive or negative for flexible operation. The PGA output for the positive or negative input voltage is calculated based on different formulas and described by the following.

- For input voltages of $V_{IN} > 0$, the PGA operates in the non-inverting mode and the PGA output is obtained using the formula below:

$$V_{OUT} = (1+R2/R1) \times V_{IN}$$

- When the PGA operates in the non-inverting mode by setting the OCPEN[1:0] to "01" with unity gain select by setting the G[2:0] to "000", the PGA will act as a unit-gain buffer whose output is equal to V_{IN}.

$$V_{OUT} = V_{IN}$$

- For input voltages of $0 > V_{IN} > -0.2V$, the PGA operates in the inverting mode and the PGA output is obtained using the formula below. Note that if the input voltage is negative, it cannot be lower than -0.2V which will result in current leakage.

$$V_{OUT} = -(R2/R1) \times V_{IN}$$

Input Offset Calibration

The OCP circuit has four operating modes controlled by the OCPEN[1:0] bit field, one of them is calibration mode. In calibration mode, operational amplifier and comparator offset can be calibrated.

Operational Amplifier Input Offset Calibration

- Step 1
  Set OCPEN[1:0]=11, OCPOOFM=1, OCPCOFM=0 and OCPORSP=1, the OCP will operate in the operational amplifier input offset calibration mode.
- Step 2
  Set OCPOOF[5:0]=000000 and then read the OCPCOUT bit.
- Step 3
  Increase the OCPOOF[5:0] value by 1 and then read the OCPCOUT bit.
  If the OCPCOUT bit state has not changed, then repeat Step 3 until the OCPCOUT bit state has changed.
  If the OCPCOUT bit state has changed, record the OCPOOF value as V_{OOS1} and then go to Step 4.
- Step 4
  Set OCPOOF[5:0]=111111 and read the OCPCOUT bit.
- Step 5
  Decrease the OCPOOF[5:0] value by 1 and then read the OCPCOUT bit.
  If the OCPCOUT bit state has not changed, then repeat Step 5 until the OCPCOUT bit state has changed.
  If the OCPCOUT bit state has changed, record the OCPOOF value as V_{OOS2} and then go to Step 6.
- Step 6
  Restore the operational amplifier input offset calibration value V_{OOS} into the OCPOOF[5:0] bit field. The offset Calibration procedure is now finished.

$$\text{Where } V_{OOS} = (V_{OOS1}+V_{OOS2}) / 2$$

Note: S4 is off. In this mode, the operational amplifier outputs to OCPCOUT bypassing the comparator.

Comparator Input Offset Calibration

- Step 1
  Set OCPEN[1:0]=11, OCPCOFM=1 and OCPOOFM=0, the OCP will now operate in the comparator input offset calibration mode.
- Step 2
  Set OCPCOF[4:0]=00000 and read the OCPCOUT bit.
- Step 3
  Increase the OCPCOF[4:0] value by 1 and then read the OCPCOUT bit.
  If the OCPCOUT bit state has not changed, then repeat Step 3 until the OCPCOUT bit state has changed.
  If the OCPCOUT bit state has changed, record the OCPCOF value as V_{COS1} and then go to Step 4.
- Step 4
  Set OCPCOF[4:0]=11111 and then read the OCPCOUT bit.
- Step 5
  Decrease the OCPCOF[4:0] value by 1 and then read the OCPCOUT bit.
  If the OCPCOUT bit state has not changed, then repeat Step 5 until the OCPCOUT bit state has changed.
  If the OCPCOUT bit state has changed, record the OCPCOF value as V_{COS2} and then go to Step 6.

- Step 6

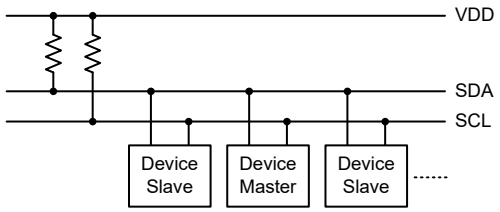
  Restore the comparator input offset calibration value V_{COS} into the OCPCOF[4:0] bit field. The offset Calibration procedure is now finished.

  Where $V_{COS} = (V_{COS1}+V_{COS2})/2$

Note: S4 is on and the D/A converter is off. This situation is only available for comparator calibration procedure. In the normal operation mode, S4 is off.

I²C Interface

The I²C interface is used to communicate with external peripheral devices such as sensors, EEPROM memory etc. Originally developed by Philips, it is a two-line low speed serial interface for synchronous serial data transfer. The advantage of only two lines for communication, relatively simple communication protocol and the ability to accommodate multiple devices on the same bus has made it an extremely popular interface type for many applications.

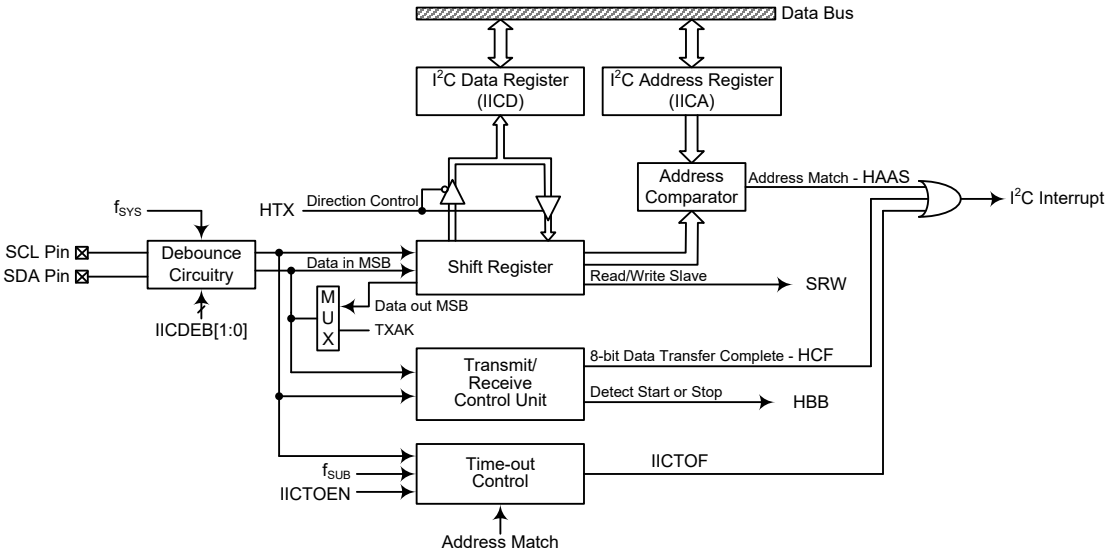


I²C Master Slave Bus Connection

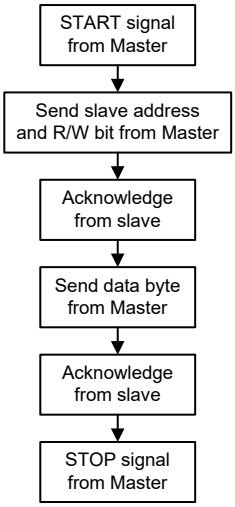
I²C Interface Operation

The I²C serial interface is a two-line interface, a serial data line, SDA, and serial clock line, SCL. As many devices may be connected together on the same bus, their outputs are both open drain types. For this reason it is necessary that external pull-high resistors are connected to these outputs. Note that no chip select line exists, as each device on the I²C bus is identified by a unique address which will be transmitted and received on the I²C bus.

When two devices communicate with each other on the bidirectional I²C bus, one is known as the master device and one as the slave device. Both master and slave can transmit and receive data. However, it is the master device that has overall control of the bus. For this device, which only operate in slave mode, there are two methods of transferring data on the I²C bus, the slave transmit mode and the slave receive mode. The pull-high control function pin-shared with SCL/SDA pin is still applicable even if the I²C device is activated and the related internal pull-high function could be controlled by its corresponding pull-high control register. It is suggested that the device should not enter the IDLE/SLEEP mode during the I²C communication.



I²C Block Diagram



I²C Interface Operation

The IICDEB1 and IICDEB0 bits determine the debounce time of the I²C interface. This uses the internal clock to in effect add a debounce time to the external clock to reduce the possibility of glitches on the clock line causing erroneous operation. The debounce time, if selected, can be chosen to be either 2 or 4 system clocks. To achieve the required I²C data transfer speed, there exists a relationship between the system clock, f_{SYS}, and the I²C debounce time. For either the I²C Standard or Fast mode operation, users must take care of the selected system clock frequency and the configured debounce time to match the criterion shown in the following table.

I²C Debounce Time Selection	I²C Standard Mode (100kHz)	I²C Fast Mode (400kHz)
No Debounce	f_{SYS} > 2MHz	f_{SYS} > 5MHz
2 system clock debounce	f_{SYS} > 4MHz	f_{SYS} > 10MHz
4 system clock debounce	f_{SYS} > 8MHz	f_{SYS} > 20MHz

I²C Minimum f_{SYS} Frequency Requirements

I²C Registers

There are three control registers associated with the I²C bus, IICC0, IICC1 and IICTOC, one address register IICA and one data register, IICD.

Register Name	Bit							
	7	6	5	4	3	2	1	0
IICC0	—	—	—	—	IICDEB1	IICDEB0	IICEN	—
IICC1	HCF	HAAS	HBB	HTX	TXAK	SRW	IAMWU	RXAK
IICD	D7	D6	D5	D4	D3	D2	D1	D0
IICA	IICA6	IICA5	IICA4	IICA3	IICA2	IICA1	IICA0	—
IICTOC	IICTOEN	IICTOF	IICTOS5	IICTOS4	IICTOS3	IICTOS2	IICTOS1	IICTOS0

I²C Register List

I²C Data Register

The IICD register is used to store the data being transmitted and received. Before the device writes data to the I²C bus, the actual data to be transmitted must be placed in the IICD register. After the data is received from the I²C bus, the device can read it from the IICD register. Any transmission or reception of data from the I²C bus must be made via the IICD register.

- **IICD Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	x	x	x	x	x	x	x	x

"x": unknown

Bit 7~0 **D7~D0**: I²C data register bit 7 ~ bit 0

I²C Address Register

The IICA register is the location where the 7-bit slave address of the slave device is stored. Bits 7~1 of the IICA register define the device slave address. Bit 0 is not defined. When a master device, which is connected to the I²C bus, sends out an address, which matches the slave address in the IICA register, the slave device will be selected.

- **IICA Register**

Bit	7	6	5	4	3	2	1	0
Name	IICA6	IICA5	IICA4	IICA3	IICA2	IICA1	IICA0	—
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	—
POR	0	0	0	0	0	0	0	—

Bit 7~1 **IICA6~IICA0**: I²C slave address
IICA6~IICA0 is the I²C slave address bit 6 ~ bit 0.

Bit 0 Unimplemented, read as "0"

I²C Control Registers

There are three control registers for the I²C interface, IICC0, IICC1 and IICTOC. The IICC0 register is used to control the enable/disable function and select the debounce time. The IICC1 register contains the relevant flags which are used to indicate the I²C communication status. Another register, IICTOC, is used to control the I²C time-out function and is described in the corresponding section.

• **IICC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	IICDEB1	IICDEB0	IICEN	—
R/W	—	—	—	—	R/W	R/W	R/W	—
POR	—	—	—	—	0	0	0	—

Bit 7~4 Unimplemented, read as "0"

Bit 3~2 **IICDEB1~IICDEB0**: I²C debounce time selection
00: No debounce
01: 2 system clock debounce
1x: 4 system clock debounce
Note that the I²C debounce circuit will operate normally if the system clock, f_{SYS}, is derived from the f_H clock or the IAMWU bit is equal to 0. Otherwise, the debounce circuit will have no effect and be bypassed.

Bit 1 **IICEN**: I²C enable control
0: Disable
1: Enable
The bit is the overall on/off control for the I²C interface. When the IICEN bit is cleared to zero to disable the I²C interface, the SDA and SCL lines will lose their I²C function and the I²C operating current will be reduced to a minimum value. When the bit is high the I²C interface is enabled. If the IICEN bit changes from low to high, the contents of the I²C control bits such as HTX and TXAK will remain at the previous settings and should therefore be first initialised by the application program while the relevant I²C flags such as HCF, HAAS, HBB, SRW and RXAK will be set to their default states.

Bit 0 Unimplemented, read as "0"

• **IICC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	HCF	HAAS	HBB	HTX	TXAK	SRW	IAMWU	RXAK
R/W	R	R	R	R/W	R/W	R	R/W	R
POR	1	0	0	0	0	0	0	1

Bit 7 **HCF**: I²C bus data transfer completion flag
0: Data is being transferred
1: Completion of an 8-bit data transfer
The HCF flag is the data transfer flag. This flag will be zero when data is being transferred. Upon completion of an 8-bit data transfer the flag will go high and an interrupt will be generated. The following is an example of the flow of a two-byte I²C data transfer.

- First, the I²C slave device receives a start signal from the I²C master and then the HCF bit is automatically cleared to zero.
- Second, the I²C slave device finishes receiving the 1st data byte and then the HCF bit is automatically set to one.
- Third, the user reads the 1st data byte from the IICD register by the application program and then the HCF bit is automatically cleared to zero.
- Fourth, the I²C slave device finishes receiving the 2nd data byte and then the HCF bit is automatically set to one and so on.
- Finally, the I²C slave device receives a stop signal from the I²C master and then the HCF bit is automatically set to one.

Bit 6 **HAAS**: I²C bus address match flag
0: Address not match
1: Address match
The HAAS flag is the address match flag. This flag is used to determine if the slave device address is the same as the master transmit address. If the addresses match then this bit will be high, if there is no match then the flag will be low.

Bit 5 **HBB**: I²C bus busy flag
0: I²C Bus is not busy
1: I²C Bus is busy
The HBB flag is the I²C busy flag. This flag will be "1" when the I²C bus is busy which will occur when a START signal is detected. The flag will be cleared to "0" when the bus is free which will occur when a STOP signal is detected.

Bit 4 **HTX**: I²C slave device is transmitter or receiver selection
0: Slave device is the receiver
1: Slave device is the transmitter

Bit 3 **TXAK**: I²C bus transmit acknowledge flag
0: Slave send acknowledge flag
1: Slave do not send acknowledge flag
The TXAK bit is the transmit acknowledge flag. After the slave device receipt of 8 bits of data, this bit will be transmitted to the bus on the 9th clock from the slave device. The slave device must always set TXAK bit to "0" before further data is received.

Bit 2 **SRW**: I²C slave read/write flag
0: Slave device should be in receive mode
1: Slave device should be in transmit mode
The SRW flag is the I²C Slave Read/Write flag. This flag determines whether the master device wishes to transmit or receive data from the I²C bus. When the transmitted address and slave address is match, that is when the HAAS flag is set high, the slave device will check the SRW flag to determine whether it should be in transmit mode or receive mode. If the SRW flag is high, the master is requesting to read data from the bus, so the slave device should be in transmit mode. When the SRW flag is zero, the master will write data to the bus, therefore the slave device should be in receive mode to read this data.

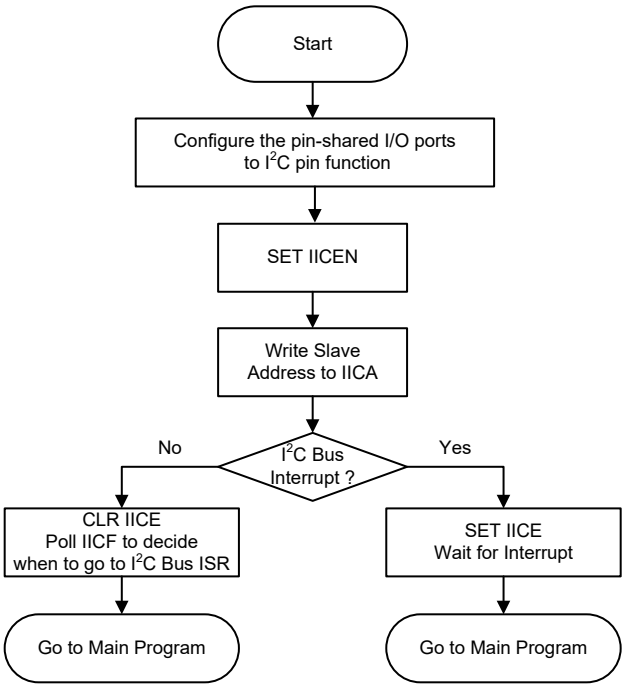
Bit 1 **IAMWU**: I²C address match wake-up control
0: Disable
1: Enable
This bit should be set to 1 to enable the I²C address match wake-up from the SLEEP or IDLE Mode. If the IAMWU bit has been set before entering either the SLEEP or IDLE mode to enable the I²C address match wake-up, then this bit must be cleared by the application program after wake-up to ensure correction device operation.

Bit 0 **RXAK**: I²C bus receive acknowledge flag
0: Slave receive acknowledge flag
1: Slave does not receive acknowledge flag
The RXAK flag is the receiver acknowledge flag. When the RXAK flag is "0", it means that a acknowledge signal has been received at the 9th clock, after 8 bits of data have been transmitted. When the slave device in the transmit mode, the slave device checks the RXAK flag to determine if the master receiver wishes to receive the next byte. The slave transmitter will therefore continue sending out data until the RXAK flag is "1". When this occurs, the slave transmitter will release the SDA line to allow the master to send a STOP signal to release the I²C Bus.

I²C Bus Communication

Communication on the I²C bus requires four separate steps, a START signal, a slave device address transmission, a data transmission and finally a STOP signal. When a START signal is placed on the I²C bus, all devices on the bus will receive this signal and be notified of the imminent arrival of data on the bus. The first seven bits of the data will be the slave address with the first bit being the MSB. If the address of the slave device matches that of the transmitted address, the HAAS bit in the IICC1 register will be set and an I²C interrupt will be generated. After entering the interrupt service routine, the slave device must first check the condition of the HAAS and IICTOF bits to determine whether the interrupt source originates from an address match or from the completion of an 8-bit data transfer completion or from the I²C bus time-out occurrence. During a data transfer, note that after the 7-bit slave address has been transmitted, the following bit, which is the 8th bit, is the read/write bit whose value will be placed in the SRW bit. This bit will be checked by the slave device to determine whether to go into transmit or receive mode. Before any transfer of data to or from the I²C bus, the microcontroller must initialise the bus, the following are steps to achieve this:

- Step 1
  Configure the relevant pin-shared I/O ports to I²C pin function (SCL and SDA).
- Step 2
  Set the IICEN bit in the IICC0 register to "1" to enable the I²C bus.
- Step 3
  Write the slave address of the device to the I²C bus address register IICA.
- Step 4
  Set the IICE interrupt enable bit of the interrupt control register to enable the I²C interrupt.



I²C Bus Initialisation Flowchart

I²C Bus Start Signal

The START signal can only be generated by the master device connected to the I²C bus and not by the slave device. This START signal will be detected by all devices connected to the I²C bus. When detected, this indicates that the I²C bus is busy and therefore the HBB bit will be set. A START condition occurs when a high to low transition on the SDA line takes place when the SCL line remains high.

I²C Slave Address

The transmission of a START signal by the master will be detected by all devices on the I²C bus. To determine which slave device the master wishes to communicate with, the address of the slave device will be sent out immediately following the START signal. All slave devices, after receiving this 7-bit address data, will compare it with their own 7-bit slave address. If the address sent out by the master matches the internal address of the microcontroller slave device, then an internal I²C bus interrupt signal will be generated. The next bit following the address, which is the 8th bit, defines the read/write status and will be saved to the SRW bit of the IICC1 register. The slave device will then transmit an acknowledge bit, which is a low level, as the 9th bit. The slave device will also set the status flag HAAS when the addresses match.

As an I²C bus interrupt can come from three sources, when the program enters the interrupt subroutine, the HAAS and IICTOF bits should be examined to see whether the interrupt source has come from a matching slave address or from the completion of a data byte transfer or from the I²C bus time-out occurrence. When a slave address is matched, the device must be placed in either the transmit mode and then write data to the IICD register, or in the receive mode where it must implement a dummy read from the IICD register to release the SCL line.

I²C Bus Read/Write Signal

The SRW bit in the IICC1 register defines whether the master device wishes to read data from the I²C bus or write data to the I²C bus. The slave device should examine this bit to determine if it is to be a transmitter or a receiver. If the SRW flag is “1” then this indicates that the master device wishes to read data from the I²C bus, therefore the slave device must be set to send data to the I²C bus as a transmitter. If the SRW flag is “0” then this indicates that the master wishes to send data to the I²C bus, therefore the slave device must be set to read data from the I²C bus as a receiver.

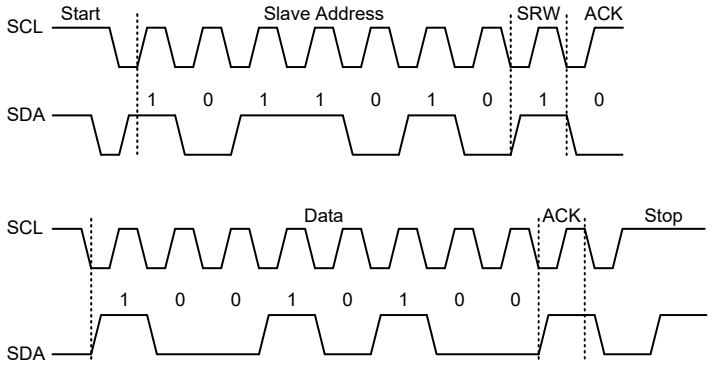
I²C Bus Slave Address Acknowledge Signal

After the master has transmitted a calling address, any slave device on the I²C bus, whose own internal address matches the calling address, must generate an acknowledge signal. The acknowledge signal will inform the master that a slave device has accepted its calling address. If no acknowledge signal is received by the master then a STOP signal must be transmitted by the master to end the communication. When the HAAS flag is high, the addresses have matched and the slave device must check the SRW flag to determine if it is to be a transmitter or a receiver. If the SRW flag is high, the slave device should be set to be a transmitter so the HTX bit in the IICC1 register should be set to “1”. If the SRW flag is low, then the microcontroller slave device should be set as a receiver and the HTX bit in the IICC1 register should be set to “0”.

I²C Bus Data and Acknowledge Signal

The transmitted data is 8-bit wide and is transmitted after the slave device has acknowledged receipt of its slave address. The order of serial bit transmission is the MSB first and the LSB last. After receipt of 8 bits of data, the receiver must transmit an acknowledge signal, level "0", before it can receive the next data byte. If the slave transmitter does not receive an acknowledge bit signal from the master receiver, then the slave transmitter will release the SDA line to allow the master to send a STOP signal to release the I²C Bus. The corresponding data will be stored in the IICD register. If set as a transmitter, the slave device must first write the data to be transmitted into the IICD register. If set as a receiver, the slave device must read the transmitted data from the IICD register.

When the slave receiver receives the data byte, it must generate an acknowledge bit, known as TXAK, on the 9th clock. The slave device, which is set as a transmitter will check the RXAK bit in the IICC1 register to determine if it is to send another data byte, if not then it will release the SDA line and await the receipt of a STOP signal from the master.

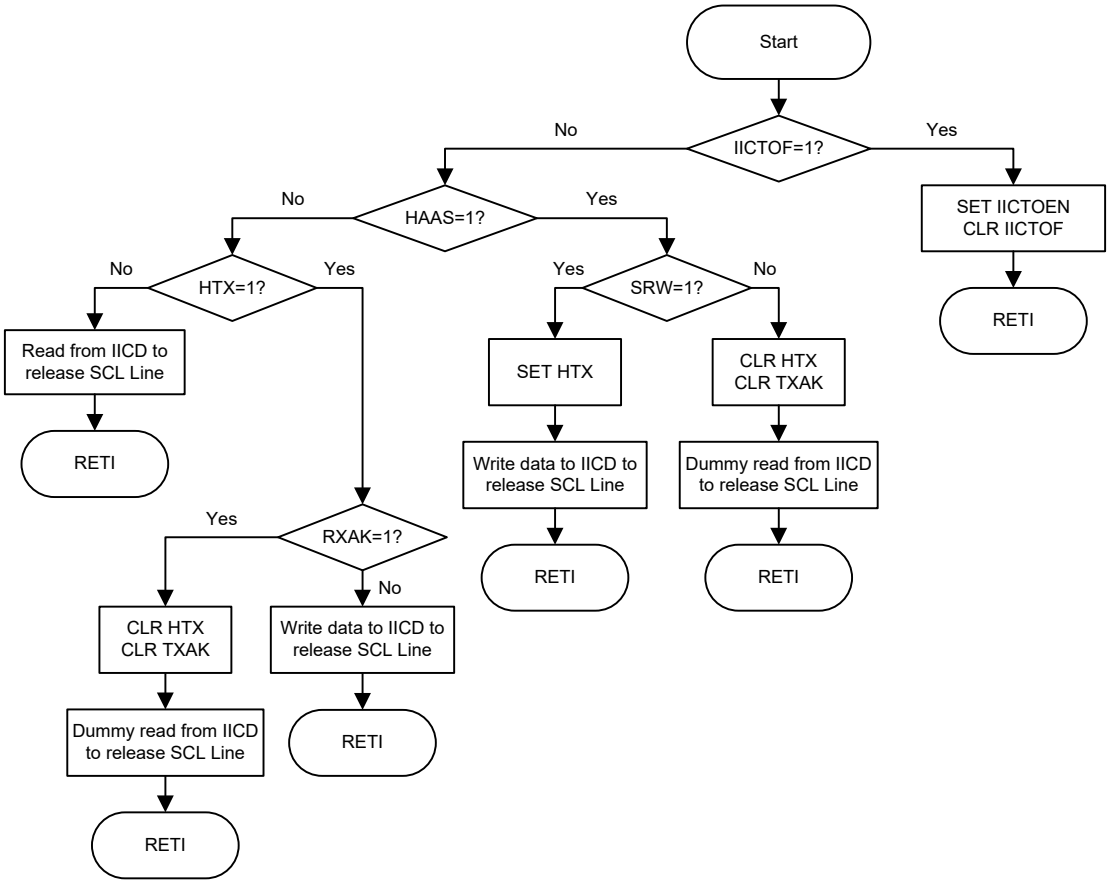


S=Start (1 bit)
SA=Slave Address (7 bits)
SR=SRW bit (1 bit)
M=Slave device send acknowledge bit (1 bit)
D=Data (8 bits)
A=ACK (RXAK bit for transmitter, TXAK bit for receiver, 1 bit)
P=Stop (1 bit)

S	SA	SR	M	D	A	D	A	·····	S	SA	SR	M	D	A	D	A	·····	P

I²C Communication Timing Diagram

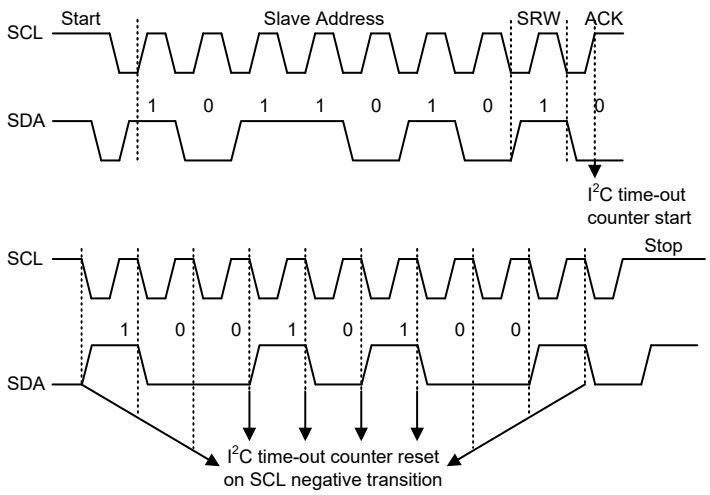
Note: When a slave address is matched, the device must be placed in either the transmit mode and then write data to the IICD register, or in the receive mode where it must implement a dummy read from the IICD register to release the SCL line.



I²C Bus ISR Flowchart

I²C Time-out Control

In order to reduce the problem of I²C lockup due to reception of erroneous clock sources, a time-out function is provided. If the clock source to the I²C is not received for a while, then the I²C circuitry and registers will be reset after a certain time-out period. The time-out counter starts counting on an I²C bus "START" & "address match" condition, and is cleared by an SCL falling edge. Before the next SCL falling edge arrives, if the time elapsed is greater than the time-out setup by the IICTOC register, then a time-out condition will occur. The time-out function will stop when an I²C "STOP" condition occurs.



I²C Time-out

When an I²C time-out counter overflow occurs, the counter will stop and the IICTOEN bit will be cleared to zero and the IICTOF bit will be set high to indicate that a time-out condition has occurred. The time-out condition will also generate an interrupt which uses the I²C interrupt vector. When an I²C time-out occurs, the I²C internal circuitry will be reset and the registers will be reset into the following condition:

Registers	After I²C Time-out
IICD, IICA, IICC0	No change
IICC1	Reset to POR condition

I²C Registers after Time-out

The IICTOF flag can be cleared by the application program. There are 64 time-out periods which can be selected using IICTOS bit field in the IICTOC register. The time-out time is given by the formula: $[(1\sim64)\times32]/f_{SUB}$. This gives a time-out period which ranges from about 1ms to 64ms.

- **IICTOC Register**

Bit	7	6	5	4	3	2	1	0
Name	IICTOEN	IICTOF	IICTOS5	IICTOS4	IICTOS3	IICTOS2	IICTOS1	IICTOS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

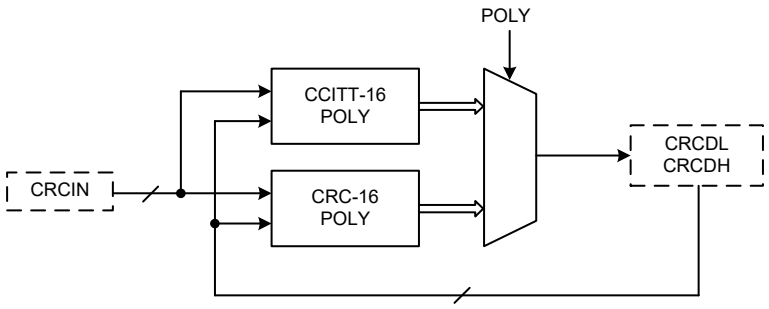
Bit 7 **IICTOEN**: I²C Time-out control
0: Disable
1: Enable

Bit 6 **IICTOF**: I²C Time-out flag
0: No time-out occurred
1: Time-out occurred
This bit is set high when time-out occurs and can only be cleared to zero by application program.

Bit 5~0 **IICTOS5~IICTOS0**: I²C Time-out period selection
I²C time-out clock source is $f_{SUB}/32$.
I²C time-out time is equal to $(IICTOS[5:0]+1)\times(32/f_{SUB})$.

Cyclic Redundancy Check – CRC

The Cyclic Redundancy Check, CRC, calculation unit is an error detection technique test algorithm used to verify data transmission or storage data correctness. A CRC calculation takes a data stream or a block of data as input and generates a 16-bit output remainder. Ordinarily, a data stream is suffixed by a CRC code and used as a checksum when being sent or stored. Therefore, the received or restored data stream is calculated by the same generator polynomial as described in the following section.



CRC Block Diagram

CRC Registers

The CRC generator contains an 8-bit CRC data input register, CRCIN, and a CRC checksum register pair, CRCDH and CRCDL. The CRCIN register is used to input new data and the CRCDH and CRCDL registers are used to hold the previous CRC calculation result. A CRC control register, CRCCR, is used to select which CRC generating polynomial is used.

Register Name	Bit							
	7	6	5	4	3	2	1	0
CRCCR	—	—	—	—	—	—	—	POLY
CRCIN	D7	D6	D5	D4	D3	D2	D1	D0
CRCDL	D7	D6	D5	D4	D3	D2	D1	D0
CRCDH	D7	D6	D5	D4	D3	D2	D1	D0

CRC Registers List

• CRCCR Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	POLY
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as "0"

Bit 0 **POLY**: 16-bit CRC generating polynomial selection
0: CRC-CCITT: $X^{16}+X^{12}+X^5+1$
1: CRC-16: $X^{16}+X^{15}+X^2+1$

• CRCIN Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: CRC input data register

• **CRCDL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: 16-bit CRC checksum low byte data register

• **CRCDH Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: 16-bit CRC checksum high byte data register

CRC Operation

The CRC generator provides the 16-bit CRC result calculation based on the CRC16 and CCITT CRC16 polynomials. In this CRC generator, there are only these two polynomials available for the numeric values calculation. It cannot support the 16-bit CRC calculations based on any other polynomials.

The following two expressions can be used for the CRC generating polynomial which is determined using the POLY bit in the CRC control register, CRCCR. The CRC calculation result is called as the CRC checksum, CRCSUM, and stored in the CRC checksum register pair, CRCDH and CRCDL.

- CRC-CCITT: $X^{16}+X^{12}+X^5+1$
- CRC-16: $X^{16}+X^{15}+X^2+1$

CRC Computation

Each write operation to the CRCIN register creates a combination of the previous CRC value stored in the CRCDH and CRCDL registers and the new data input. The CRC unit calculates the CRC data register value byte by byte. It will take one MCU instruction cycle to calculate the CRC checksum.

CRC Calculation Procedures

1. Clear the checksum register pair, CRCDH and CRCDL.
2. Execute an “Exclusive OR” operation with the 8-bit input data byte and the 16-bit CRCSUM high byte. The result is called the temporary CRCSUM.
3. Shift the temporary CRCSUM value left by one bit and move a “0” into the LSB.
4. Check the shifted temporary CRCSUM value after procedure 3.

   If the MSB is 0, then this shifted temporary CRCSUM will be considered as a new temporary CRCSUM.

   Otherwise, execute an “Exclusive OR” operation with the shifted temporary CRCSUM in procedure 3 and a data “8005H”. Then the operation result will be regarded as the new temporary CRCSUM.

   Note that the data to be perform an “Exclusive OR” operation is “8005H” for the CRC-16 polynomial while for the CRC-CCITT polynomial the data is “1021H”.
5. Repeat the procedure 3 ~ procedure 4 until all bits of the input data byte are completely calculated.
6. Repeat the procedure 2 ~ procedure 5 until all of the input data bytes are completely calculated. Then, the latest calculated result is the final CRC checksum, CRCSUM.

CRC Calculation Examples

- Write 1 byte of input data into the CRCIN register and the corresponding CRC checksum are individually calculated as the following table shown.

CRC Data Input / CRC Polynomial	00H	01H	02H	03H	04H	05H	06H	07H
CRC-CCITT ($X^{16}+X^{12}+X^5+1$)	0000H	1021H	2042H	3063H	4084H	50A5H	60C6H	70E7H
CRC-16 ($X^{16}+X^{15}+X^2+1$)	0000H	8005H	800FH	000AH	801BH	001EH	0014H	8011H

Note: The initial value of the CRC checksum register pair, CRCDH and CRCDL, is zero before each CRC input data is written into the CRCIN register.

- Write 4 bytes of input data into the CRCIN register sequentially and the CRC checksum are sequentially listed in the following table.

CRC Data Input / CRC Polynomial	CRCIN=78H→56H→34H→12H
CRC-CCITT ($X^{16}+X^{12}+X^5+1$)	(CRCDH, CRCDL) = FF9FH→BBC3H→A367H→D0FAH
CRC-16 ($X^{16}+X^{15}+X^2+1$)	(CRCDH, CRCDL) = 0110h→91F1h→F2DEh→5C43h

Note: The initial value of the CRC checksum register pair, CRCDH and CRCDL, is zero before the sequential CRC data input operation.

Program Memory CRC Checksum Calculation Example

1. Clear the checksum register pair, CRCDH and CRCDL.
2. Select the CRC-CCITT or CRC-16 polynomial as the generating polynomial using the POLY bit in the CRCCR register.
3. Execute the table read instruction to read the program memory data value.
4. Write the table data low byte into the CRCIN register and execute the CRC calculation with the current CRCSUM value. Then a new CRCSUM result will be obtained and stored in the CRC checksum register pair, CRCDH and CRCDL.
5. Write the table data high byte into the CRCIN register and execute the CRC calculation with the current CRCSUM value. Then a new CRCSUM result will be obtained and stored in the CRC checksum register pair, CRCDH and CRCDL.
6. Repeat the procedure 3 ~ procedure 5 to read the next program memory data value and execute the CRC calculation until all program memory data are read followed by the sequential CRC calculation. Then the value in the CRC checksum register pair is the final CRC calculation result.

Low Voltage Detector – LVD

The device has a Low Voltage Detector function, also known as LVD. This enables the device to monitor the power supply voltage, V_{DD}, and provide a warning signal should it fall below a certain level. This function may be especially useful in battery applications where the supply voltage will gradually reduce as the battery ages, as it allows an early warning battery low signal to be generated. The Low Voltage Detector also has the capability of generating an interrupt signal.

LVD Register

The Low Voltage Detector function is controlled using a single register with the name LVDC. Three bits in this register, VLVD2~VLVD0, are used to select one of eight fixed voltages below which a low voltage condition will be determined. A low voltage condition is indicated when the LVDO bit is set. If the LVDO bit is low, this indicates that the V_{DD} voltage is above the preset low voltage value. The LVDEN bit is used to control the overall on/off function of the low voltage detector. Setting the bit high will enable the low voltage detector. Clearing the bit to zero will switch off the internal low voltage detector circuits. As the low voltage detector will consume a certain amount of power, it may be desirable to switch off the circuit when not in use, an important consideration in power sensitive battery powered applications.

- **LVDC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	LVDO	LVDEN	VBGEN	VLVD2	VLVD1	VLVD0
R/W	—	—	R	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5 **LVDO**: LVD output flag
0: No low voltage detected
1: Low voltage detected

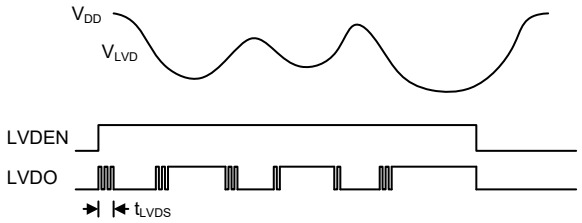
Bit 4 **LVDEN**: Low voltage detector control
0: Disable
1: Enable

Bit 3 **VBGEN**: Bandgap buffer control
0: Disable
1: Enable
Note that the Bandgap circuit is enabled when the LVD or LVR function is enabled or when the VBGEN bit is set to 1.

Bit 2~0 **VLVD2~VLVD0**: LVD voltage selection
000: 2.0V
001: 2.2V
010: 2.4V
011: 2.7V
100: 3.0V
101: 3.3V
110: 3.6V
111: 4.0V

LVD Operation

The Low Voltage Detector function operates by comparing the power supply voltage, V_{DD}, with a pre-specified voltage level stored in the LVDC register. This pre-spedified voltage has a range of 2.0V~4.0V. When the power supply voltage, V_{DD}, falls below this pre-determined value, the LVDO bit will be set high indicating a low power supply voltage condition. When the device is in the SLEEP mode, the low voltage detector will be disabled even if the LVDEN bit is high. After enabling the Low Voltage Detector, a time delay t_{LVDS} should be allowed for the circuitry to stabilise before reading the LVDO bit. Note also that as the V_{DD} voltage may rise and fall rather slowly, at the voltage near that of V_{LVD}, there may be multiple LVDO bit transitions.



LVD Operation

The Low Voltage Detector also has its own interrupt, providing an alternative means of low voltage detection, in addition to polling the LVDO bit. The interrupt will only be generated after a delay of t_{LVD} after the LVDO bit has been set high by a low voltage condition, i.e., V_{DD} falls below the preset LVD voltage. In this case, the LVF interrupt request flag will be set, causing an interrupt to be generated. This will cause the device to wake up from the IDLE Mode, however if the Low Voltage Detector wake-up function is not required then the LVF flag should be first set high before the device enters the IDLE Mode.

Interrupts

Interrupts are an important part of any microcontroller system. When an external event or an internal function such as a Timer Module or an A/D converter requires microcontroller attention, their corresponding interrupt will enforce a temporary suspension of the main program allowing the microcontroller to direct attention to their respective needs. The device contains two external interrupts and several internal interrupt functions. The external interrupts are generated by the action of the external INT0~INT1 pins, while the internal interrupts are generated by various internal functions such as the TMs, Time Bases, I^2C and the A/D converter, etc.

Interrupt Registers

Overall interrupt control, which basically means the setting of request flags when certain microcontroller conditions occur and the setting of interrupt enable bits by the application program, is controlled by a series of registers, located in the Special Purpose Data Memory, as shown in the accompanying table. The registers fall into three categories. The first is the INTC0~INTC2 registers which configure the primary interrupts. The second is the MFI0~MFI1 registers which configure the Multi-function interrupts. Finally there is an INTEG register to configure the external interrupt trigger edge type.

Each register contains a number of enable bits to enable or disable individual interrupts as well as interrupt flags to indicate the presence of an interrupt request. The naming convention of these follows a specific pattern. First is listed an abbreviated interrupt type, then the (optional) number of that interrupt followed by either an “E” for enable/disable bit or “F” for request flag.

Function	Enable Bit	Request Flag	Notes
Global	EMI	—	—
INTn Pin	INTnE	INTnF	n=0~1
Over Circuit Protection	OCPE	OCPF	—
Time Bases	TBnE	TBnF	n=0~1
I²C Interface	IICE	IICF	—
A/D Converter	ADE	ADF	—
LVD	LVE	LVF	—
EEPTOM	DEE	DEF	—
Multi-function	MFnE	MFnF	n=0~1
PTM	PTMnPE	PTMnPF	n=0~1
	PTMnAE	PTMnAF	

Interrupt Register Bit Naming Conventions

Register Name	Bit							
	7	6	5	4	3	2	1	0
INTEG	—	—	—	—	INT1S1	INT1S0	INT0S1	INT0S0
INTC0	—	INT1F	OCPF	INT0F	INT1E	OCPE	INT0E	EMI
INTC1	TB1F	TB0F	MF1F	MF0F	TB1E	TB0E	MF1E	MF0E
INTC2	DEF	LVF	ADF	IICF	DEE	LVE	ADE	IICE
MFI0	—	—	PTM0AF	PTM0PF	—	—	PTM0AE	PTM0PE
MFI1	—	—	PTM1AF	PTM1PF	—	—	PTM1AE	PTM1PE

Interrupt Register List

- **INTEG Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	INT1S1	INT1S0	INT0S1	INT0S0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3~2 **INT1S1~INT1S0**: Interrupt trigger edge selection for INT1 pin
00: Disable
01: Rising edge
10: Falling edge
11: Rising and falling edges

Bit 1~0 **INT0S1~INT0S0**: Interrupt trigger edge selection for INT0 pin
00: Disable
01: Rising edge
10: Falling edge
11: Rising and falling edges

- **INTC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	INT1F	OCPF	INT0F	INT1E	OCPE	INT0E	EMI
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	0	0	0	0	0	0	0

Bit 7 Unimplemented, read as "0"

Bit 6 **INT1F**: INT1 interrupt request flag
0: No request
1: Interrupt request

Bit 5 **OCPF**: OCP interrupt request flag
0: No request
1: Interrupt request

Bit 4 **INT0F**: INT0 interrupt request flag
0: No request
1: Interrupt request

Bit 3 **INT1E**: INT1 interrupt control
0: Disable
1: Enable

Bit 2 **OCPE**: OCP interrupt control
0: Disable
1: Enable

Bit 1 **INT0E**: INT0 interrupt control
0: Disable
1: Enable

Bit 0 **EMI**: Global interrupt control
0: Disable
1: Enable

• **INTC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	TB1F	TB0F	MF1F	MF0F	TB1E	TB0E	MF1F	MF0E
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **TB1F**: Time Base 1 interrupt request flag
0: No request
1: Interrupt request

Bit 6 **TB0F**: Time Base 0 interrupt request flag
0: No request
1: Interrupt request

Bit 5 **MF1F**: Multi-functon 1 interrupt request flag
0: No request
1: Interrupt request

Bit 4 **MF0F**: Multi-functon 0 interrupt request flag
0: No request
1: Interrupt request

Bit 3 **TB1E**: Time Base 1 interrupt control
0: Disable
1: Enable

Bit 2 **TB0E**: Time Base 0 interrupt control
0: Disable
1: Enable

Bit 1 **MF1E**: Multi-functon 1 interrupt control
0: Disable
1: Enable

Bit 0 **MF0E**: Multi-functon 0 interrupt control
0: Disable
1: Enable

• **INTC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	DEF	LVF	ADF	IICF	DEE	LVE	ADE	IICE
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **DEF**: EEPROM interrupt request flag
0: No request
1: Interrupt request

Bit 6 **LVF**: LVD interrupt request flag
0: No request
1: Interrupt request

Bit 5 **ADF**: A/D Converter interrupt request flag
0: No request
1: Interrupt request

Bit 4 **IICF**: I^2C interrupt request flag
0: No request
1: Interrupt request

Bit 3 **DEE**: EEPROM interrupt control
0: Disable
1: Enable

Bit 2 **LVE**: LVD interrupt control
0: Disable
1: Enable

Bit 1 **ADE**: A/D Converter interrupt control
0: Disable
1: Enable

Bit 0 **IICE**: I^2C interrupt control
0: Disable
1: Enable

• **MFI0 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	PTM0AF	PTM0PF	—	—	PTM0AE	PTM0PE
R/W	—	—	R/W	R/W	—	—	R/W	R/W
POR	—	—	0	0	—	—	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5 **PTM0AF**: PTM0 Comparator A match interrupt request flag
0: No request
1: Interrupt request

Bit 4 **PTM0PF**: PTM0 Comparator P match interrupt request flag
0: No request
1: Interrupt request

Bit 3~2 Unimplemented, read as "0"

Bit 1 **PTM0AE**: PTM0 Comparator A match interrupt control
0: Disable
1: Enable

Bit 0 **PTM0PE**: PTM0 Comparator P match interrupt control
0: Disable
1: Enable

• **MFI1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	PTM1AF	PTM1PF	—	—	PTM1AE	PTM1PE
R/W	—	—	R/W	R/W	—	—	R/W	R/W
POR	—	—	0	0	—	—	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5 **PTM1AF**: PTM1 Comparator A match interrupt request flag
0: No request
1: Interrupt request

Bit 4 **PTM1PF**: PTM1 Comparator P match interrupt request flag
0: No request
1: Interrupt request

Bit 3~2 Unimplemented, read as "0"

Bit 1 **PTM1AE**: PTM1 Comparator A match interrupt control
0: Disable
1: Enable

Bit 0 **PTM1PE**: PTM1 Comparator P match interrupt control
0: Disable
1: Enable

Interrupt Operation

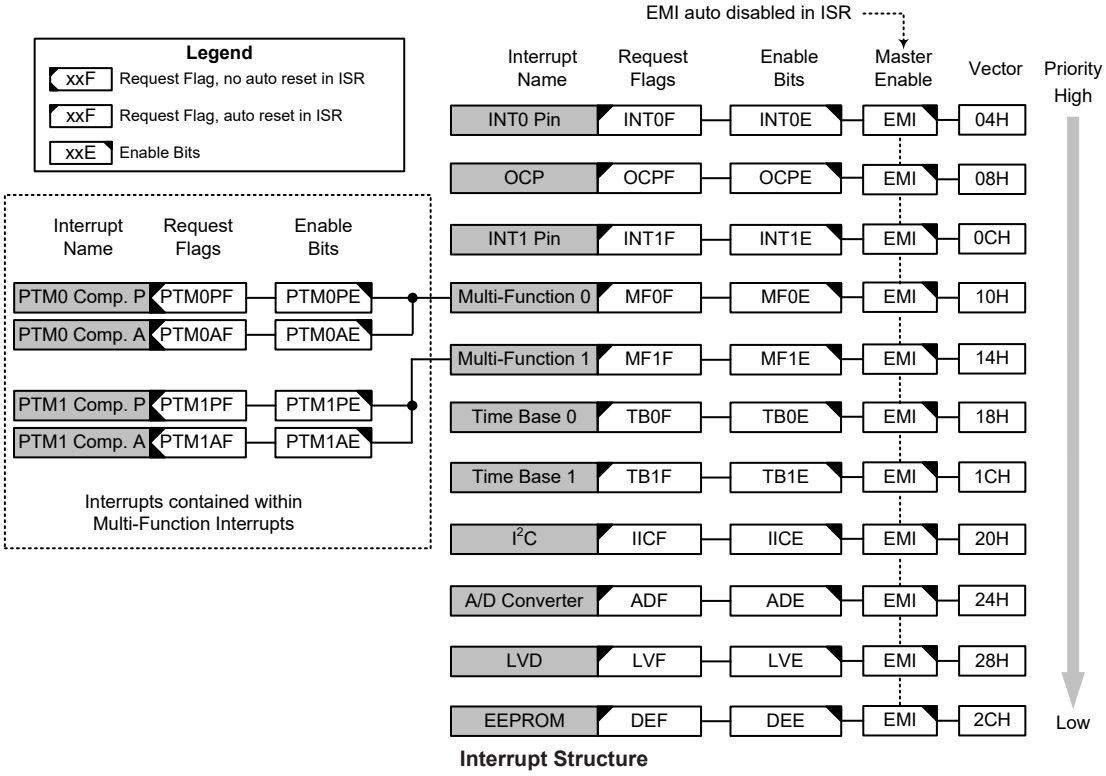
When the conditions for an interrupt event occur, such as a TM Comparator P or Comparator A match or A/D conversion completion, etc., the relevant interrupt request flag will be set. Whether the request flag actually generates a program jump to the relevant interrupt vector is determined by the condition of the interrupt enable bit. If the enable bit is set high then the program will jump to its relevant vector; if the enable bit is zero then although the interrupt request flag is set an actual interrupt will not be generated and the program will not jump to the relevant interrupt vector. The global interrupt enable bit, if cleared to zero, will disable all interrupts.

When an interrupt is generated, the Program Counter, which stores the address of the next instruction to be executed, will be transferred onto the stack. The Program Counter will then be loaded with a new address which will be the value of the corresponding interrupt vector. The microcontroller will then fetch its next instruction from this interrupt vector. The instruction at this vector will usually be a JMP which will jump to another section of program which is known as the interrupt service routine. Here is located the code to control the appropriate interrupt. The interrupt service routine must be terminated with a RETI, which retrieves the original Program Counter address from the stack and allows the microcontroller to continue with normal execution at the point where the interrupt occurred.

The various interrupt enable bits, together with their associated request flags, are shown in the accompanying diagrams with their order of priority. Some interrupt sources have their own individual vector while others share the same multi-function interrupt vector. Once an interrupt subroutine is serviced, all other interrupts will be blocked, as the global interrupt enable bit, EMI bit will be cleared automatically. This will prevent any further interrupt nesting from occurring. However, if other interrupt requests occur during this interval, although the interrupt will not be immediately serviced, the request flag will still be recorded.

If an interrupt requires immediate servicing while the program is already in another interrupt service routine, the EMI bit should be set after entering the routine to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even if the related interrupt is enabled, until the Stack Pointer is decreased. If immediate service is desired, the stack must be prevented from becoming full. In case of simultaneous requests, the accompanying diagram shows the priority that

is applied. All of the interrupt request flags when set will wake up the device if it is in SLEEP or IDLE Mode, however to prevent a wake-up from occurring the corresponding flag should be set before the device is in SLEEP or IDLE Mode.



Interrupt Structure

External Interrupts

The external interrupts are controlled by signal transitions on the INT0~INT1 pins. An external interrupt request will take place when the external interrupt request flag, INTnF, is set, which will occur when a transition, whose type is chosen by the edge select bits, appears on the external interrupt pin. To allow the program to branch to their respective interrupt vector addresses, the global interrupt enable bit, EMI, and the external interrupt enable bit, INTnE, must first be set. Additionally the correct interrupt edge type must be selected using the INTEG register to enable the external interrupt function and to choose the trigger edge type. As the external interrupt pins are pin-shared with I/O pins, they can only be configured as external interrupt pins if their respective external interrupt enable bits in the corresponding interrupt register have been set and the external interrupt pins are selected by the corresponding pin-shared function selection bits. The pins must also be set as an input by setting the corresponding bit in the port control register.

When the interrupt is enabled, the stack is not full and the desired transition type appears on the external interrupt pin, a subroutine call to the external interrupt vector, will take place. When the interrupt is serviced, the external interrupt request flag, INTnF, will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts. Note that any pull-high resistor selections on the external interrupt pins will remain valid even if the pin is used as an external interrupt input.

The INTEG register is used to select the type of active edge that will trigger the external interrupt. A choice of either rising or falling or both edge types can be chosen to trigger an external interrupt. Note that the INTEG register can also be used to disable the external interrupt function.

Over Current Protection Interrupt

The OCP Interrupt is controlled by detecting the OCPI input current. An OCP Interrupt request will take place when the OCP Interrupt request flag, OCPF, is set, which occurs when the OCP circuit detects an over current condition. To allow the program to branch to its interrupt vector address, the global interrupt enable bit, EMI, and OCP Interrupt enable bit, OCPE, must first be set. When the interrupt is enabled, the stack is not full and an over current condition is detected, a subroutine call to the OCP Interrupt vector, will take place. When the interrupt is serviced, the OCP Interrupt flag, OCPF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

Multi-function Interrupts

Within the device there are two Multi-function interrupts. Unlike the other independent interrupts, these interrupts have no independent source, but rather are formed from other existing interrupt sources, namely the TM interrupts.

A Multi-function interrupt request will take place when the Multi-function interrupt request flag MFnF is set. The Multi-function interrupt flag will be set when any of its included functions generate an interrupt request flag. When the Multi-function interrupt is enabled and the stack is not full, and one of the interrupts contained within the Multi-function interrupt occurs, a subroutine call to the corresponding Multi-function interrupt vector will take place. When the interrupt is serviced, the related Multi-Function request flag will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts.

However, it must be noted that, although the Multi-function Interrupt request flag will be automatically reset when the interrupt is serviced, the request flags from the original source of the Multi-function interrupt will not be automatically reset and must be manually reset by the application program.

TM Interrupts

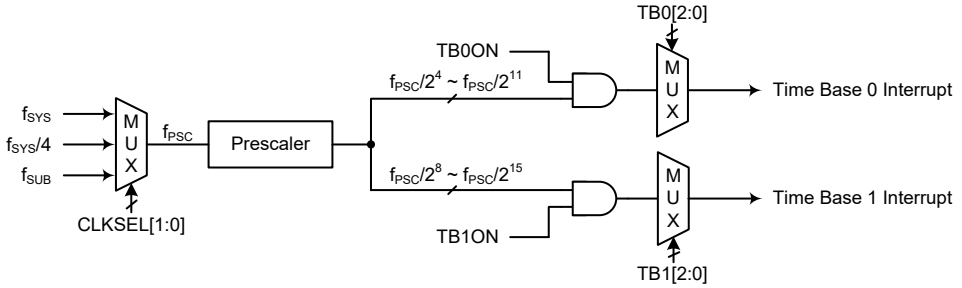
The Periodic TMs each have two interrupts, one comes from the comparator A match situation and the other comes from the comparator P match situation. All of the TM interrupts are contained within the Multi-function Interrupts. For each of the Periodic TMs there are two interrupt request flags and two enable control bits. A TM interrupt request will take place when any of the TM request flags are set, a situation which occurs when a TM comparator P or A match situation happens.

To allow the program to branch to their respective interrupt vector addresses, the global interrupt enable bit, EMI, the respective TM Interrupt enable bit and the relevant Multi-function Interrupt enable bit, MFnE, must also be set. When the interrupt is enabled, the stack is not full and a TM comparator match situation occurs, a subroutine call to the relevant Multi-function Interrupt vector locations will take place. When the TM interrupt is serviced, the EMI bit will be automatically cleared to disable other interrupts. However, only the related MFnF flag will be automatically cleared. As the TM interrupt request flag will not be automatically cleared, it has to be cleared by the application program.

Time Base Interrupts

The function of the Time Base Interrupts is to provide regular time signals in the form of an internal interrupt. They are controlled by the overflow signal from their respective internal timers. When this happens their respective interrupt request flags, TB0F or TB1F will be set. To allow the program to branch to their respective interrupt vector addresses, the global interrupt enable bit, EMI and the Time Base enable bit, TB0E or TB1E, must first be set. When the interrupt is enabled, the stack is not full and the Time Base overflows, a subroutine call to their respective vector locations will take place. When the interrupt is serviced, the interrupt request flag, TB0F or TB1F, will be automatically reset and the EMI bit will be cleared to disable other interrupts.

The purpose of the Time Base Interrupts is to provide an interrupt signal at fixed time periods. Their clock source, f_{PSC}, originates from the internal clock source f_{SYS}, $f_{SYS}/4$ or f_{SUB} and then passes through a divider, the division ratio of which is selected by programming the appropriate bits in the TB0C or TB1C register to obtain longer interrupt periods whose value ranges. The clock source that generates f_{PSC}, which in turn controls the Time Base interrupt period, is selected using the CLKSEL[1:0] bits in the PSCR register.



Time Base Interrupts

• PSCR Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	CLKSEL1	CLKSEL0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **CLKSEL1~CLKSEL0**: Prescaler clock source selection
00: f_{SYS}
01: $f_{SYS}/4$
1x: f_{SUB}

• TB0C Register

Bit	7	6	5	4	3	2	1	0
Name	TB0ON	—	—	—	—	TB02	TB01	TB00
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TB0ON**: Time Base 0 control
0: Disable
1: Enable

Bit 6~4 Unimplemented, read as "0"

Bit 2~0 **TB02~TB00**: Time Base 0 time-out period selection
000: $2^4/f_{PSC}$
001: $2^5/f_{PSC}$
010: $2^6/f_{PSC}$
011: $2^7/f_{PSC}$
100: $2^8/f_{PSC}$
101: $2^9/f_{PSC}$
110: $2^{10}/f_{PSC}$
111: $2^{11}/f_{PSC}$

• **TB1C Register**

Bit	7	6	5	4	3	2	1	0
Name	TB1ON	—	—	—	—	TB12	TB11	TB10
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TB1ON**: Time Base 1 control
0: Disable
1: Enable

Bit 6~4 Unimplemented, read as "0"

Bit 2~0 **TB12~TB10**: Time Base 1 time-out period selection
000: $2^8/f_{PSC}$
001: $2^9/f_{PSC}$
010: $2^{10}/f_{PSC}$
011: $2^{11}/f_{PSC}$
100: $2^{12}/f_{PSC}$
101: $2^{13}/f_{PSC}$
110: $2^{14}/f_{PSC}$
111: $2^{15}/f_{PSC}$

I²C Interrupt

An I²C interrupt request will take place when the I²C Interrupt request flag, IICF, is set, which occurs when a byte of data has been received or transmitted by the I²C interface, or an I²C slave address match occurs, or an I²C bus time-out occurs. To allow the program to branch to its interrupt vector address, the global interrupt enable bit, EMI, and the I²C Interrupt enable bit, IICE, must first be set. When the interrupt is enabled, the stack is not full and any of the above described situations occurs, a subroutine call to the I²C Interrupt vector, will take place. When the interrupt is serviced, the I²C Interrupt flag, IICF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

A/D Converter Interrupt

The A/D Converter Interrupt is controlled by the termination of an A/D conversion process. An A/D Converter Interrupt request will take place when the A/D Converter Interrupt request flag, ADF, is set, which occurs when the A/D conversion process finishes. To allow the program to branch to its interrupt vector address, the global interrupt enable bit, EMI, and A/D Interrupt enable bit, ADE, must first be set. When the interrupt is enabled, the stack is not full and the A/D conversion process has ended, a subroutine call to the A/D Converter Interrupt vector will take place. When the interrupt is serviced, the A/D Converter Interrupt flag, ADF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

LVD Interrupt

An LVD Interrupt request will take place when the LVD Interrupt request flag, LVF, is set, which occurs when the Low Voltage Detector function detects a preset low power supply voltage. To allow the program to branch to its interrupt vector address, the global interrupt enable bit, EMI, and the Low Voltage Interrupt enable bit, LVE, must first be set. When the interrupt is enabled, the stack is not full and a preset low voltage condition occurs, a subroutine call to the LVD Interrupt vector will take place. When the Low Voltage Interrupt is serviced, the LVD Interrupt flag, LVF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

EEPROM Interrupt

An EEPROM Interrupt request will take place when the EEPROM Interrupt request flag, DEF, is set, which occurs when an EEPROM Write cycle ends. To allow the program to branch to its interrupt vector address, the global interrupt enable bit, EMI, and the EEPROM Interrupt enable bit, DEE, must first be set. When the interrupt is enabled, the stack is not full and an EEPROM Write cycle ends, a subroutine call to the EEPROM Interrupt vector will take place. When the EEPROM Interrupt is serviced, the EEPROM Interrupt flag, DEF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

Interrupt Wake-up Function

Each of the interrupt functions has the capability of waking up the microcontroller when in the SLEEP or IDLE Mode. A wake-up is generated when an interrupt request flag changes from low to high and is independent of whether the interrupt is enabled or not. Therefore, even though this device is in the SLEEP or IDLE Mode and its system oscillator stopped, situations such as external edge transitions on the external interrupt pin or a low power supply voltage may cause their respective interrupt flag to be set high and consequently generate an interrupt. Care must therefore be taken if spurious wake-up situations are to be avoided. If an interrupt wake-up function is to be disabled then the corresponding interrupt request flag should be set high before the device enters the SLEEP or IDLE Mode. The interrupt enable bits have no effect on the interrupt wake-up function.

Programming Considerations

By disabling the relevant interrupt enable bits, a requested interrupt can be prevented from being serviced, however, once an interrupt request flag is set, it will remain in this condition in the interrupt register until the corresponding interrupt is serviced or until the request flag is cleared by the application program.

Where a certain interrupt is contained within a Multi-function interrupt, then when the interrupt service routine is executed, as only the Multi-function interrupt request flags, MFnF, will be automatically cleared, the individual request flag for the function needs to be cleared by the application program.

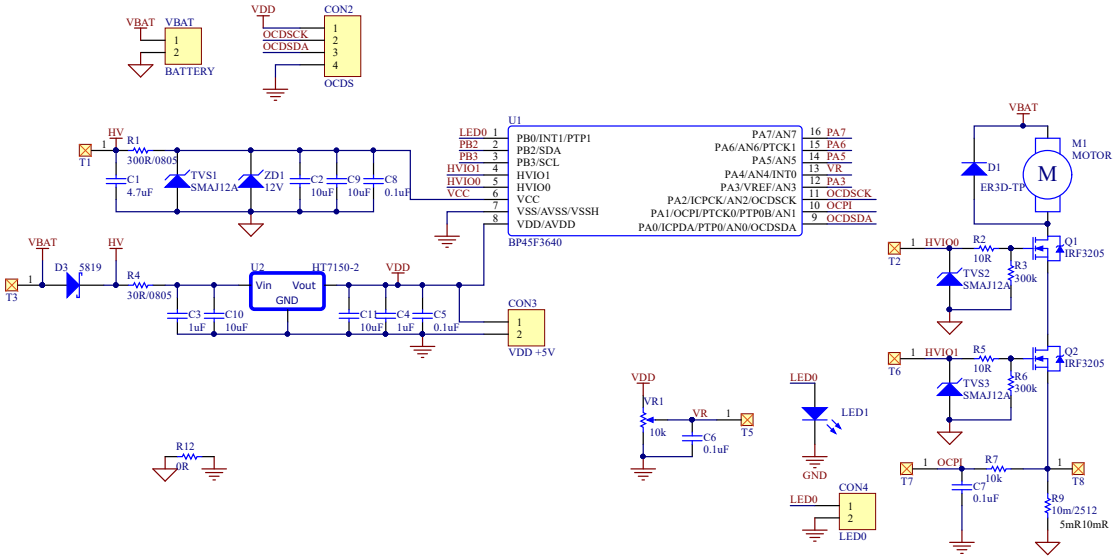
It is recommended that programs do not use the “CALL” instruction within the interrupt service subroutine. Interrupts often occur in an unpredictable manner or need to be serviced immediately. If only one stack is left and the interrupt is not well controlled, the original control sequence will be damaged once a CALL subroutine is executed in the interrupt subroutine.

Every interrupt has the capability of waking up the microcontroller when it is in the SLEEP or IDLE Mode, the wake-up being generated when the interrupt request flag changes from low to high. If it is required to prevent a certain interrupt from waking up the microcontroller then its respective request flag should be first set high before enter SLEEP or IDLE Mode.

As only the Program Counter is pushed onto the stack, then when the interrupt is serviced, if the contents of the accumulator, status register or other registers are altered by the interrupt service program, their contents should be saved to the memory at the beginning of the interrupt service routine.

To return from an interrupt subroutine, either a RET or RETI instruction may be executed. The RETI instruction in addition to executing a return to the main program also automatically sets the EMI bit high to allow further interrupts. The RET instruction however only executes a return to the main program leaving the EMI bit in its present zero state and therefore disabling the execution of further interrupts.

Application Circuits



Instruction Set

Introduction

Central to the successful operation of any microcontroller is its instruction set, which is a set of program instruction codes that directs the microcontroller to perform certain operations. In the case of Holtek microcontroller, a comprehensive and flexible set of over 60 instructions is provided to enable programmers to implement their application with the minimum of programming overheads.

For easier understanding of the various instruction codes, they have been subdivided into several functional groupings.

Instruction Timing

Most instructions are implemented within one instruction cycle. The exceptions to this are branch, call, or table read instructions where two instruction cycles are required. One instruction cycle is equal to 4 system clock cycles, therefore in the case of an 8MHz system oscillator, most instructions would be implemented within 0.5μs and branch or call instructions would be implemented within 1μs. Although instructions which require one more cycle to implement are generally limited to the JMP, CALL, RET, RETI and table read instructions, it is important to realize that any other instructions which involve manipulation of the Program Counter Low register or PCL will also take one more cycle to implement. As instructions which change the contents of the PCL will imply a direct jump to that new address, one more cycle will be required. Examples of such instructions would be “CLR PCL” or “MOV PCL, A”. For the case of skip instructions, it must be noted that if the result of the comparison involves a skip operation then this will also take one more cycle, if no skip is involved then only one cycle is required.

Moving and Transferring Data

The transfer of data within the microcontroller program is one of the most frequently used operations. Making use of several kinds of MOV instructions, data can be transferred from registers to the Accumulator and vice-versa as well as being able to move specific immediate data directly into the Accumulator. One of the most important data transfer applications is to receive data from the input ports and transfer data to the output ports.

Arithmetic Operations

The ability to perform certain arithmetic operations and data manipulation is a necessary feature of most microcontroller applications. Within the Holtek microcontroller instruction set are a range of add and subtract instruction mnemonics to enable the necessary arithmetic to be carried out. Care must be taken to ensure correct handling of carry and borrow data when results exceed 255 for addition and less than 0 for subtraction. The increment and decrement instructions such as INC, INCA, DEC and DECA provide a simple means of increasing or decreasing by a value of one of the values in the destination specified.

Logical and Rotate Operation

The standard logical operations such as AND, OR, XOR and CPL all have their own instruction within the Holtek microcontroller instruction set. As with the case of most instructions involving data manipulation, data must pass through the Accumulator which may involve additional programming steps. In all logical data operations, the zero flag may be set if the result of the operation is zero. Another form of logical data manipulation comes from the rotate instructions such as RR, RL, RRC and RLC which provide a simple means of rotating one bit right or left. Different rotate instructions exist depending on program requirements. Rotate instructions are useful for serial port programming applications where data can be rotated from an internal register into the Carry bit from where it can be examined and the necessary serial bit set high or low. Another application which rotate data operations are used is to implement multiplication and division calculations.

Branches and Control Transfer

Program branching takes the form of either jumps to specified locations using the JMP instruction or to a subroutine using the CALL instruction. They differ in the sense that in the case of a subroutine call, the program must return to the instruction immediately when the subroutine has been carried out. This is done by placing a return instruction "RET" in the subroutine which will cause the program to jump back to the address right after the CALL instruction. In the case of a JMP instruction, the program simply jumps to the desired location. There is no requirement to jump back to the original jumping off point as in the case of the CALL instruction. One special and extremely useful set of branch instructions are the conditional branches. Here a decision is first made regarding the condition of a certain data memory or individual bits. Depending upon the conditions, the program will continue with the next instruction or skip over it and jump to the following instruction. These instructions are the key to decision making and branching within the program perhaps determined by the condition of certain input switches or by the condition of internal data bits.

Bit Operations

The ability to provide single bit operations on Data Memory is an extremely flexible feature of all Holtek microcontrollers. This feature is especially useful for output port bit programming where individual bits or port pins can be directly set high or low using either the "SET [m].i" or "CLR [m].i" instructions respectively. The feature removes the need for programmers to first read the 8-bit output port, manipulate the input data to ensure that other bits are not changed and then output the port with the correct new data. This read-modify-write process is taken care of automatically when these bit operation instructions are used.

Table Read Operations

Data storage is normally implemented by using registers. However, when working with large amounts of fixed data, the volume involved often makes it inconvenient to store the fixed data in the Data Memory. To overcome this problem, Holtek microcontrollers allow an area of Program Memory to be setup as a table where data can be directly stored. A set of easy to use instructions provides the means by which this fixed data can be referenced and retrieved from the Program Memory.

Other Operations

In addition to the above functional instructions, a range of other instructions also exist such as the "HALT" instruction for Power-down operations and instructions to control the operation of the Watchdog Timer for reliable program operations under extreme electric or electromagnetic environments. For their relevant operations, refer to the functional related sections.

Instruction Set Summary

The instructions related to the data memory access in the following table can be used when the desired data memory is located in Data Memory sector 0.

Table Conventions

x: Bits immediate data
m: Data Memory address
A: Accumulator
i: 0~7 number of bits
addr: Program memory address

Mnemonic	Description	Cycles	Flag Affected
Arithmetic			
ADD A,[m]	Add Data Memory to ACC	1	Z, C, AC, OV, SC
ADDM A,[m]	Add ACC to Data Memory	1Note	Z, C, AC, OV, SC
ADD A,x	Add immediate data to ACC	1	Z, C, AC, OV, SC
ADC A,[m]	Add Data Memory to ACC with Carry	1	Z, C, AC, OV, SC
ADCM A,[m]	Add ACC to Data memory with Carry	1Note	Z, C, AC, OV, SC
SUB A,x	Subtract immediate data from the ACC	1	Z, C, AC, OV, SC, CZ
SUB A,[m]	Subtract Data Memory from ACC	1	Z, C, AC, OV, SC, CZ
SUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	1Note	Z, C, AC, OV, SC, CZ
SBC A,x	Subtract immediate data from ACC with Carry	1	Z, C, AC, OV, SC, CZ
SBC A,[m]	Subtract Data Memory from ACC with Carry	1	Z, C, AC, OV, SC, CZ
SBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	1Note	Z, C, AC, OV, SC, CZ
DAA [m]	Decimal adjust ACC for Addition with result in Data Memory	1Note	C
Logic Operation			
AND A,[m]	Logical AND Data Memory to ACC	1	Z
OR A,[m]	Logical OR Data Memory to ACC	1	Z
XOR A,[m]	Logical XOR Data Memory to ACC	1	Z
ANDM A,[m]	Logical AND ACC to Data Memory	1Note	Z
ORM A,[m]	Logical OR ACC to Data Memory	1Note	Z
XORM A,[m]	Logical XOR ACC to Data Memory	1Note	Z
AND A,x	Logical AND immediate Data to ACC	1	Z
OR A,x	Logical OR immediate Data to ACC	1	Z
XOR A,x	Logical XOR immediate Data to ACC	1	Z
CPL [m]	Complement Data Memory	1Note	Z
CPLA [m]	Complement Data Memory with result in ACC	1	Z
Increment & Decrement			
INCA [m]	Increment Data Memory with result in ACC	1	Z
INC [m]	Increment Data Memory	1Note	Z
DECA [m]	Decrement Data Memory with result in ACC	1	Z
DEC [m]	Decrement Data Memory	1Note	Z
Rotate			
RRA [m]	Rotate Data Memory right with result in ACC	1	None
RR [m]	Rotate Data Memory right	1Note	None
RRCA [m]	Rotate Data Memory right through Carry with result in ACC	1	C
RRC [m]	Rotate Data Memory right through Carry	1Note	C
RLA [m]	Rotate Data Memory left with result in ACC	1	None
RL [m]	Rotate Data Memory left	1Note	None
RLCA [m]	Rotate Data Memory left through Carry with result in ACC	1	C
RLC [m]	Rotate Data Memory left through Carry	1Note	C

Mnemonic	Description	Cycles	Flag Affected
Data Move			
MOV A,[m]	Move Data Memory to ACC	1	None
MOV [m],A	Move ACC to Data Memory	1Note	None
MOV A,x	Move immediate data to ACC	1	None
Bit Operation			
CLR [m].i	Clear bit of Data Memory	1Note	None
SET [m].i	Set bit of Data Memory	1Note	None
Branch Operation			
JMP addr	Jump unconditionally	2	None
SZ [m]	Skip if Data Memory is zero	1Note	None
SZA [m]	Skip if Data Memory is zero with data movement to ACC	1Note	None
SZ [m].i	Skip if bit i of Data Memory is zero	1Note	None
SNZ [m]	Skip if Data Memory is not zero	1Note	None
SNZ [m].i	Skip if bit i of Data Memory is not zero	1Note	None
SIZ [m]	Skip if increment Data Memory is zero	1Note	None
SDZ [m]	Skip if decrement Data Memory is zero	1Note	None
SIZA [m]	Skip if increment Data Memory is zero with result in ACC	1Note	None
SDZA [m]	Skip if decrement Data Memory is zero with result in ACC	1Note	None
CALL addr	Subroutine call	2	None
RET	Return from subroutine	2	None
RET A,x	Return from subroutine and load immediate data to ACC	2	None
RETI	Return from interrupt	2	None
Table Read Operation			
TABRD [m]	Read table (specific page) to TBLH and Data Memory	2Note	None
TABRDL [m]	Read table (last page) to TBLH and Data Memory	2Note	None
ITABRD [m]	Increment table pointer TBLP first and Read table (specific page) to TBLH and Data Memory	2Note	None
ITABRDL [m]	Increment table pointer TBLP first and Read table (last page) to TBLH and Data Memory	2Note	None
Miscellaneous			
NOP	No operation	1	None
CLR [m]	Clear Data Memory	1Note	None
SET [m]	Set Data Memory	1Note	None
CLR WDT	Clear Watchdog Timer	1	TO, PDF
SWAP [m]	Swap nibbles of Data Memory	1Note	None
SWAPA [m]	Swap nibbles of Data Memory with result in ACC	1	None
HALT	Enter power down mode	1	TO, PDF

Note: 1. For skip instructions, if the result of the comparison involves a skip then two cycles are required, if no skip takes place only one cycle is required.

2. Any instruction which changes the contents of the PCL will also require 2 cycles for execution.

Extended Instruction Set

The extended instructions are used to support the full range address access for the data memory. When the accessed data memory is located in any data memory sector except sector 0, the extended instruction can be used to directly access the data memory instead of using the indirect addressing access. This can not only reduce the use of Flash memory space but also improve the CPU execution efficiency.

Mnemonic	Description	Cycles	Flag Affected
Arithmetic			
LADD A,[m]	Add Data Memory to ACC	2	Z, C, AC, OV, SC
LADDM A,[m]	Add ACC to Data Memory	2Note	Z, C, AC, OV, SC
LADC A,[m]	Add Data Memory to ACC with Carry	2	Z, C, AC, OV, SC
LADCM A,[m]	Add ACC to Data memory with Carry	2Note	Z, C, AC, OV, SC
LSUB A,[m]	Subtract Data Memory from ACC	2	Z, C, AC, OV, SC, CZ
LSUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	2Note	Z, C, AC, OV, SC, CZ
LSBC A,[m]	Subtract Data Memory from ACC with Carry	2	Z, C, AC, OV, SC, CZ
LSBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	2Note	Z, C, AC, OV, SC, CZ
LDAA [m]	Decimal adjust ACC for Addition with result in Data Memory	2Note	C
Logic Operation			
LAND A,[m]	Logical AND Data Memory to ACC	2	Z
LOR A,[m]	Logical OR Data Memory to ACC	2	Z
LXOR A,[m]	Logical XOR Data Memory to ACC	2	Z
LANDM A,[m]	Logical AND ACC to Data Memory	2Note	Z
LORM A,[m]	Logical OR ACC to Data Memory	2Note	Z
LXORM A,[m]	Logical XOR ACC to Data Memory	2Note	Z
LCPL [m]	Complement Data Memory	2Note	Z
LCPLA [m]	Complement Data Memory with result in ACC	2	Z
Increment & Decrement			
LINCA [m]	Increment Data Memory with result in ACC	2	Z
LINC [m]	Increment Data Memory	2Note	Z
LDECA [m]	Decrement Data Memory with result in ACC	2	Z
LDEC [m]	Decrement Data Memory	2Note	Z
Rotate			
LRRA [m]	Rotate Data Memory right with result in ACC	2	None
LRR [m]	Rotate Data Memory right	2Note	None
LRRCA [m]	Rotate Data Memory right through Carry with result in ACC	2	C
LRRC [m]	Rotate Data Memory right through Carry	2Note	C
LRLA [m]	Rotate Data Memory left with result in ACC	2	None
LRL [m]	Rotate Data Memory left	2Note	None
LRLCA [m]	Rotate Data Memory left through Carry with result in ACC	2	C
LRLC [m]	Rotate Data Memory left through Carry	2Note	C
Data Move			
LMOV A,[m]	Move Data Memory to ACC	2	None
LMOV [m],A	Move ACC to Data Memory	2Note	None
Bit Operation			
LCLR [m].i	Clear bit of Data Memory	2Note	None
LSET [m].i	Set bit of Data Memory	2Note	None

Mnemonic	Description	Cycles	Flag Affected
Branch			
LSZ [m]	Skip if Data Memory is zero	2Note	None
LSZA [m]	Skip if Data Memory is zero with data movement to ACC	2Note	None
LSNZ [m]	Skip if Data Memory is not zero	2Note	None
LSZ [m].i	Skip if bit i of Data Memory is zero	2Note	None
LSNZ [m].i	Skip if bit i of Data Memory is not zero	2Note	None
LSIZ [m]	Skip if increment Data Memory is zero	2Note	None
LSDZ [m]	Skip if decrement Data Memory is zero	2Note	None
LSIZA [m]	Skip if increment Data Memory is zero with result in ACC	2Note	None
LSDZA [m]	Skip if decrement Data Memory is zero with result in ACC	2Note	None
Table Read			
LTABRD [m]	Read table (specific page) to TBLH and Data Memory	3Note	None
LTABRDL [m]	Read table (last page) to TBLH and Data Memory	3Note	None
LITABRD [m]	Increment table pointer TBLP first and Read table (specific page) to TBLH and Data Memory	3Note	None
LITABRDL [m]	Increment table pointer TBLP first and Read table (last page) to TBLH and Data Memory	3Note	None
Miscellaneous			
LCLR [m]	Clear Data Memory	2Note	None
LSET [m]	Set Data Memory	2Note	None
LSWAP [m]	Swap nibbles of Data Memory	2Note	None
LSWAPA [m]	Swap nibbles of Data Memory with result in ACC	2	None

Note: 1. For these extended skip instructions, if the result of the comparison involves a skip then three cycles are required, if no skip takes place two cycles is required.

2. Any extended instruction which changes the contents of the PCL register will also require three cycles for execution.

Instruction Definition

ADC A,[m] Add Data Memory to ACC with Carry

Description The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the Accumulator.

Operation ACC ← ACC + [m] + C

Affected flag(s) OV, Z, AC, C, SC

ADCM A,[m] Add ACC to Data Memory with Carry

Description The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the specified Data Memory.

Operation [m] ← ACC + [m] + C

Affected flag(s) OV, Z, AC, C, SC

ADD A,[m] Add Data Memory to ACC

Description The contents of the specified Data Memory and the Accumulator are added. The result is stored in the Accumulator.

Operation ACC ← ACC + [m]

Affected flag(s) OV, Z, AC, C, SC

ADD A,x Add immediate data to ACC

Description The contents of the Accumulator and the specified immediate data are added. The result is stored in the Accumulator.

Operation ACC ← ACC + x

Affected flag(s) OV, Z, AC, C, SC

ADDM A,[m] Add ACC to Data Memory

Description The contents of the specified Data Memory and the Accumulator are added. The result is stored in the specified Data Memory.

Operation [m] ← ACC + [m]

Affected flag(s) OV, Z, AC, C, SC

AND A,[m] Logical AND Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical AND operation. The result is stored in the Accumulator.

Operation ACC ← ACC "AND" [m]

Affected flag(s) Z

AND A,x Logical AND immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bit wise logical AND operation. The result is stored in the Accumulator.

Operation ACC ← ACC "AND" x

Affected flag(s) Z

ANDM A,[m] Logical AND ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical AND operation. The result is stored in the Data Memory.

Operation [m] ← ACC "AND" [m]

Affected flag(s) Z

CALL addr Subroutine call

Description Unconditionally calls a subroutine at the specified address. The Program Counter then increments by 1 to obtain the address of the next instruction which is then pushed onto the stack. The specified address is then loaded and the program continues execution from this new address. As this instruction requires an additional operation, it is a two cycle instruction.

Operation Stack ← Program Counter + 1
Program Counter ← addr

Affected flag(s) None

CLR [m] Clear Data Memory

Description Each bit of the specified Data Memory is cleared to 0.

Operation [m] ← 00H

Affected flag(s) None

CLR [m].i Clear bit of Data Memory

Description Bit i of the specified Data Memory is cleared to 0.

Operation [m].i ← 0

Affected flag(s) None

CLR WDT Clear Watchdog Timer

Description The TO, PDF flags and the WDT are all cleared.

Operation WDT cleared
TO ← 0
PDF ← 0

Affected flag(s) TO, PDF

CPL [m] Complement Data Memory

Description Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa.

Operation [m] ← $\overline{[m]}$

Affected flag(s) Z

CPLA [m] Complement Data Memory with result in ACC

Description Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC ← $\overline{[m]}$

Affected flag(s) Z

DAA [m] Decimal-Adjust ACC for addition with result in Data Memory

Description Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value resulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is greater than 100, it allows multiple precision decimal addition.

Operation [m] ← ACC + 00H or
[m] ← ACC + 06H or
[m] ← ACC + 60H or
[m] ← ACC + 66H

Affected flag(s) C

DEC [m] Decrement Data Memory

Description Data in the specified Data Memory is decremented by 1.

Operation [m] ← [m] − 1

Affected flag(s) Z

DECA [m] Decrement Data Memory with result in ACC

Description Data in the specified Data Memory is decremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC ← [m] − 1

Affected flag(s) Z

HALT Enter power down mode

Description This instruction stops the program execution and turns off the system clock. The contents of the Data Memory and registers are retained. The WDT and prescaler are cleared. The power down flag PDF is set and the WDT time-out flag TO is cleared.

Operation TO ← 0
PDF ← 1

Affected flag(s) TO, PDF

INC [m] Increment Data Memory

Description Data in the specified Data Memory is incremented by 1.

Operation [m] ← [m] + 1

Affected flag(s) Z

INCA [m] Increment Data Memory with result in ACC

Description Data in the specified Data Memory is incremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC ← [m] + 1

Affected flag(s) Z

JMP addr Jump unconditionally

Description The contents of the Program Counter are replaced with the specified address. Program execution then continues from this new address. As this requires the insertion of a dummy instruction while the new address is loaded, it is a two cycle instruction.

Operation Program Counter ← addr

Affected flag(s) None

MOV A,[m] Move Data Memory to ACC

Description The contents of the specified Data Memory are copied to the Accumulator.

Operation ACC ← [m]

Affected flag(s) None

MOV A,x Move immediate data to ACC

Description The immediate data specified is loaded into the Accumulator.

Operation ACC ← x

Affected flag(s) None

MOV [m],A Move ACC to Data Memory

Description The contents of the Accumulator are copied to the specified Data Memory.

Operation [m] ← ACC

Affected flag(s) None

NOP	No operation
Description	No operation is performed. Execution continues with the next instruction.
Operation	No operation
Affected flag(s)	None

OR A,[m]	Logical OR Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical OR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC ″OR″ [m]
Affected flag(s)	Z

OR A,x	Logical OR immediate data to ACC
Description	Data in the Accumulator and the specified immediate data perform a bitwise logical OR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC ″OR″ x
Affected flag(s)	Z

ORM A,[m]	Logical OR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical OR operation. The result is stored in the Data Memory.
Operation	[m] ← ACC ″OR″ [m]
Affected flag(s)	Z

RET	Return from subroutine
Description	The Program Counter is restored from the stack. Program execution continues at the restored address.
Operation	Program Counter ← Stack
Affected flag(s)	None

RET A,x	Return from subroutine and load immediate data to ACC
Description	The Program Counter is restored from the stack and the Accumulator loaded with the specified immediate data. Program execution continues at the restored address.
Operation	Program Counter ← Stack ACC ← x
Affected flag(s)	None

RETI	Return from interrupt
Description	The Program Counter is restored from the stack and the interrupts are re-enabled by setting the EMI bit. EMI is the master interrupt global enable bit. If an interrupt was pending when the RETI instruction is executed, the pending Interrupt routine will be processed before returning to the main program.
Operation	Program Counter ← Stack EMI ← 1
Affected flag(s)	None

RL [m]	Rotate Data Memory left
Description	The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0.
Operation	[m].(i+1) ← [m].i; (i=0~6) [m].0 ← [m].7
Affected flag(s)	None

RLA [m] Rotate Data Memory left with result in ACC

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← [m].7

Affected flag(s) None

RLC [m] Rotate Data Memory left through Carry

Description The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into bit 0.

Operation [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← C
C ← [m].7

Affected flag(s) C

RLCA [m] Rotate Data Memory left through Carry with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← C
C ← [m].7

Affected flag(s) C

RR [m] Rotate Data Memory right

Description The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into bit 7.

Operation [m].i ← [m].(i+1); (i=0~6)
[m].7 ← [m].0

Affected flag(s) None

RRA [m] Rotate Data Memory right with result in ACC

Description Data in the specified Data Memory is rotated right by 1 bit with bit 0
rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← [m].0

Affected flag(s) None

RRC [m] Rotate Data Memory right through Carry

Description The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7.

Operation [m].i ← [m].(i+1); (i=0~6)
[m].7 ← C
C ← [m].0

Affected flag(s) C

RRCA [m] Rotate Data Memory right through Carry with result in ACC

Description: Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation:
ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← C
C ← [m].0

Affected flag(s): C

SBC A,[m] Subtract Data Memory from ACC with Carry

Description: The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation: $ACC \leftarrow ACC - [m] - \overline{C}$

Affected flag(s): OV, Z, AC, C, SC, CZ

SBC A, x Subtract immediate data from ACC with Carry

Description: The immediate data and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation: $ACC \leftarrow ACC - [m] - \overline{C}$

Affected flag(s): OV, Z, AC, C, SC, CZ

SBCM A,[m] Subtract Data Memory from ACC with Carry and result in Data Memory

Description: The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation: $[m] \leftarrow ACC - [m] - \overline{C}$

Affected flag(s): OV, Z, AC, C, SC, CZ

SDZ [m] Skip if decrement Data Memory is 0

Description: The contents of the specified Data Memory are first decremented by 1. If the result is 0 the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation:
[m] ← [m] − 1
Skip if [m]=0

Affected flag(s): None

SDZA [m] Skip if decrement Data Memory is zero with result in ACC

Description: The contents of the specified Data Memory are first decremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation:
ACC ← [m] − 1
Skip if ACC=0

Affected flag(s): None

SET [m] Set Data Memory

Description Each bit of the specified Data Memory is set to 1.

Operation [m] ← FFH

Affected flag(s) None

SET [m].i Set bit of Data Memory

Description Bit i of the specified Data Memory is set to 1.

Operation [m].i ← 1

Affected flag(s) None

SIZ [m] Skip if increment Data Memory is 0

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation [m] ← [m] + 1
Skip if [m]=0

Affected flag(s) None

SIZA [m] Skip if increment Data Memory is zero with result in ACC

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation ACC ← [m] + 1
Skip if ACC=0

Affected flag(s) None

SNZ [m].i Skip if Data Memory is not 0

Description If the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.

Operation Skip if [m].i ≠ 0

Affected flag(s) None

SNZ [m] Skip if Data Memory is not 0

Description The contents of the specified Data Memory are read out and then written back to the specified Data Memory again. If the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.

Operation Skip if [m]≠ 0

Affected flag(s) None

SUB A,[m] Subtract Data Memory from ACC

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − [m]

Affected flag(s) OV, Z, AC, C, SC, CZ

SUBM A,[m] Subtract Data Memory from ACC with result in Data Memory

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation [m] ← ACC − [m]

Affected flag(s) OV, Z, AC, C, SC, CZ

SUB A,x Subtract immediate data from ACC

Description The immediate data specified by the code is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − x

Affected flag(s) OV, Z, AC, C, SC, CZ

SWAP [m] Swap nibbles of Data Memory

Description The low-order and high-order nibbles of the specified Data Memory are interchanged.

Operation [m].3~[m].0 ↔ [m].7~[m].4

Affected flag(s) None

SWAPA [m] Swap nibbles of Data Memory with result in ACC

Description The low-order and high-order nibbles of the specified Data Memory are interchanged. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC.3~ACC.0 ← [m].7~[m].4
ACC.7~ACC.4 ← [m].3~[m].0

Affected flag(s) None

SZ [m] Skip if Data Memory is 0

Description The contents of the specified Data Memory are read out and then written back to the specified Data Memory again. If the contents of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation Skip if [m]=0

Affected flag(s) None

SZA [m] Skip if Data Memory is 0 with data movement to ACC

Description The contents of the specified Data Memory are copied to the Accumulator. If the value is zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation ACC ← [m]
Skip if [m]=0

Affected flag(s) None

SZ [m].i Skip if bit i of Data Memory is 0

Description If bit i of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation Skip if [m].i=0

Affected flag(s) None

TABRD [m] Read table (specific page) to TBLH and Data Memory

Description The low byte of the program code (specific page) addressed by the table pointer (TBLP and TBHP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

TABRDL [m] Read table (last page) to TBLH and Data Memory

Description The low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

ITABRD [m] Increment table pointer low byte first and read table (specific page) to TBLH and Data Memory

Description Increment table pointer low byte, TBLP, first and then the program code (specific page) addressed by the table pointer (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

ITABRDL [m] Increment table pointer low byte first and read table (last page) to TBLH and Data Memory

Description Increment table pointer low byte, TBLP, first and then the low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

XOR A,[m] Logical XOR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″XOR″ [m]

Affected flag(s) Z

XORM A,[m] Logical XOR ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR operation. The result is stored in the Data Memory.

Operation [m] ← ACC ″XOR″ [m]

Affected flag(s) Z

XOR A,x Logical XOR immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bitwise logical XOR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″XOR″ x

Affected flag(s) Z

Extended Instruction Definition

The extended instructions are used to directly access the data stored in any data memory sections.

LADC A,[m] Add Data Memory to ACC with Carry

Description The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the Accumulator.

Operation ACC ← ACC + [m] + C

Affected flag(s) OV, Z, AC, C, SC

LADCM A,[m] Add ACC to Data Memory with Carry

Description The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the specified Data Memory.

Operation [m] ← ACC + [m] + C

Affected flag(s) OV, Z, AC, C, SC

LADD A,[m] Add Data Memory to ACC

Description The contents of the specified Data Memory and the Accumulator are added. The result is stored in the Accumulator.

Operation ACC ← ACC + [m]

Affected flag(s) OV, Z, AC, C, SC

LADDM A,[m] Add ACC to Data Memory

Description The contents of the specified Data Memory and the Accumulator are added. The result is stored in the specified Data Memory.

Operation [m] ← ACC + [m]

Affected flag(s) OV, Z, AC, C, SC

LAND A,[m] Logical AND Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical AND operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″AND″ [m]

Affected flag(s) Z

LANDM A,[m] Logical AND ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical AND operation. The result is stored in the Data Memory.

Operation [m] ← ACC ″AND″ [m]

Affected flag(s) Z

LCLR [m] Clear Data Memory

Description Each bit of the specified Data Memory is cleared to 0.

Operation [m] ← 00H

Affected flag(s) None

LCLR [m].i Clear bit of Data Memory

Description Bit i of the specified Data Memory is cleared to 0.

Operation [m].i ← 0

Affected flag(s) None

LCPL [m] Complement Data Memory

Description Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa.

Operation $[m] \leftarrow \overline{[m]}$

Affected flag(s) Z

LCPLA [m] Complement Data Memory with result in ACC

Description Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation $ACC \leftarrow \overline{[m]}$

Affected flag(s) Z

LDAA [m] Decimal-Adjust ACC for addition with result in Data Memory

Description Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value resulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is greater than 100, it allows multiple precision decimal addition.

Operation $[m] \leftarrow ACC + 00H$ or
$[m] \leftarrow ACC + 06H$ or
$[m] \leftarrow ACC + 60H$ or
$[m] \leftarrow ACC + 66H$

Affected flag(s) C

LDEC [m] Decrement Data Memory

Description Data in the specified Data Memory is decremented by 1.

Operation $[m] \leftarrow [m] - 1$

Affected flag(s) Z

LDECA [m] Decrement Data Memory with result in ACC

Description Data in the specified Data Memory is decremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation $ACC \leftarrow [m] - 1$

Affected flag(s) Z

LINC [m] Increment Data Memory

Description Data in the specified Data Memory is incremented by 1.

Operation $[m] \leftarrow [m] + 1$

Affected flag(s) Z

LINCA [m] Increment Data Memory with result in ACC

Description Data in the specified Data Memory is incremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation $ACC \leftarrow [m] + 1$

Affected flag(s) Z

LMOV A,[m] Move Data Memory to ACC

Description The contents of the specified Data Memory are copied to the Accumulator.

Operation ACC ← [m]

Affected flag(s) None

LMOV [m],A Move ACC to Data Memory

Description The contents of the Accumulator are copied to the specified Data Memory.

Operation [m] ← ACC

Affected flag(s) None

LOR A,[m] Logical OR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical OR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″OR″ [m]

Affected flag(s) Z

LORM A,[m] Logical OR ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical OR operation. The result is stored in the Data Memory.

Operation [m] ← ACC ″OR″ [m]

Affected flag(s) Z

LRL [m] Rotate Data Memory left

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0.

Operation [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← [m].7

Affected flag(s) None

LRLA [m] Rotate Data Memory left with result in ACC

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← [m].7

Affected flag(s) None

LRLC [m] Rotate Data Memory left through Carry

Description The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into bit 0.

Operation [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← C
C ← [m].7

Affected flag(s) C

LRLCA [m] Rotate Data Memory left through Carry with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← C
C ← [m].7

Affected flag(s) C

LRR [m] Rotate Data Memory right

Description The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into bit 7.

Operation [m].i ← [m].(i+1); (i=0~6)
[m].7 ← [m].0

Affected flag(s) None

LRRA [m] Rotate Data Memory right with result in ACC

Description Data in the specified Data Memory is rotated right by 1 bit with bit 0 rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← [m].0

Affected flag(s) None

LRRC [m] Rotate Data Memory right through Carry

Description The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7.

Operation [m].i ← [m].(i+1); (i=0~6)
[m].7 ← C
C ← [m].0

Affected flag(s) C

LRRCA [m] Rotate Data Memory right through Carry with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← C
C ← [m].0

Affected flag(s) C

LSBC A,[m] Subtract Data Memory from ACC with Carry

Description The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − [m] − $\overline{C}$

Affected flag(s) OV, Z, AC, C, SC, CZ

LSBCM A,[m] Subtract Data Memory from ACC with Carry and result in Data Memory

Description The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation [m] ← ACC − [m] − $\overline{C}$

Affected flag(s) OV, Z, AC, C, SC, CZ

LSDZ [m] Skip if decrement Data Memory is 0

Description The contents of the specified Data Memory are first decremented by 1. If the result is 0 the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation [m] ← [m] − 1
Skip if [m]=0

Affected flag(s) None

LSDZA [m] Skip if decrement Data Memory is zero with result in ACC

Description The contents of the specified Data Memory are first decremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation ACC ← [m] − 1
Skip if ACC=0

Affected flag(s) None

LSET [m] Set Data Memory

Description Each bit of the specified Data Memory is set to 1.

Operation [m] ← FFH

Affected flag(s) None

LSET [m].i Set bit of Data Memory

Description Bit i of the specified Data Memory is set to 1.

Operation [m].i ← 1

Affected flag(s) None

LSIZ [m] Skip if increment Data Memory is 0

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation [m] ← [m] + 1
Skip if [m]=0

Affected flag(s) None

LSIZA [m] Skip if increment Data Memory is zero with result in ACC

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation ACC ← [m] + 1
Skip if ACC=0

Affected flag(s) None

LSNZ [m].i Skip if Data Memory is not 0

Description If the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is 0 the program proceeds with the following instruction.

Operation Skip if [m].i ≠ 0

Affected flag(s) None

LSNZ [m] Skip if Data Memory is not 0

Description The contents of the specified Data Memory are read out and then written to the specified Data Memory again. If the content of the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is 0 the program proceeds with the following instruction.

Operation Skip if [m] ≠ 0

Affected flag(s) None

LSUB A,[m] Subtract Data Memory from ACC

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − [m]

Affected flag(s) OV, Z, AC, C, SC, CZ

LSUBM A,[m] Subtract Data Memory from ACC with result in Data Memory

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation [m] ← ACC − [m]

Affected flag(s) OV, Z, AC, C, SC, CZ

LSWAP [m] Swap nibbles of Data Memory

Description The low-order and high-order nibbles of the specified Data Memory are interchanged.

Operation [m].3~[m].0 ↔ [m].7~[m].4

Affected flag(s) None

LSWAPA [m] Swap nibbles of Data Memory with result in ACC

Description The low-order and high-order nibbles of the specified Data Memory are interchanged. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC.3~ACC.0 ← [m].7~[m].4
ACC.7~ACC.4 ← [m].3~[m].0

Affected flag(s) None

LSZ [m] Skip if Data Memory is 0

Description The contents of the specified Data Memory are read out and then written to the specified Data Memory again. If the contents of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation Skip if [m]=0

Affected flag(s) None

LSZA [m] Skip if Data Memory is 0 with data movement to ACC

Description The contents of the specified Data Memory are copied to the Accumulator. If the value is zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation ACC ← [m]
Skip if [m]=0

Affected flag(s) None

LSZ [m].i Skip if bit i of Data Memory is 0

Description If bit i of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation Skip if [m].i=0

Affected flag(s) None

LTABRD [m] Read table (specific page) to TBLH and Data Memory

Description The low byte of the program code (specific page) addressed by the table pointer (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

LTABRDL [m] Read table (last page) to TBLH and Data Memory

Description The low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

LITABRD [m] Increment table pointer low byte first and read table (specific page) to TBLH and Data Memory

Description Increment table pointer low byte, TBLP, first and then the program code (specific page) addressed by the table pointer (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

LITABRDL [m] Increment table pointer low byte first and read table (last page) to TBLH and Data Memory

Description Increment table pointer low byte, TBLP, first and then the low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

LXOR A,[m] Logical XOR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″XOR″ [m]

Affected flag(s) Z

LXORM A,[m] Logical XOR ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR operation. The result is stored in the Data Memory.

Operation [m] ← ACC ″XOR″ [m]

Affected flag(s) Z

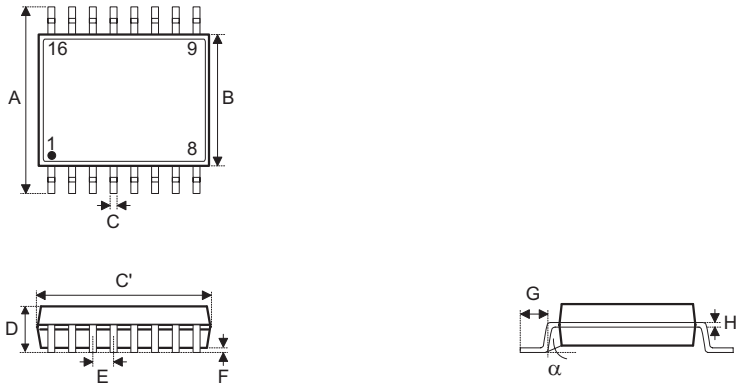
Package Information

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the Holtek website for the latest version of the Package/Carton Information.

Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- The Operation Instruction of Packing Materials
- Carton information

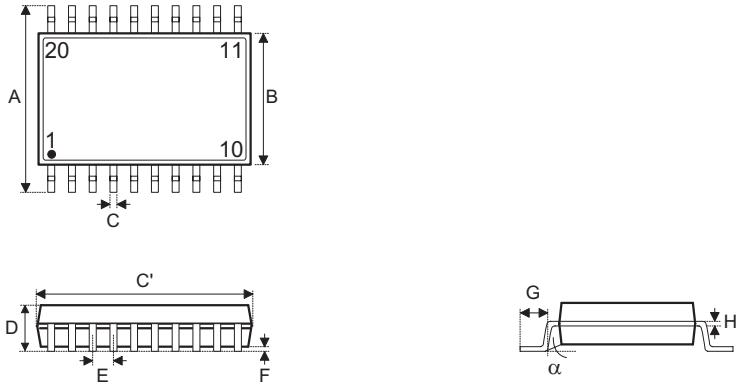
16-pin SSOP (150mil) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.236 BSC	—
B	—	0.154 BSC	—
C	0.008	—	0.012
C’	—	0.193 BSC	—
D	—	—	0.069
E	—	0.025 BSC	—
F	0.004	—	0.010
G	0.016	—	0.050
H	0.004	—	0.010
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	6.000 BSC	—
B	—	3.900 BSC	—
C	0.20	—	0.30
C’	—	4.900 BSC	—
D	—	—	1.75
E	—	0.635 BSC	—
F	0.10	—	0.25
G	0.41	—	1.27
H	0.10	—	0.25
α	0°	—	8°

20-pin SSOP (209mil) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.291	0.307	0.323
B	0.197	0.209	0.220
C	0.009	—	0.015
C’	0.272	0.283	0.295
D	—	—	0.079
E	—	0.026 BSC	—
F	0.002	—	—
G	0.022	—	0.037
H	0.004	—	0.008
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	7.40	7.80	8.20
B	5.00	5.30	5.60
C	0.22	—	0.38
C’	6.90	7.20	7.50
D	—	—	2.00
E	—	0.65 BSC	—
F	0.05	—	—
G	0.55	0.75	0.95
H	0.09	—	0.21
α	0°	—	8°